

UNITED STATES SECURITIES AND EXCHANGE COMMISSION

Washington, D.C. 20549

FORM 6-K

REPORT OF FOREIGN PRIVATE ISSUER
PURSUANT TO RULE 13a-16 OR 15d-16 UNDER
THE SECURITIES EXCHANGE ACT OF 1934

Report on Form 6-K dated June 4, 2010

Commission File Number: 1-13546

STMicroelectronics N.V.
(Name of Registrant)

39, Chemin du Champ-des-Filles
1228 Plan-les-Ouates, Geneva, Switzerland

(Address of Principal Executive Offices)

Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.

Form 20-F Q

Form 40-F £

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(1):

Yes £

No Q

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(7):

Yes £

No Q

Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.

Yes £

No Q

If "Yes" is marked, indicate below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82- _____

Enclosure: A presentation prepared by STMicroelectronics with respect to its Field Day at its Field Day held in London, England on June 3, 2010.



Field Trip 2010

London, June 3

STMicroelectronics



Welcome & Introduction

Tait Sorensen

Director - Investor Relations

STMicroelectronics

Field Trip Agenda



Time	Presentation	Speaker
10:00 am	Welcome & Introduction	T. Sorensen
10:05	Company Strategy & Vision	C. Bozotti
10:25	ST Business & Operations	A. Dutheil
10:45	Financial Performance & Roadmap	C. Ferro
11:05	Sustainable Technology & Leadership	J-M. Chery
11:25	Q&A Panel	C. Bozotti/A. Dutheil/C. Ferro/J-M. Chery
11:50	BREAK	
12:00pm	Multimedia Convergence & ACCI Sector Overview	P. Lambinet
12:20	IMS Overview & Advanced Analog & Smart Power	C. Papa
12:40	ST-Ericsson: Towards Transformation	G. Delfassy
1:00	Q&A Panel	C. Bozotti/P. Lambinet/C. Papa /G. Delfassy
1:30	LUNCH	
2:30	Breakout Sessions	
5:00 - 6:30	Reception	

Field Trip Agenda – Breakout Sessions



	<u>Ballroom</u> Ground Floor	<u>Mirror Room</u> Ground Floor	<u>St. James</u> 6 th Floor	<u>Clarence</u> 6 th Floor	<u>Boardroom</u> 6 th Floor	<u>Kensington</u> 6 th Floor
2:30 – 3:00	ST-Ericsson	Home Entertainment		Automotive		MCUs
3:00 – 3:30	ST-Ericsson			Automotive	Americas	MEMS
3:30 – 4:00	ST-Ericsson	Home Entertainment	Computer & Networking			MCUs
4:00 – 4:30			Computer & Networking	Automotive	Americas	MEMS
4:30 – 5:00		Home Entertainment	Computer & Networking		Americas	Power & Smart Power
5:00	Reception – Ballroom Reception Area					

- Americas: The Land of Opportunity (R. Krysiak)
- Automotive (P. Grimme)
- Computer & Networking (GL Bertino)
- Home Entertainment (P. Lambinet)
- MCUs (C. Dardanne)
- MEMS & Adv. Analog (B. Vigna)
- Power & Smart Power (M. Lo Presti)
- ST-Ericsson (P. Langlois)

Forward Looking Statements



- Some of the statements contained in these presentations that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance or events to differ materially from those in such statements due to, among other factors:
 - Significant changes in demand in the key application markets and from key customers served by our products make it extremely difficult to accurately forecast and plan our future business activities. In particular, following a period of significant order cancellations, we recently experienced a strong surge in customer demand, which has led to capacity constraints in certain applications;
 - our ability to utilize and operate our manufacturing facilities at sufficient levels to cover fixed operating costs in periods of reduced customer demand, as well as our ability to ramp up production efficiently and rapidly to respond to increased customer demand, and the financial impact of obsolete or excess inventories if actual demand differs from our expectations;
 - our ability to successfully integrate the acquisitions we pursue, in particular the successful integration and operation of the ST-Ericsson joint venture;
 - ST-Ericsson is a new wireless joint venture, representing a significant investment and risk for our business. The joint venture is currently engaged in restructuring initiatives and further declines in the wireless market, as well as the inability of ST-Ericsson to complete its ongoing restructuring plans or to successfully compete, could result in additional significant impairment and restructuring charges;
 - we currently hold a significant financial investment in Micron Technology Inc ("Micron") as a result of the previously announced sale to Micron of our equity investment in Numonyx in an all-stock transaction. Our shares in Micron are subject to certain resale restrictions and, consequently, there is no guaranty as to when we will be able to sell them and at what price;
 - our ability to compete in our industry since a high percentage of our costs are fixed and are incurred in currencies other than U.S. dollars, especially in light of the volatility in the foreign exchange markets and, more particularly, in the U.S. dollar exchange rate as compared to the other major currencies we use for our operations;
 - the outcome of ongoing litigation as well as any new litigation to which we may become a defendant;
 - changes in our overall tax position as a result of changes in tax laws or the outcome of tax audits, and our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;
 - the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;
 - our ability to execute our restructuring initiatives in accordance with our plans if unforeseen events require adjustments or delays in implementation or require new plans;
 - our ability in an intensely competitive environment to secure customer acceptance and to achieve our pricing expectations for high-volume supplies of new products in whose development we have been, or are currently, investing;
 - changes in the political, social or economic environment, including as a result of military conflict, social unrest and/or terrorist activities, economic turmoil, as well as natural events such as severe weather, health risks, epidemics, earthquakes, volcano eruptions or other acts of nature in, or affecting, the countries in which we, our key customers or our suppliers, operate.
- Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward-looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions. Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2009, as filed with the SEC on March 10, 2010. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.



Company Strategy & Vision

Carlo Bozotti

President and Chief Executive Officer

STMicroelectronics



ST Business & Operations

Alain Dutheil
Chief Operating Officer

STMicroelectronics

A Year-Ago...The Global Recession



- Semiconductor bookings dropped rapidly in Q408; demand remained weak in first half of 2009
- Impact on industry's revenue evolution greater than initially expected
- Industry utilization rates reached unprecedented low levels; capacity cut to react to lack of demand
- Inventory levels were substantially reduced
- Economic impact varied by geography
 - China - started to recover
 - Europe, US and Japan – still difficult conditions
- Global market bottomed in mid-2009

Managed Well Through the Downturn...



- ST exited the recession a stronger and leaner company
 - Increased operating leverage
 - Completed ~\$750M of cost savings initiatives in 2009
 - Improved financial strength and stability
 - Over \$2.76B in gross cash and marketable securities exiting March 2010
 - Continued progress in advanced technology R&D partnerships
 - Reshaped manufacturing
- Committed to the ongoing integration of ST-Ericsson
- Performance of ST's global team
 - Reacted quickly to align manufacturing, costs and working capital to end markets
 - Stayed focused on customers

2009 Semiconductor Industry Revenue

TAM: -9%

SAM: -13%

ST (ex FMG): -10.8%

- Resuming progress towards long-term financial goals
 - Focused on reaching sustainable levels of sales and net income
 - Organic growth / new product innovation
 - Disciplined portfolio management
 - Leveraging global scale and scope
 - Commitment to shareholder value creation

- ST-Ericsson
 - Competitive cost structure / completion of announced restructuring programs
 - New portfolio
 - Preparing the company for future, profitable growth

Current Expectations
2010 Semiconductor Industry Revenue
SAM: approximately +20%



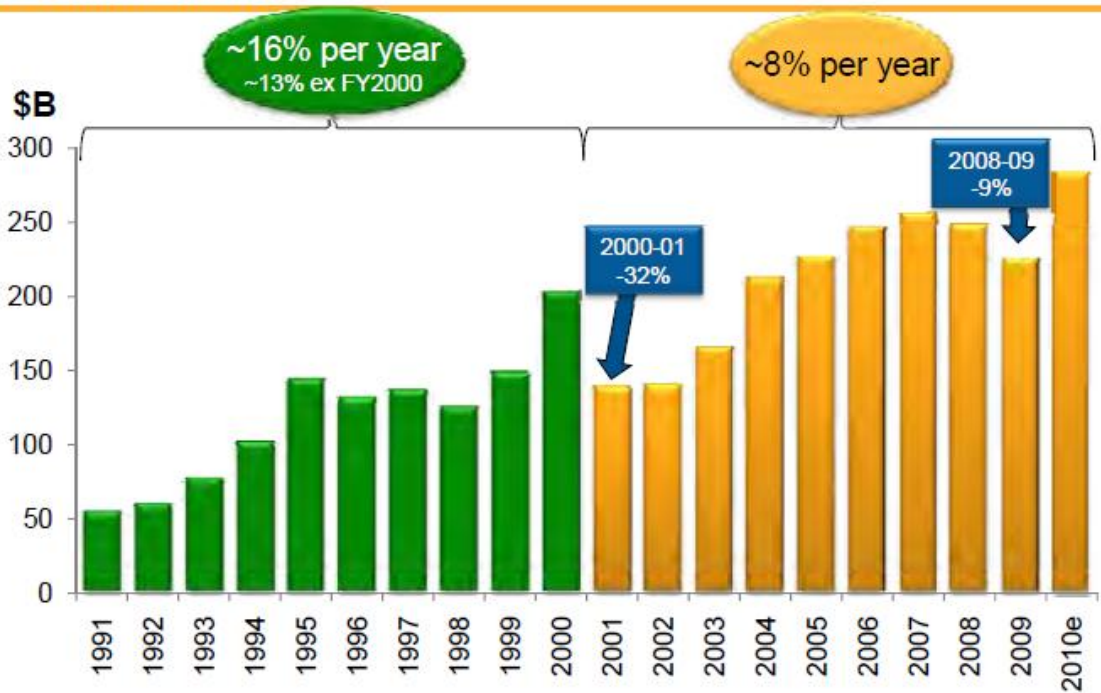
Semiconductor Industry

STMicroelectronics

Semiconductor Market Growth



Total Available Market



- Demand driven cycle less severe
- Recession led to 2 years of decline
- Semis well positioned to grow in future years

Source: WSTS

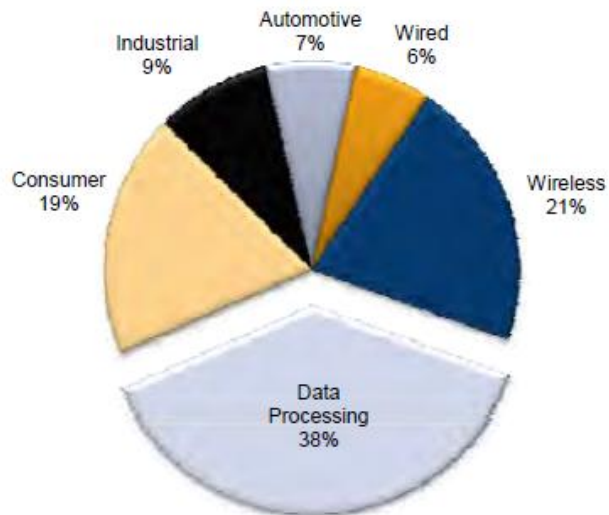
STMicroelectronics

Key Target Areas

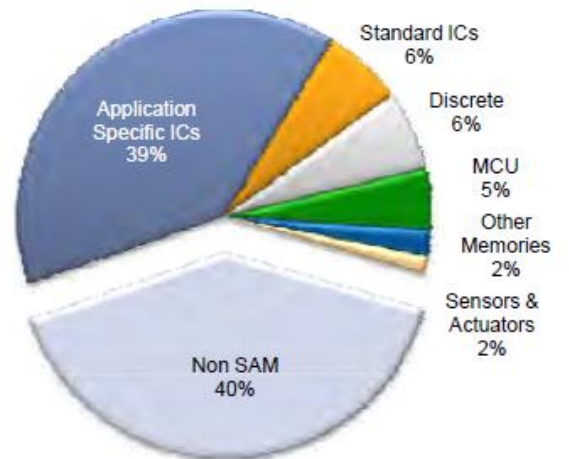
Total Available Market



Application



Product



ST: well positioned, diversified, many opportunities

Source: iSuppli (including memories), WSTS

STMicroelectronics

- Multimedia convergence is accelerating
- Re-rating of industry growth
- Semiconductor market is moving East
- Cost of fabs and process R&D are soaring
- Foundries are getting a significant share of semi business
- R&D is shifting across the value chain
- Industry is consolidating by application
- Pervasion into new high-growth industries



Company Overview

STMicroelectronics

STMicroelectronics

A Global Semiconductor Company



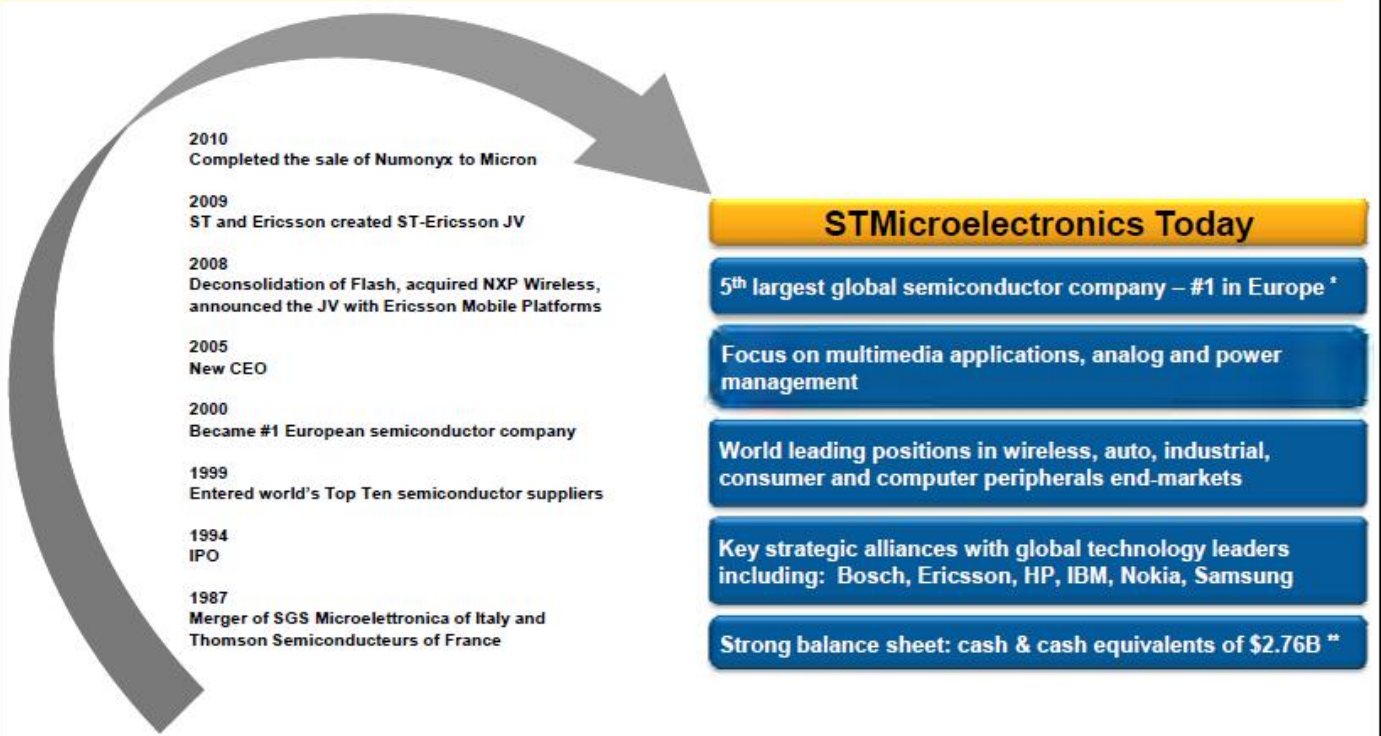
Q110 revenue: \$2,325M
By location of order shipment



- ❑ FY09 revenues of \$8.51B
- ❑ 15 main manufacturing sites
- ❑ Advanced R&D centers in 10 countries
- ❑ Over 51,000 employees, including ST-Ericsson
- ❑ Listed on NYSE Euronext (New York & Paris) and Milan stock exchanges

STMicroelectronics

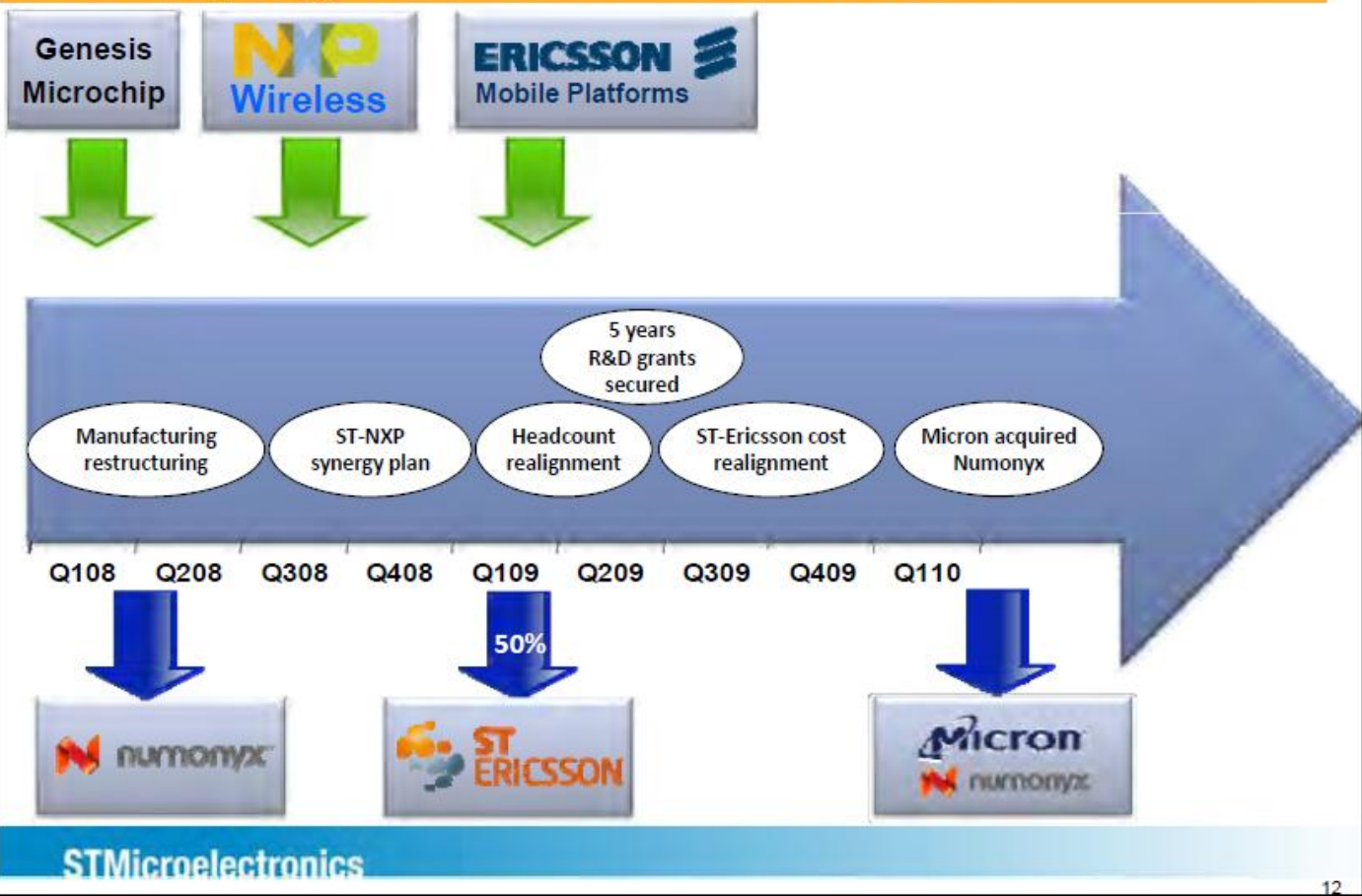
The Evolution of ST



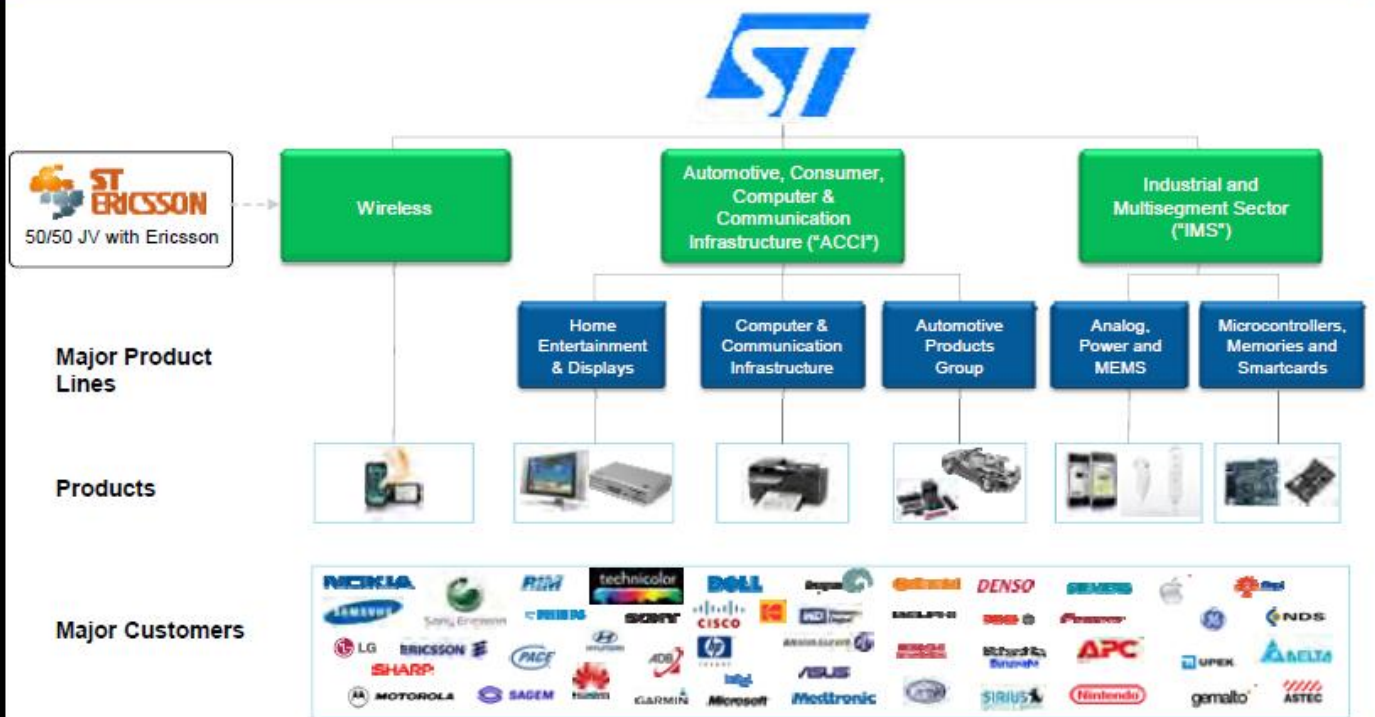
*Source: iSuppli, 2009

**As at March 27, 2010, including non-current marketable securities and cash restricted at JV.

Reshaping ST's Product Portfolio



Business Segment Overview



Diversified Customer Base

2009 Top 30 OEM and Top EMS Customers



Communications

- Huawei
- Nokia
- Research in Motion
- SonyEricsson
- Samsung

Consumer

- ADB
- Cisco/Scientific Atlanta
- Garmin
- LG Electronics
- Nintendo
- Pace
- Panasonic
- Philips
- Sagem
- Sharp
- Technicolor

Automotive

- Bosch
- Conti
- Delphi
- Denso
- Marelli

Computer

- Apple
- Dell
- Eastman Kodak
- HP
- Seagate
- Western Digital

Industrial

- Delta
- Gemalto
- Siemens

EMS

- Cal-Comp.
- Elcoteq
- Flextronics
- HonHai Foxconn
- Jabil
- Sanmina – SCI

Note: Alphabetically listed by main application sector

Top Players in 2009 by Application



Digital Consumer



Automotive



Industrial



Wireless Communications



Source: iSuppli, ST

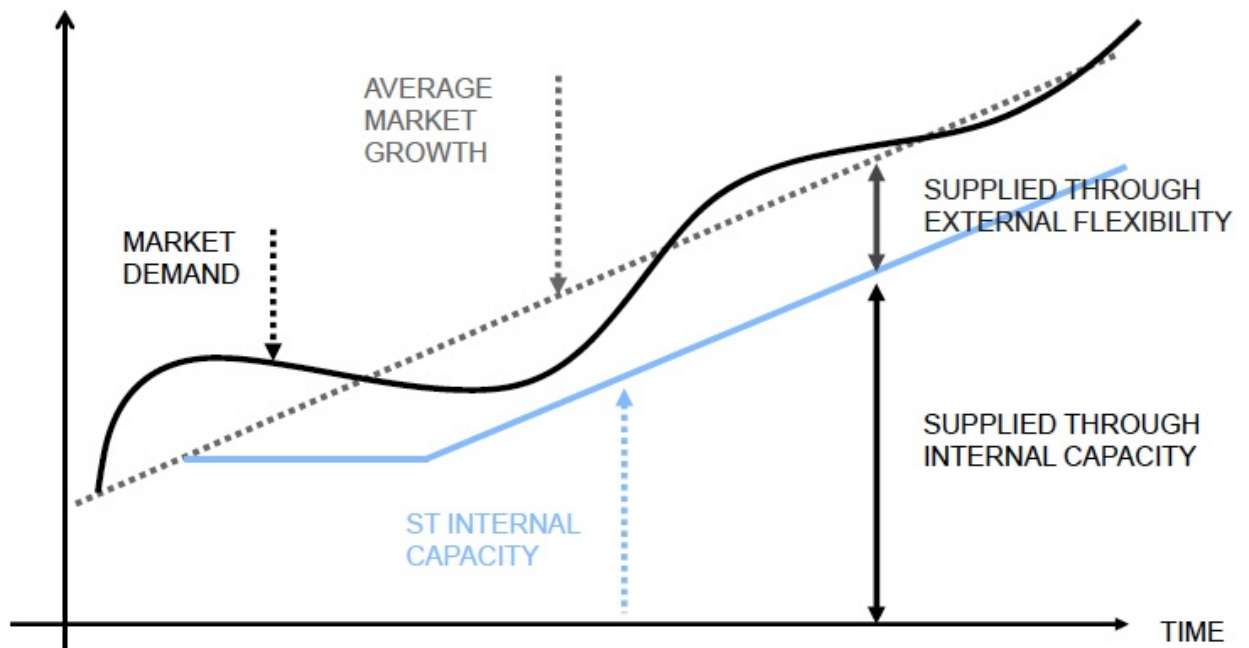


Manufacturing

Lighter Asset Model



Manufacturing Flexibility Through The Market Cycle



Target Model: 80% internal, 20% outsourced

ST Manufacturing Evolution



ST STRATEGY PATH:

IDM → Flexible IDM → Lighter Asset

NUMBER OF FRONT END FABs:

17 → 14 → 9 → 8

WAFER PROBING (EWS):

From Europe to a major WW center in Singapore

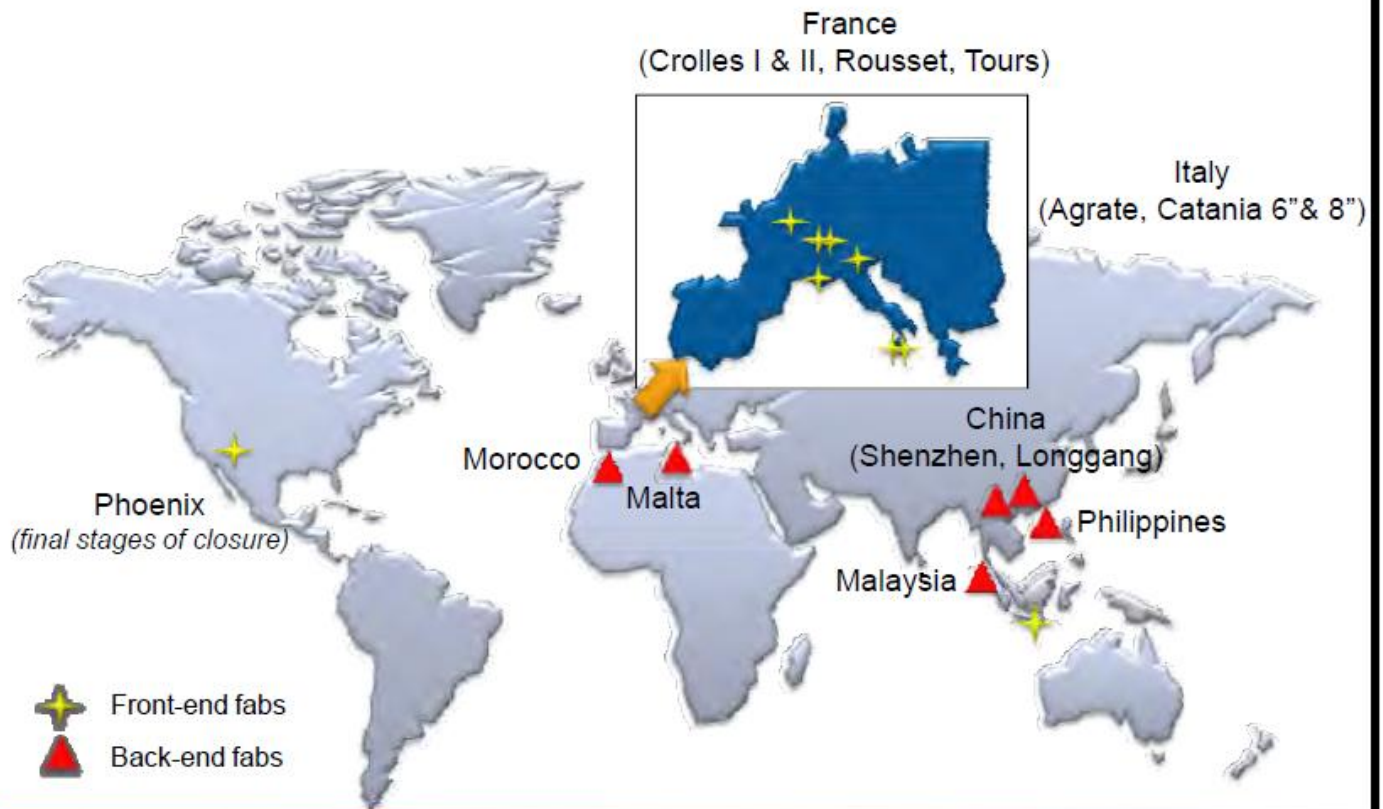
ASSEMBLY – NUMBER OF PLANTS:

In Mediterranean : 3 → 2
In Asia: 3 (1 China) → 4 (2 China) → Expand Asia

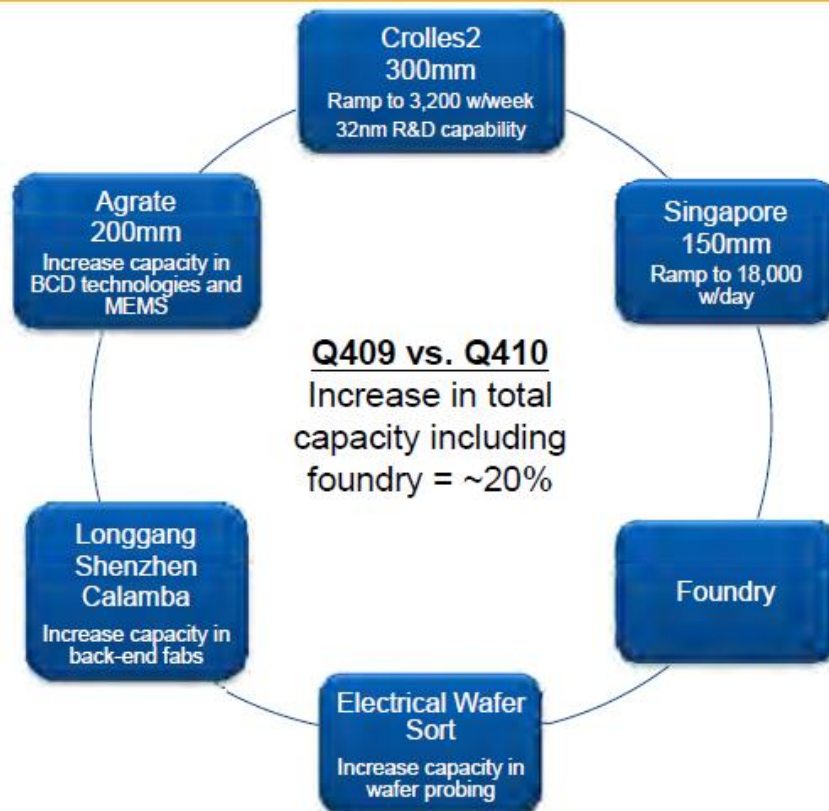
2005

end 2009

Manufacturing Locations



Key Initiatives to Increase Capacity - 2010





Conclusion

2010 Corporate Priorities



Gain market share



Cost reduction / capacity expansion



Maximize R&D innovation



Value from new products





Financial Performance & Roadmap

Carlo Ferro

Chief Financial Officer

STMicroelectronics

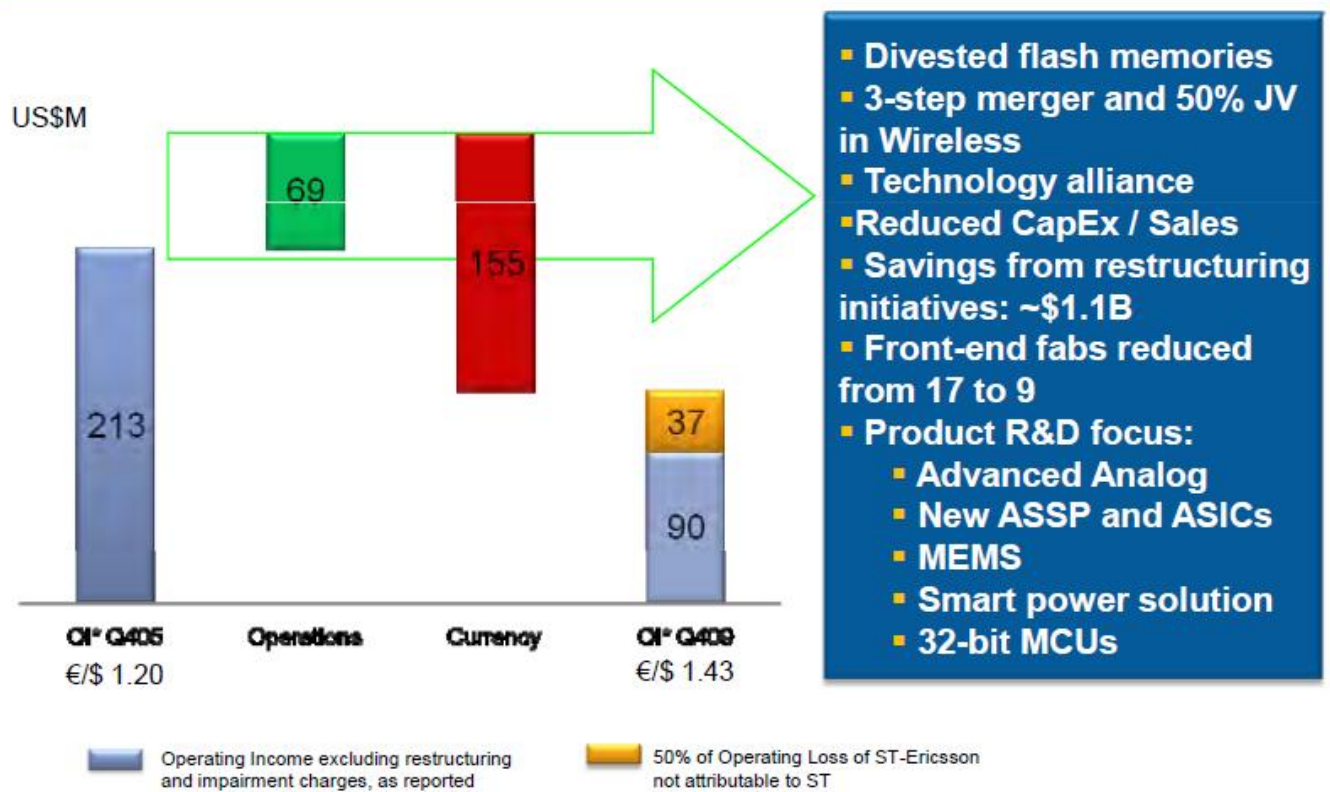
- **Our Financial Results**
- **Our Opportunities**
- **Our Target Financial Model**



Our Results

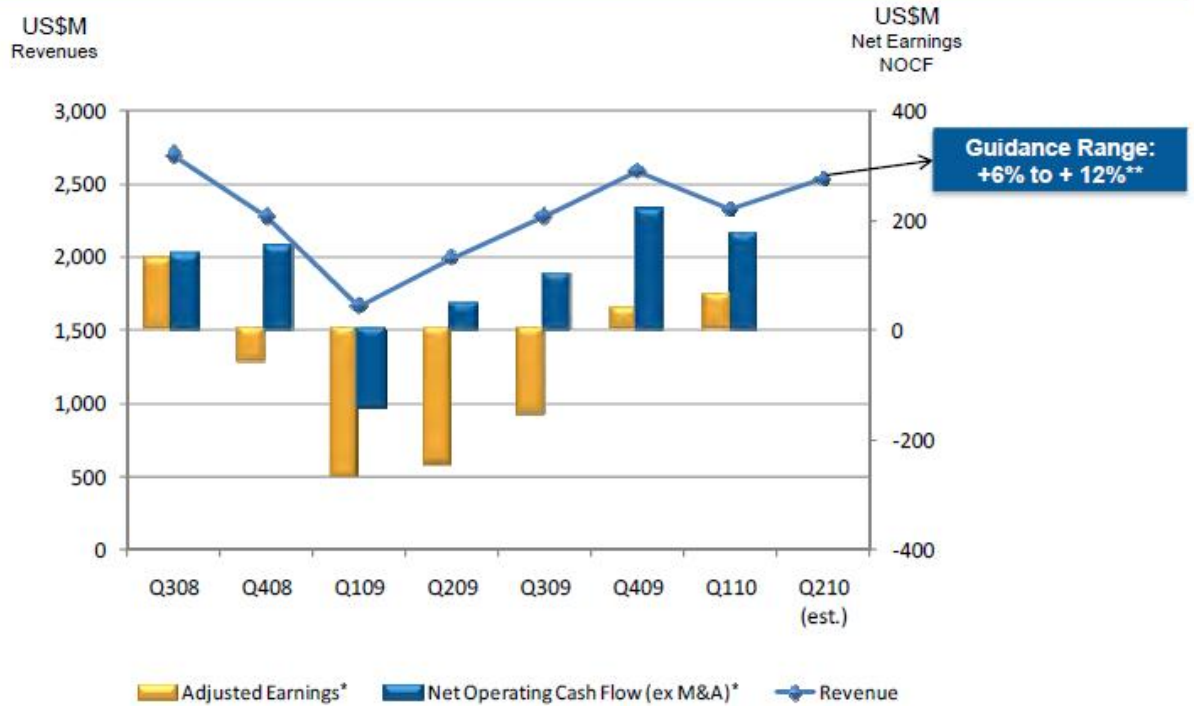
STMicroelectronics

4 Years of Progress Masked by Currency



- Divested flash memories
- 3-step merger and 50% JV in Wireless
- Technology alliance
- Reduced CapEx / Sales
- Savings from restructuring initiatives: ~\$1.1B
- Front-end fabs reduced from 17 to 9
- Product R&D focus:
 - Advanced Analog
 - New ASSP and ASICs
 - MEMS
 - Smart power solution
 - 32-bit MCUs

Recovered From the Recession in 2009



*Adjusted Earnings and NOCF (ex M&A) are non-GAAP measures that, the Company believes, provide useful information. See appendix for definition.
 **Q210 revenues guidance estimate: sequential growth of between 6% and 12%.

Our Results



<i>In US\$M, except EPS</i>	Q308	Q409	Q110		FY09	FY08
Net Revenues	2,696	2,583	2,325		8,510	9,842
Gross Margin	35.6%	37.0%	37.7%		30.9%	36.2%
Adjusted Operating Profit before Restructuring attributable to Parent⁽¹⁾	210	128	81		(499)	468
Adjusted Operating Margin⁽¹⁾	7.8%	5.7%	4.0%		-6.8%	4.8%
EPS Diluted	(0.32)	(0.08)	0.06		(1.29)	(0.88)
Adjusted EPS Diluted*	0.15	0.04	0.07		(0.72)	0.40
RONA attributable to Parent⁽¹⁾	10.5%	7.6%	5.1%		-28.3%	5.9%
Net Operating Cash Flow (before M&A)*	140	221	176		226	647
Effective Exchange Rate €/\$	1.54	1.43	1.39		1.37	1.49

*Some of the measures above are non-GAAP measures that, the Company believes, provide useful information. See appendix and below for definition and calculation methodology.

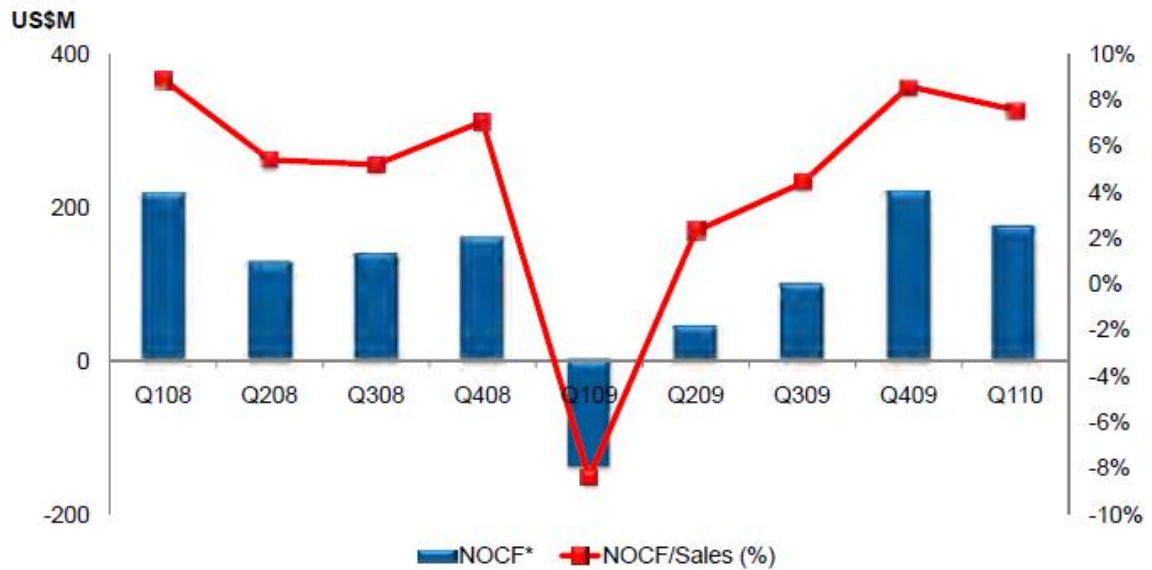
⁽¹⁾ Description of adjusted metrics attributable to parents:

- Adjusted Operating Profit attributable to parent = Reported Operating Profit/Loss before restructuring – ½ of ST-Ericsson JVS Operating Profit/Loss before restructuring
- Adjusted Operating Margin attributable to parent = Operating Profit attributable to parent / (Reported Revenues – ½ of ST-Ericsson JVS Revenues)
- RONA attributable to parent = Annualized Operating profit attributable to parent / (Reported Net Assets – ½ of ST-Ericsson JVS Net Assets)

Net Operating Cash Flow



Net Operating Cash Flow (ex M&A)*



*Net Operating Cash Flow (ex M&A) is a non-GAAP measure that, the Company believes, provides useful information. See appendix for definition.

Numonyx Deal*



Transaction

- Micron acquired Numonyx Holdings B.V. in consideration for 140M shares of Micron common stock, including assumed management's stock plan
- Deal closed on May 7, 2010

Consideration for ST

- In connection with the sale of its 48.6% stake in Numonyx, ST has received:
 - 66.88M shares of Micron common stock
 - They will be dealt as a financial investment
 - At May 6, 2010 Micron's share price of \$ 8.75, the value of the shares is \$585.2M
 - A substantial portion of such shares is hedged
 - In connection a payable of \$77.8M is due by ST to Francisco Partners
 - future full ownership of the Numonyx M6 facility in Catania, Italy,
 - ST has committed to contribute it to the new photovoltaic joint initiative owned 33% by ST; valued 60M €

Financial impact to ST

- **Total consideration, net of the payable, of \$580M**
- **Eliminated the risk of \$225M related to the ST's guarantee to a Numonyx loan, which has been repaid in full at closing**
- **Opportunity to accelerate the recovery of \$250M of restricted cash, due to the earlier redemption of the Hynix-Numonyx deposit**

- **\$800M to over \$1B improvement of ST's capital structure**
- **ST's estimated gain after tax to be recorded in Q210 P&L: ~\$245M***

* Based on Micron's trading price of \$8.75 per share on May 6, 2010.

A Solid Financial Foundation



(US\$ million)	Dec. 31, 2008	Dec. 31, 2009	Mar. 27, 2010
Available Cash	1,640	2,394	2,342
Restricted Cash	250	476	368
Marketable Securities, Non-current	242	42	47
TOTAL	2,132	2,912	2,757
Total Financial Debt	(2,677)	(2,492)	(2,191)
Net Financial Position	(545)	420	566

DIVESTITURES

- \$1.1B net proceeds from M&A in 2009
- Sale of Numonyx in May 2010: will increase liquidity by an estimate of over \$500M after lock-up period
- Sale of Phoenix signed in May 2010

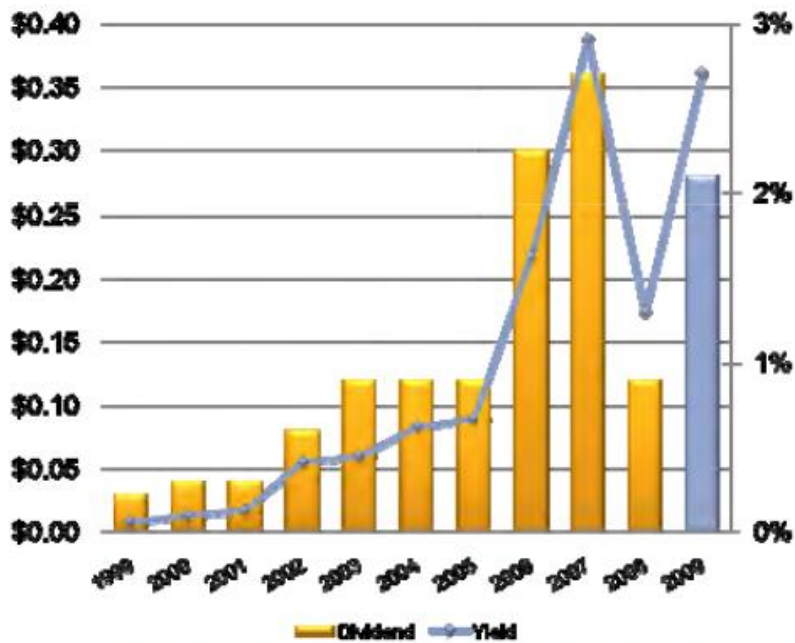
ARS LITIGATION

- February 2009: won FINRA award ordering Credit Suisse to pay to ST \$406M plus interest
- December 2009 collected \$75M
- March 2010: won in US District Court: confirms award and denies CS motion to vacate
- CS may still appeal but based on the award and the Federal Court, ST can expect to collect a further \$354M including interest

2016 CONVERT BOND

- Dec 2009 / Jan 2010: repurchased \$316M
- In Q210 repurchased additional \$55M
- 15.3M shares to be cancelled
- Redemption of residual \$673M likely due in February 2011

Dividend Evolution



Dividend Yield as of
May 31, 2010:

Company	% Yield**
MCHP	4.85%
TSM	4.58%
MXIM	4.45%
STM	3.62%
LLTC	3.16%
INTC	2.74%
XLNX	2.49%
NSM	2.24%
AMAT	1.91%
KLAC	1.92%
TXN	1.89%
BRCM	0.90%

Dividend increased to \$0.28 per share representing ~3.6% yield*

* 2009 annualized dividend is payable in four equal installments: May, August and November 2010 and February 2011.

** Source: Capital IQ



Our Opportunities

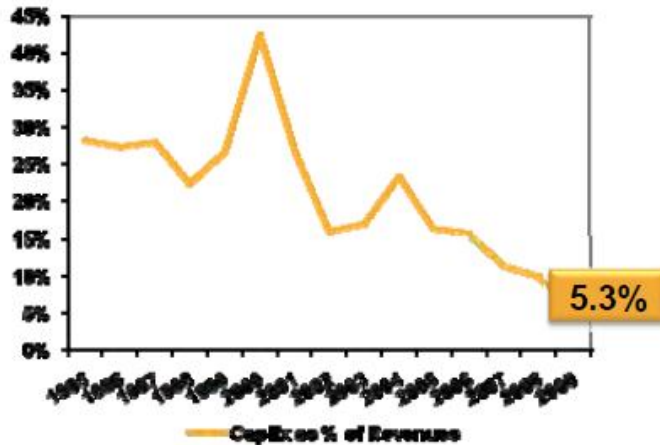
STMicroelectronics

Assets Lighter Strategy

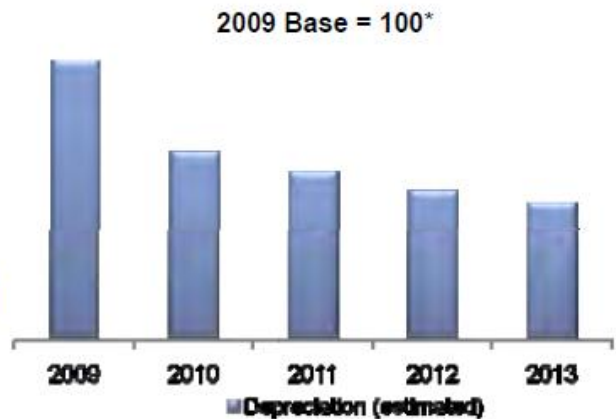


- Sustainable 5% to about 7% capex-to-sales ratio in a cycle
- Targeting ~20% increase in capacity (internal & external) Q409 vs. Q410

CapEx to Sales Ratio



Depreciation by Wafer

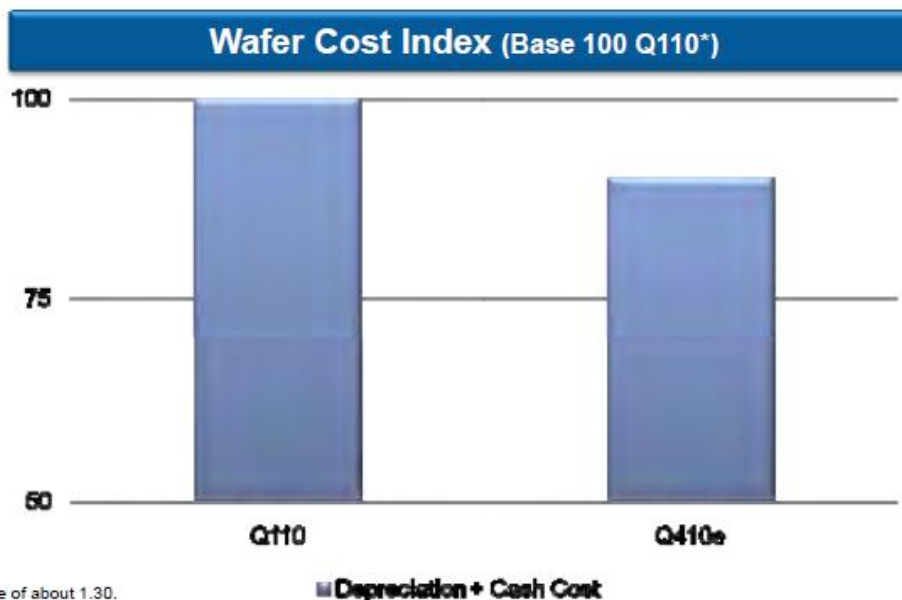


*Based on assumed €/€ rate of about 1.30.

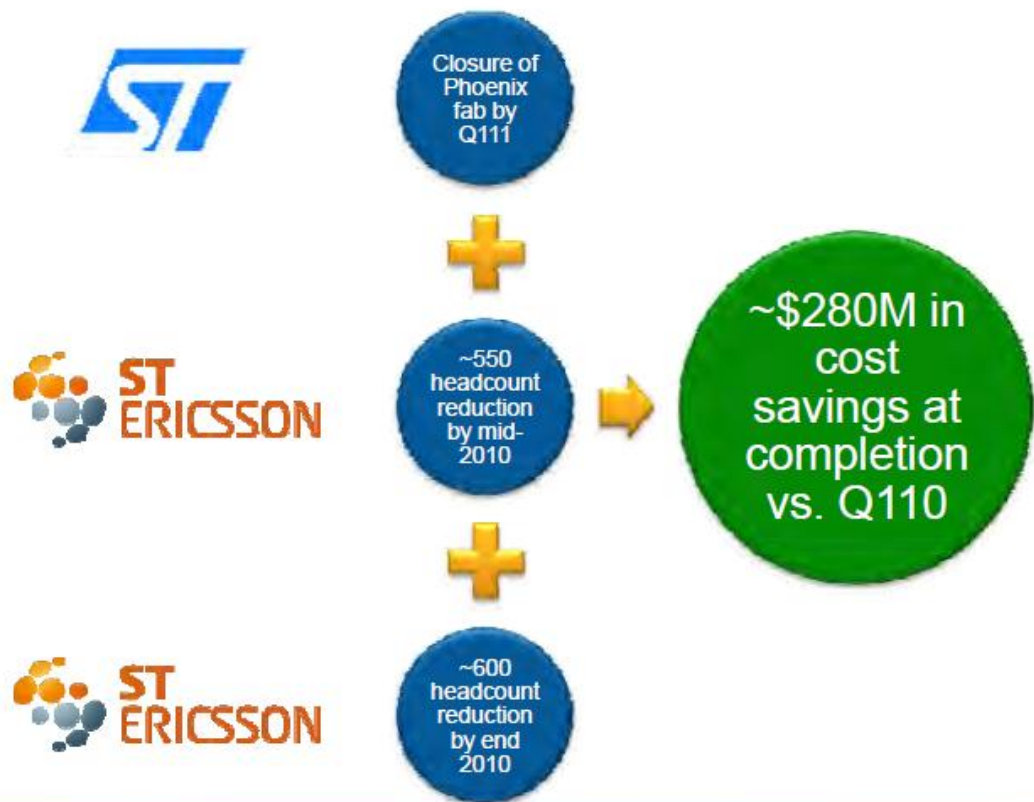
Continuous Focus on Cost Reduction



- Manufacturing focused to reduce wafer costs, after return to full loading
- Currency, cash cost efficiency and roll-over depreciation are expected to contribute to about 10% wafer cost reduction from Q110 thru Q410*
- Further cost reduction after the final phase-out of Phoenix fab, from Q210
- Assembly cost reductions driven by volume, shift to Asia and Gold-Copper conversion



Completing the On-Going Restructuring



Currency Exposure



Total Costs (COGS+OpEx) By Currency (Q110)



Other 5% SEK 5%

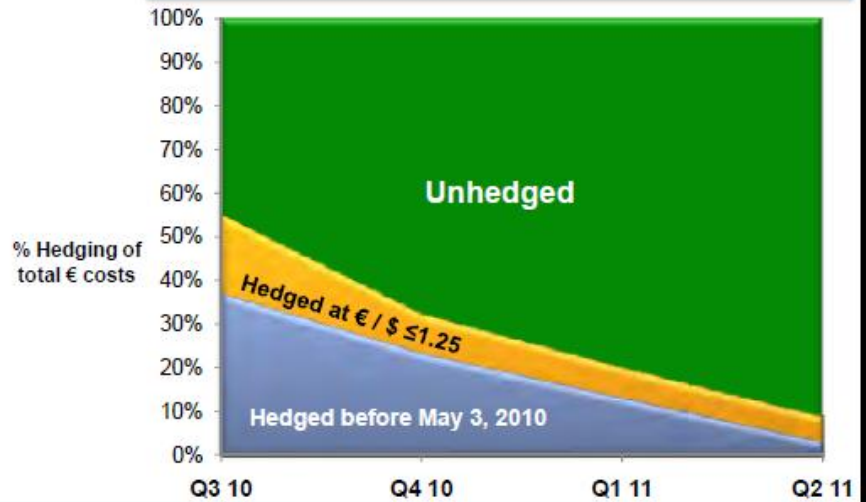
*Euro (€) includes currencies such as GBP, CHF, MAD Morocco.

**As of May 31, 2010.

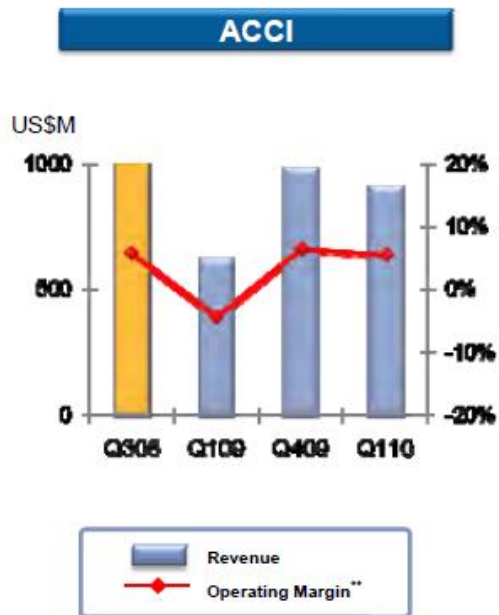
Quarterly Currency Effect: +1% change

- ±\$4 to \$5 million impact to gross profit
- ±\$4 to \$5 million impact on operating expenses
- ±\$8 to \$10 million on operating profit

Hedging: % of Euro exposure currently hedged**



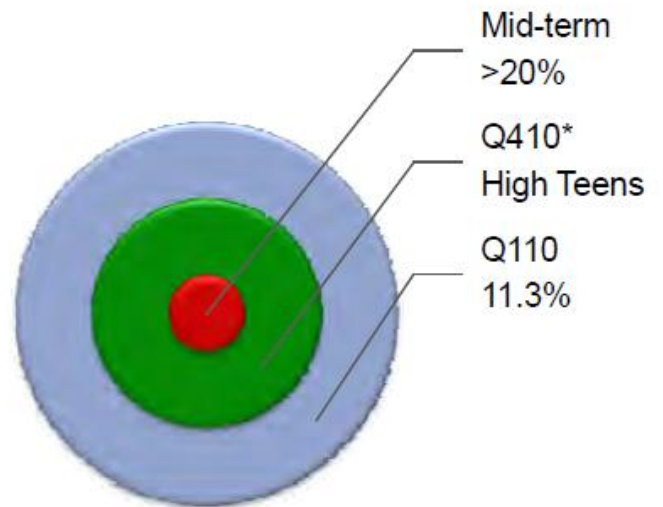
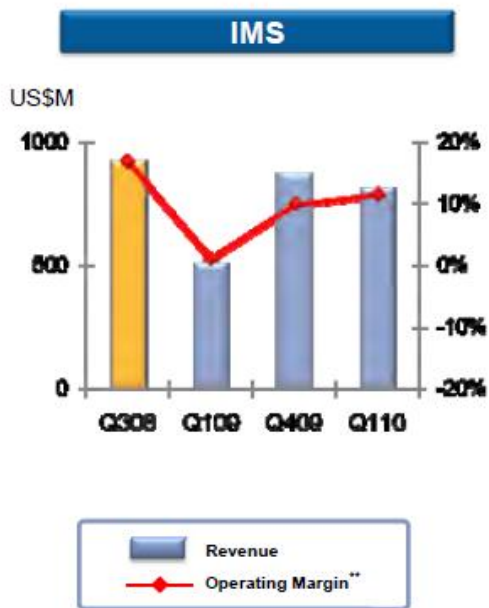
ACCI: Performance & Targets*



*Q410 assumes revenues based on a substantial continuity in market demand trends and an effective exchange rate between 1.25 €/€ to 1.30 €/€.

**Segment operating results exclude, among others, unsaturation charges.

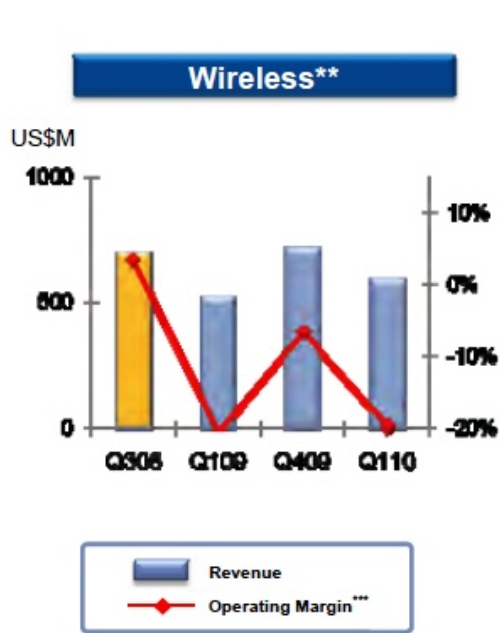
IMS: Performance & Targets*



*Q410 assumes revenues based on a substantial continuity in market demand trends and an effective exchange rate between 1.25 €/€ to 1.30 €/€.

**Segment operating results exclude, among others, unsaturation charges.

Wireless: Performance & Targets*



ST-Ericsson plans profitability at quarterly revenue run rate of \geq \$750 million, after restructuring is complete

*Q410 assumes revenues based on substantial continuity in market demand trends and an effective exchange rate between 1.25 €/€ to 1.30 €/€.

** See appendix – Q308 included 2 months of former NXP business and was before formation of ST-Ericsson.

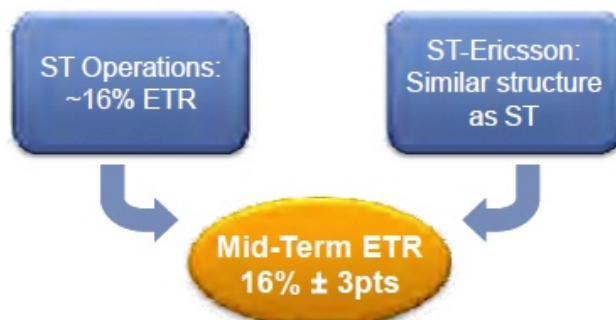
***Segment operating results exclude, among others, unsaturation charges.

Effective Tax Rate



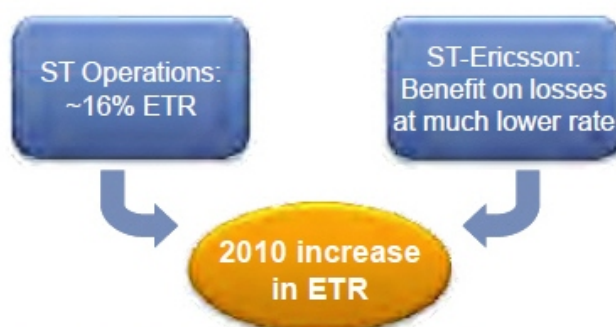
- **Sustainable ETR: 16% ± 3 points**

- Once ST moves to a higher overall profit before tax and a more uniform distribution of earnings among ST operations and ST-Ericsson
- Tax structure is still a competitive advantage



- **Short-term ETR**

- Currently estimate a significantly higher ETR and will improve as ST-Ericsson recovers from losses





Our Target Model

Financial Model*



Transitional Model:

~ All segments at / above break-even
Low / mid-single-digit operating margin
Back to net operating cash flow of 6% to 10% of sales

Q409 – Q110 Achievements

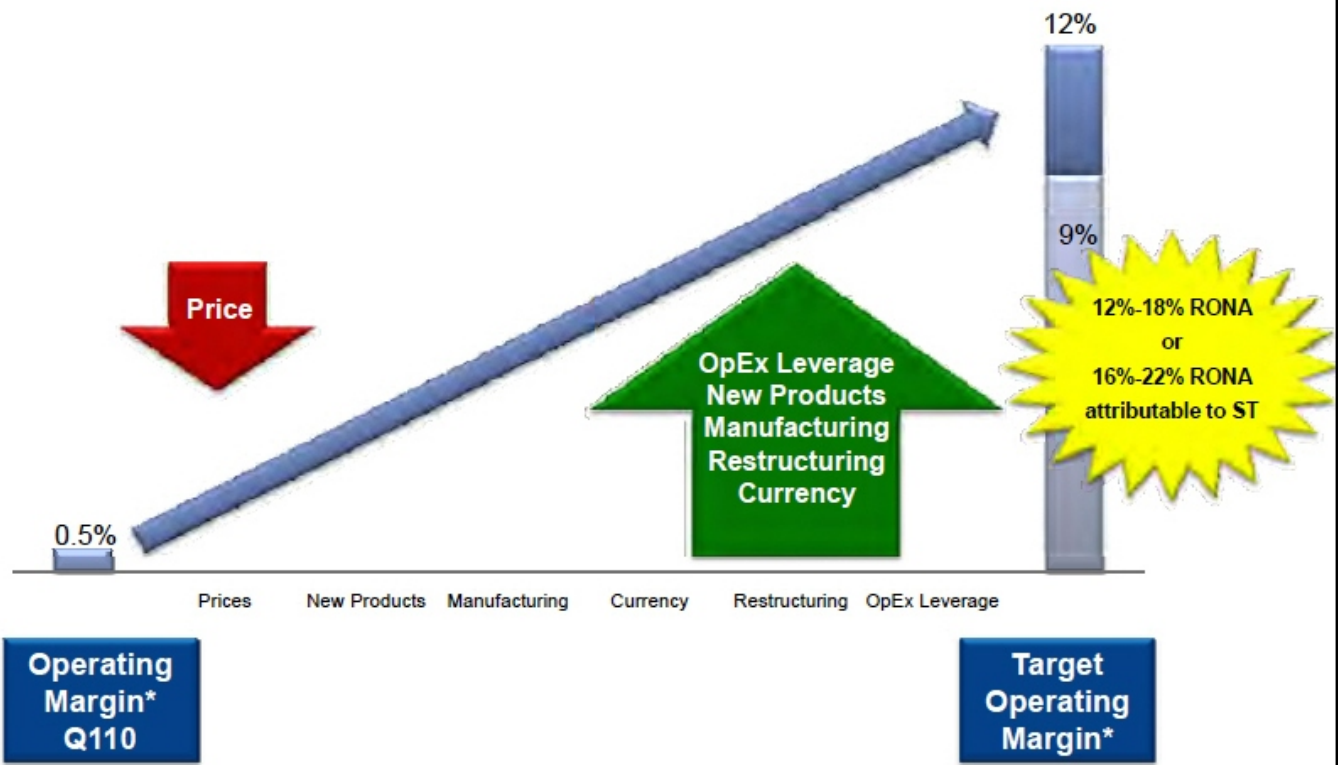
Operating margin: 3.5% in Q4 down to 0.5% in Q110 on seasonally lower revenues
Excluding Wireless: operating margin 7.4% in both periods
Net operating cash flow: 8.6% and 7.6% of sales respectively in the two periods

ST Financial Model

9% to 12% operating margin x 1.3-1.4 net assets turns
12% to 18% return on net assets (RONA) target
Double digit net operating cash flow as % of sales

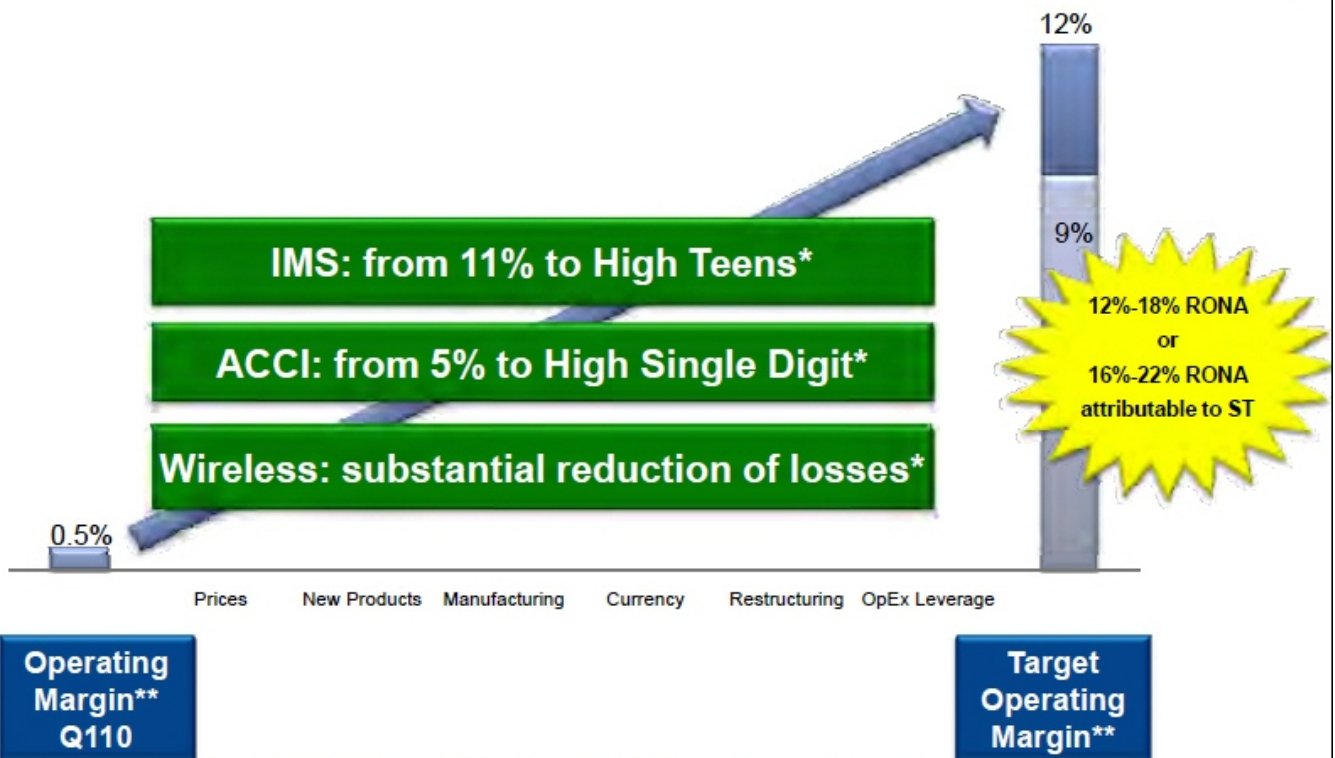
*See appendix

...Achievable in Short Term



* Operating margin before restructuring charges: not a GAAP measure, please see appendix.

...by Improvements in All Segments*



*Product segment targets assume substantial continuity in market demand trends and an effective exchange rate between 1.25 €/€ to 1.30 €/€.

**Operating margin before restructuring charges: not a GAAP measure, please see appendix.

Shareholders Value Proposition



- **Net operating cash flow** is defined as net cash from operating activities minus net cash used in investing activities, excluding payment for purchases of and proceeds from the sale of marketable securities (both current and non-current), short-term deposits and restricted cash. We believe net operating cash flow provides useful information for investors and management because it measures our capacity to generate cash from our operating and investing activities to sustain our operating activities. Net operating cash flow is not a U.S. GAAP measure and does not represent total cash flow since it does not include the cash flows generated by or used in financing activities. In addition, our definition of net operating cash flow may differ from definitions used by other companies.
- **Net financial position: resources (debt)**, represents the balance between our total financial resources and our total financial debt. Our total financial resources include cash and cash equivalents, current and non-current marketable securities, short-term deposits and restricted cash, and our total financial debt include bank overdrafts, the current portion of long-term debt and long-term debt, all as represented in our consolidated balance sheet. We believe our net financial position provides useful information for investors because it gives evidence of our global position either in terms of net indebtedness or net cash by measuring our capital resources based on cash, cash equivalents and marketable securities and the total level of our financial indebtedness. Net financial position is not a U.S. GAAP measure.
- **Adjusted Net Earnings** is a non-GAAP measure and is used by the Company's management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items. Non-GAAP earnings excludes impairment, restructuring charges and other related closure costs attributable to Parent Company's shareholders, the impact of purchase accounting (such as in-process R&D costs and inventory step-up charges), other-than-temporary impairment charges on financial assets and impairment related to equity investments, net of the relevant tax impact.
- **Financial Model:** Presented at May 2009 Analyst Day
- **Key Information on Consolidation / Deconsolidation:**
 - ST completed the deconsolidation of its Flash Memory Group (FMG) segment and took an equity interest in Numonyx on March 30, 2008, which is reported under the equity method of valuation with a one quarter lag in reporting.
 - ST-NXP Wireless, a joint venture initially owned 80% by ST, began operations on August 2, 2008 and was fully consolidated into ST's operating results. On February 1, 2009 and prior to the closing of the merger of ST-NXP Wireless and Ericsson Mobile Platforms to create ST-Ericsson, ST exercised its option to buy out NXP's 20% ownership stake of ST-NXP Wireless.
 - ST-Ericsson, a joint venture owned 50% by ST, began operations on February 3, 2009 and is consolidated into ST's operating results as of that date. ST-Ericsson is led by a development and marketing company and is consolidated by ST. A separate platform design company providing platform designs mostly to the development and marketing company is accounted for by ST using the equity method.
- **Wireless Segment:** As of February 3, 2009, "Wireless" includes the portion of sales and operating results of the 50/50 ST-Ericsson joint venture as consolidated in the Company's revenues and operating results, as well as other items affecting operating results related to the wireless business.
- **Sales recorded by ST-Ericsson and consolidated by ST are included in Telecom and Distribution**

Pre-Tax Items to Adjusted Earnings*



OPERATING RESULT NET EARNINGS	<i>In US\$M</i>					
	Q308	Q409	Q110		FY09	FY08
U.S. GAAP Net Earnings	(289)	(70)	57		(1,131)	(786)
NXP Wireless Inventory Step-up	57					88
Genesis in Process R&D						21
NXP Wireless in Process R&D	76					76
Impairment & Restructuring Charges (attributable to Parent Company's shareholders)**	22	65	20		240	481
Other-than-Temporary Impairment	14	68			139	138
Numonyx Impairment	300				203	480
Estimated Income Tax effect of Adj.	(46)	(27)	(15)		(79)	(141)
Adjusted Net Earnings*	134	36	62		(627)	356

*See appendix.

**Total impairment & restructuring charges were \$96M in Q409 and \$33M in Q110.



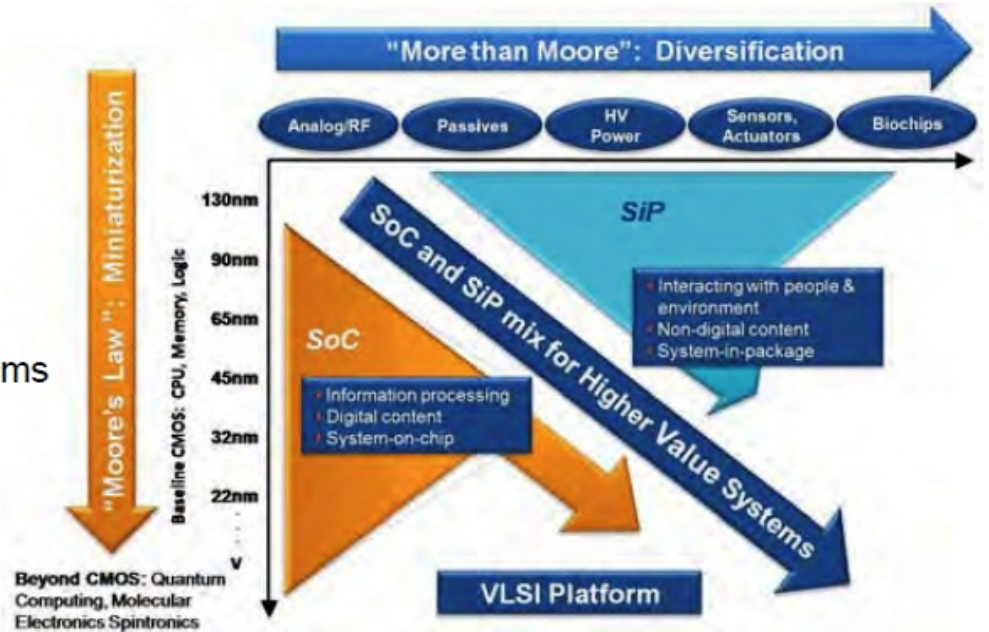
Sustainable Technology & Leadership

Jean-Marc Chery
Chief Technology Officer

STMicroelectronics

Technology is bringing a competitive advantage to ST in the field of multimedia convergence and power applications

- R&D leadership & technology segmentation
- R&D value chain breakdown & management
- Technology programs status & roadmap
- Summary



- **Fast Time to Market**
 - First device tape out
 - Device volume and yield ramp up

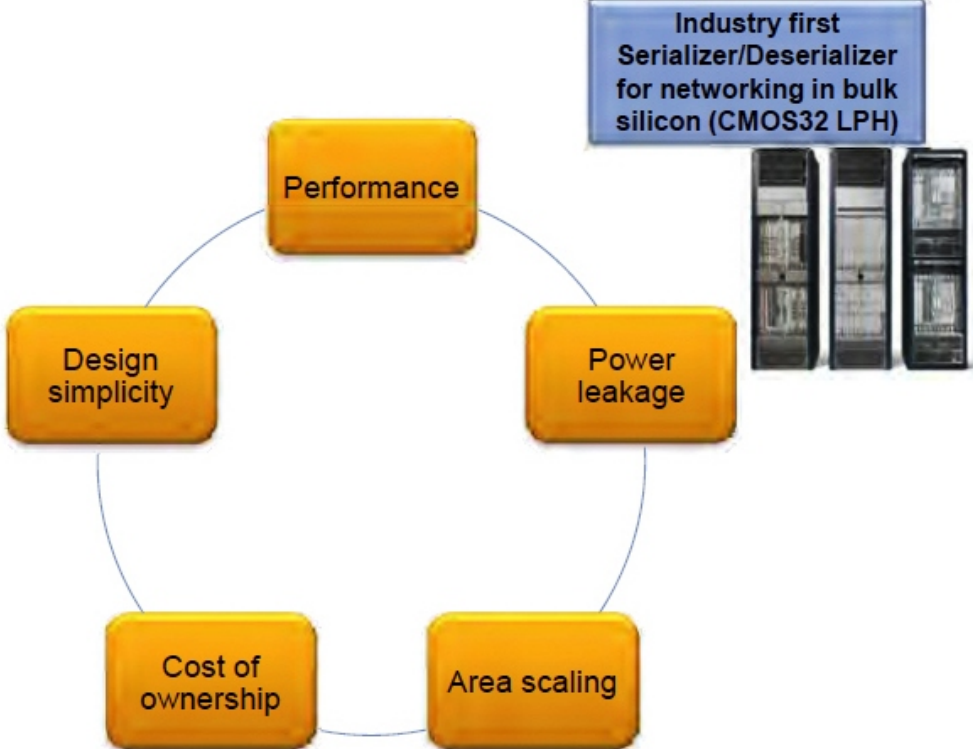
- **Innovation**
 - Performance, power, area scaling
 - Cost of ownership, design simplicity

- **Supply Chain Multi Sourcing**
 - Time to market first source
 - Second / alternative source

CMOS Logic/Analog Characteristics



- High Performance
- General Purpose
- Low-Power
- Analog / Derivatives



Value Chain Breakdown



Fundamental Research	Advanced Semiconductor R&D	Technology Development	Manufacturing
<ul style="list-style-type: none"> ▪ Screen new materials & processes 	<ul style="list-style-type: none"> ▪ Innovation in integrated device & process technology 	<ul style="list-style-type: none"> ▪ Process qualification ▪ Technology to design ▪ Design platform qualification ▪ Device performance master plan 	<ul style="list-style-type: none"> ▪ Fast yield learning curve ▪ Multi source enablement
<p>Accelerates technology innovation and leverages multi third party competence centers</p> <ul style="list-style-type: none"> ▪ Foundation / advanced R&D through joint academia / research institutes cooperation <ul style="list-style-type: none"> ▪ CEA LETI: a cornerstone ▪ Advanced CMOS, both low power and general purpose, R&D through ISDA <ul style="list-style-type: none"> ▪ Advanced R&D pre T0 		<p>Balancing technology operations with internal/third party competence centers:</p> <ul style="list-style-type: none"> ▪ Advanced CMOS process through International Semiconductor Development Alliance (ISDA) with strong concurrent development activities ▪ Analog and Derivatives process through internal cluster of Agrate and Crolles ▪ Distributed design enablement through Agrate / Crolles / Greater Noida 	

Leadership, Experience, Know-How, Commitment

- The **CORRECT**, early choice on:
 - Materials
 - Process flow
 - Device architecture



...creates the difference on device ideal balanced performance vs. applications

Distributed, Cooperative R&D

- Leverages best-in-class innovation vs.
 - Targeted products
 - Critical decision factors
 - Technologies
- Mitigates risk of choice
- Shares expenses



Concurrent ISDA engineering enables best-in-class and lean development techniques for:

- **Better silicon proven solution and lower cost**
- **Manufacturing synchronization for wafer fab**
- **Multi sourcing enablement**
- **Fast learning cycle for time to market**

Focused ST cluster on advanced CMOS concentrating activities of industrialization, derivatives/analog development, design platform enables:

- **Fast volume, yield learning internal ramp up**
- **Lean capex and opex**
- **Technology differentiation**
- **Best-in-class technology to design, enablement**
- **Efficient design platform**

Strengthening core competencies: device architecture, process integration, design enablement

■ Crolles:

- Low-power device
- RF add-on devices
- Embedded Dram and high performance device
- CMOS imaging sensor
- Photo lithography, TSV and 3D



■ Agrate:

- Smart-Power and analog
- Embedded Nvm



■ Greater Noida:


- Design enablement



- **Competitive innovation driven by ST's proactive approach and credibility**
- **Global and networked R&D competence centers optimized and managed by ST**
- **ST's commitment to a sustainable innovation expenses-to-sales ratio**

Status of Key Programs

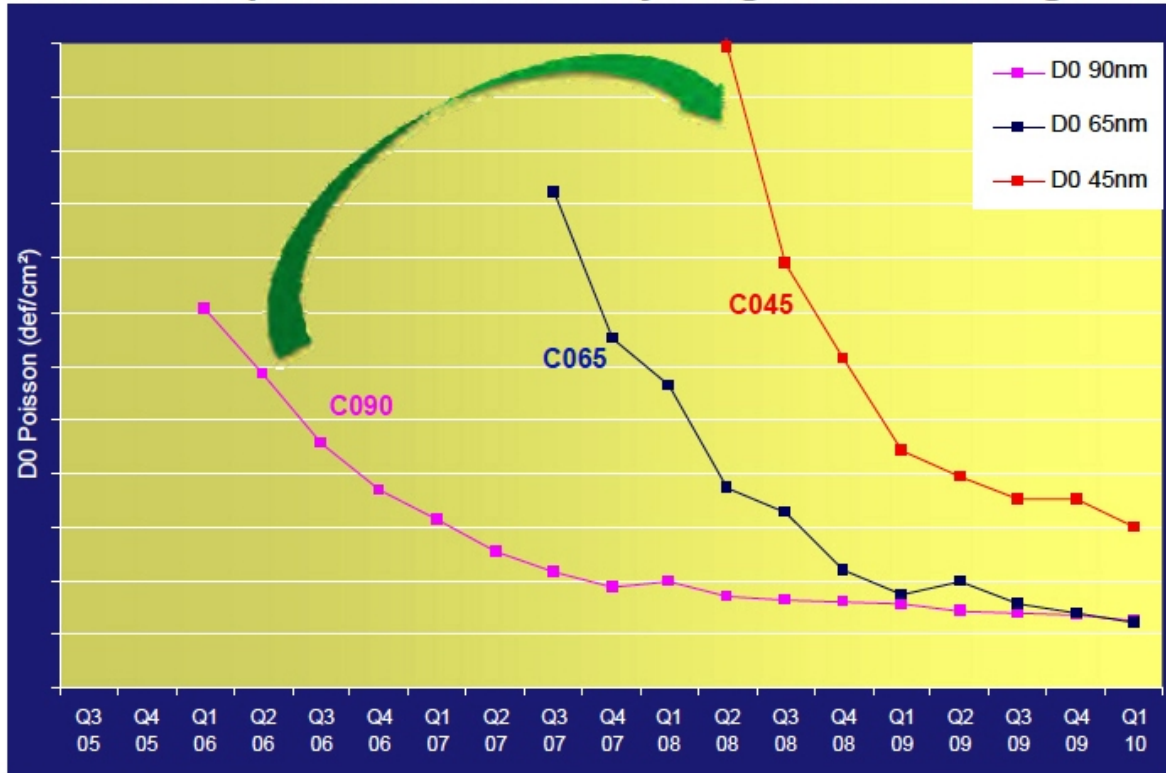


CMOS 65LP	Mass production yielding at best-in-class
CMOS 55LP	Production ramp up started Q309
CMOS 45LP	Prototyping, production ramp up Q410
CMOS 40LP	Prototyping, production ramp up Q211
CMOS 32LP	Prototyping, production ramp up Q311
CMOS 32LP	Crolles 300 installing capacity 
CMOS 28LP	Designing, prototyping Q211

Yield Learning – D₀ Trend



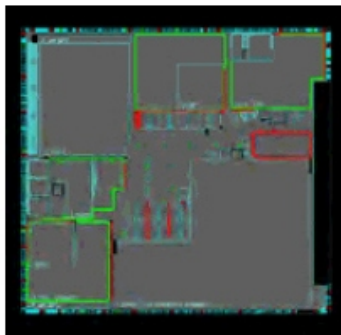
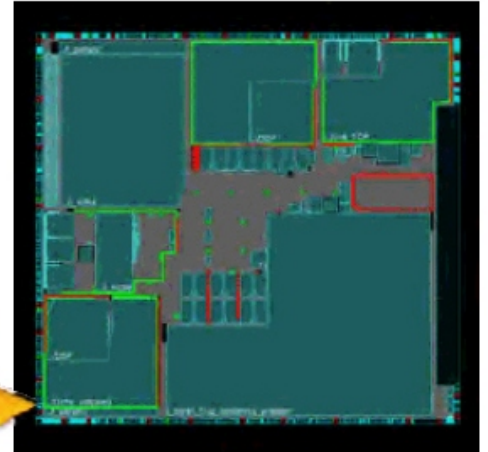
Tremendous improvement of time to yield generation after generation



U8500 Platform

Designed on ST leading-edge, LP 45nm -
a key enabler to achieve the performance

ST-Ericsson breaks through
smartphone performance barrier
Cortex A9 @ 1.2 GHz in Feb. 2010

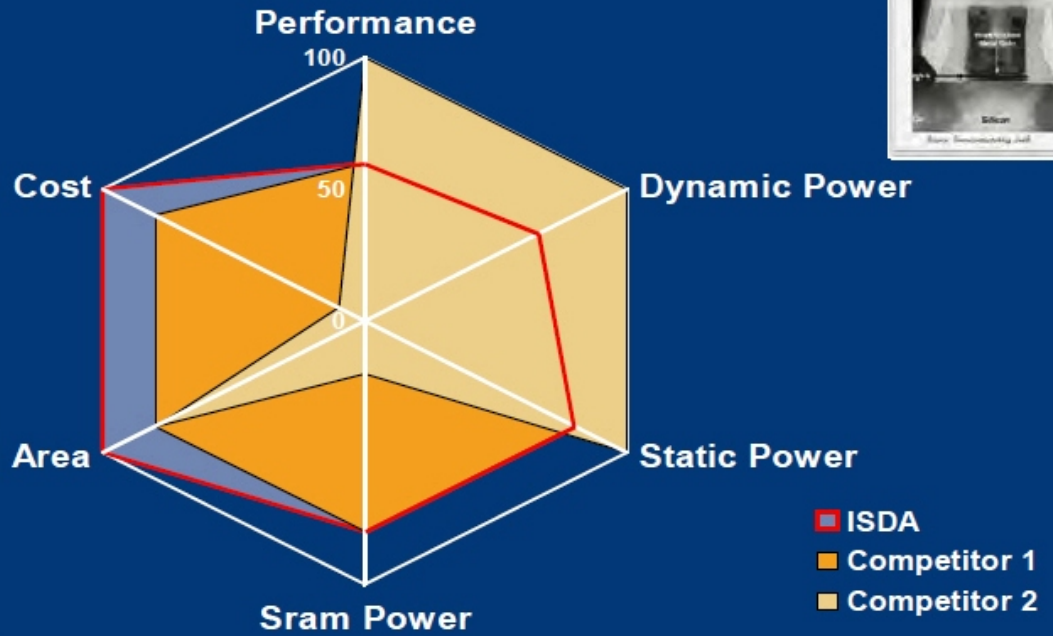
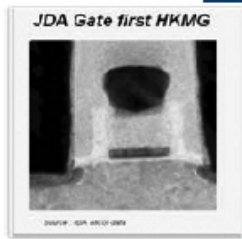
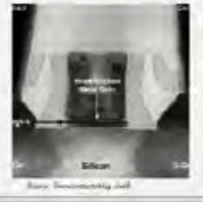


Immediately ported to the LP 32nm
ensuring economical sustainability
and further performance improvement

Cortex A9 @ 1.5 GHz

HKMG gate first ideal for balanced performance, power, area scaling, cost and design simplicity

Intel's Gate last HKMG



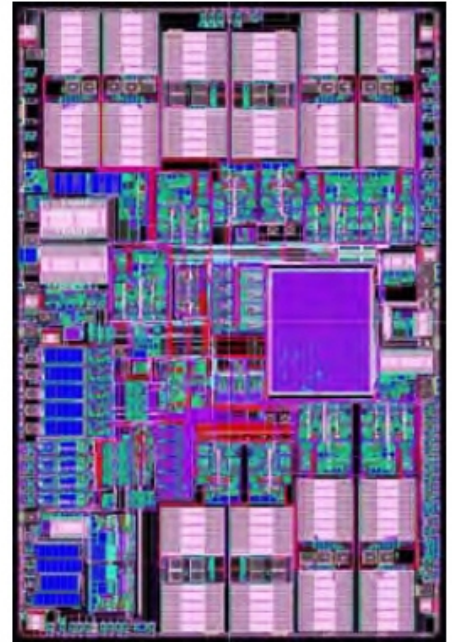
Other Key Programs



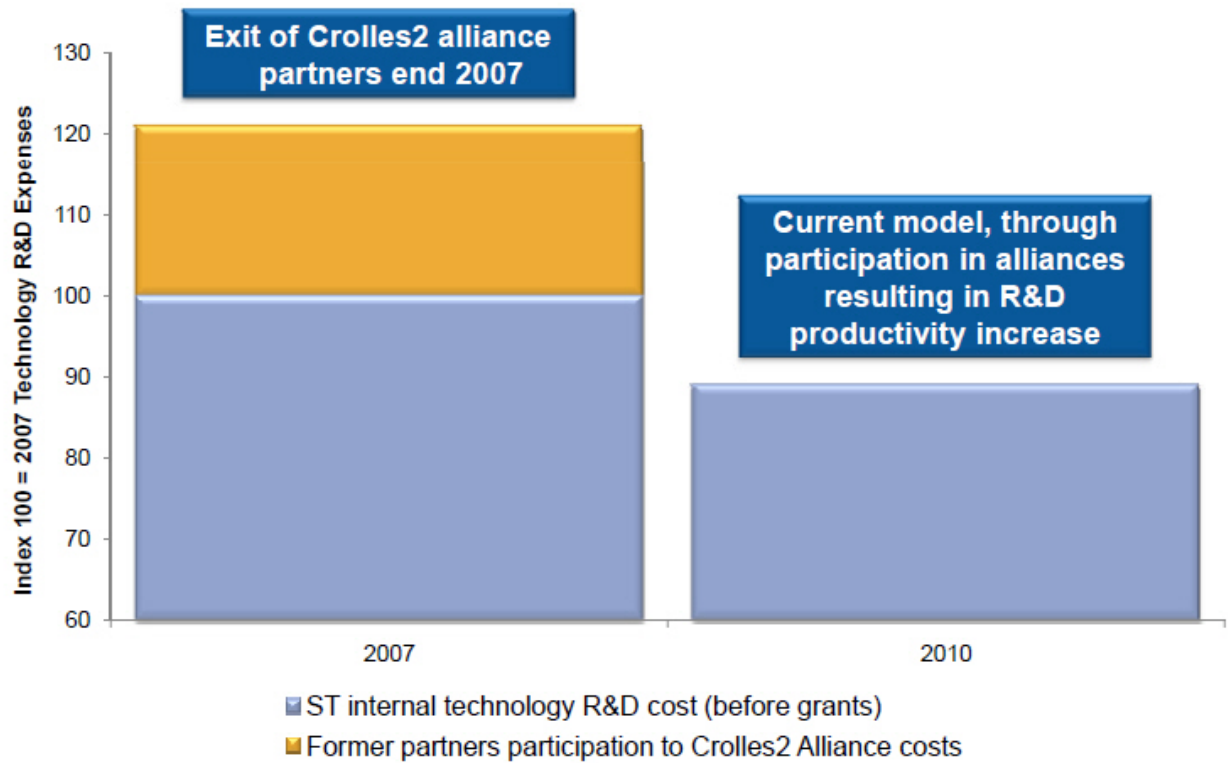
CMOS 65RF	Prototyping, production ramp up Q310
CMOS F9	Production ramp up started Q309
CMOS F10	Prototyping, production ramp up Q310
BCD8 A	Production ramp up started Q309
BCD8 AS	Prototyping, production ramp up Q310

Key description

- **Technology: BCD8A-40V 4 metal Cu – 30 Mask**
- **Die size: 51mm²**
- **Challenges:**
 - 1st automotive BCD8 product
 - New HIQUAD110 package
 - Bonding: CU wire 1mil POA, 2mils passive, UBM (NiPd)



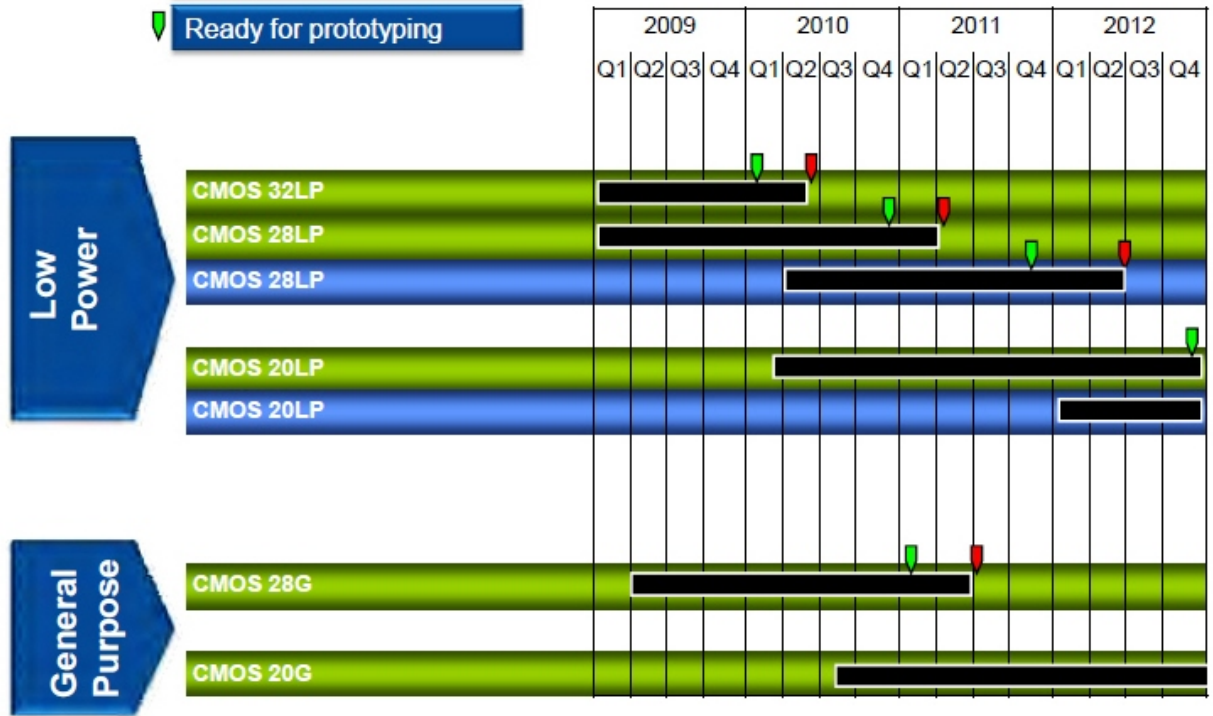
VLSI Platform R&D Model








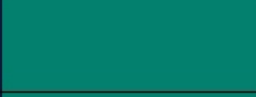







CMOS Technology Roadmap






- Ready for production
- Ready for prototyping





CMOS45...28 LP/G Manufacturing Source

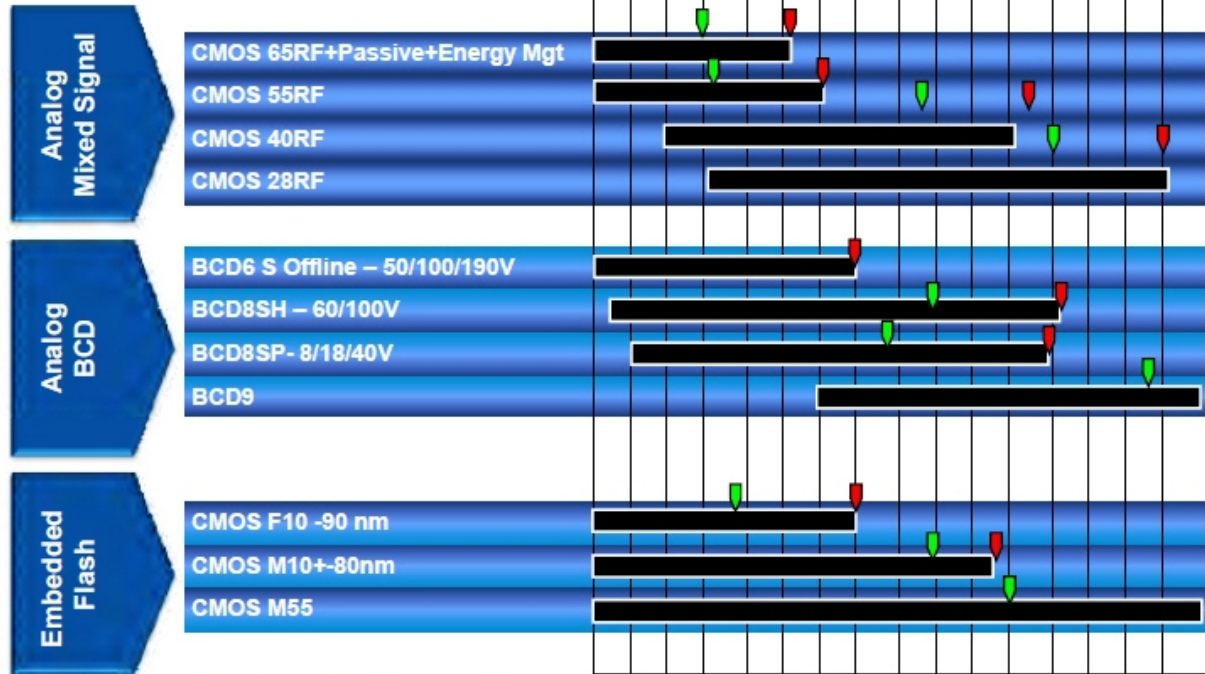
Technology / Source	First TTM	Second	Alternative
CMOS 45LP			No
CMOS 40LP			
CMOS 40G		No	No
CMOS 32LP			No
CMOS 28LP			
CMOS 28G			No

	Crolles 300
	One of multi-foundries source
	Another one of multi-foundries source

Derivatives/Analog Technology



-  Ready for production
-  Ready for prototyping



Derivatives/Analog Manufacturing Source

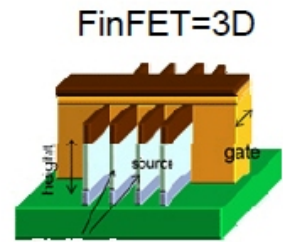
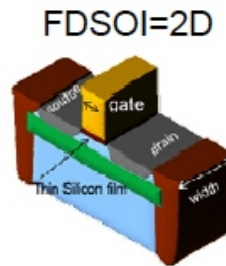
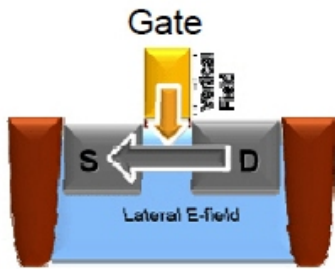
Technology / Source	First TTM	Second
HC MOS9A	Crolles 200	Foundry *
CMOS65/ 55RF	Crolles 300	Foundry *
CMOS55 eFlash	Crolles 300	Foundry *
CMOSF10	Rousset 8	Foundry *
BCD8	Agrate 8	Catania M5

* One out of multi-foundries sources

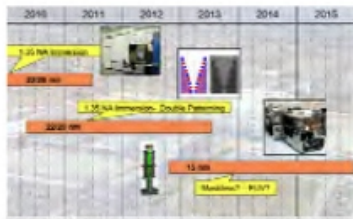
The Future is Bright...



Devices architecture (FDSOI, FinFET 3D)



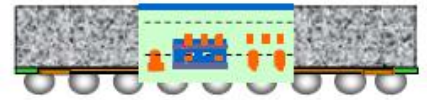
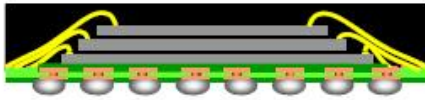
Photolithography (multiple patterning, extreme UV)



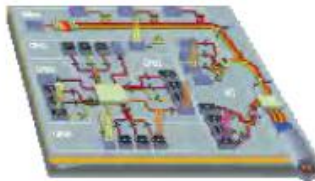
...as Innovation Drives Breakthroughs...

3D/Heterogeneous integration: a competitive advantage on the solution cost at same device performance, power leakage and area scaling

Solution cost is driven by process and design complexity

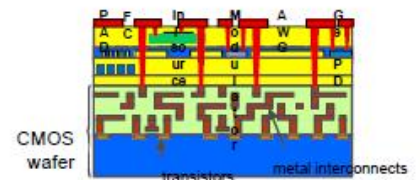


Photonics on Silicon



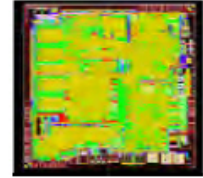
- Communication bandwidth rapidly increasing from few Gb/s to 100Gb/s
- Copper wire technology not able to sustain such data rates
- Photonics on silicon technology allows die to die and within die optical communication

- Optical connections already present in servers/routers rack to rack communications



Derivatives / Mixed Signal Analog trends:

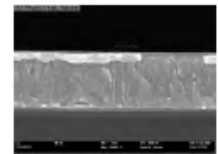
- Integration on single chip of digital analog and RF add on devices



- Flash cell architecture, driving area scaling

Power / Analog trends:

- Some increase in Logic content but decrease of die area with 160nm/130nm technology nodes
- New modules architecture and materials for better power / analog features





- **Enables differentiated / competitive product positioning through:**
 - Device integration and device add-on for derivatives / analog
 - Design enablement
 - Specific process modules for best device performance
 - Fast yield learning cycle time techniques
- **Cooperative model allowing leveraged capture of technology innovation and risk mitigation:**
 - Leverages: Full multi sourcing supply chain efficiency
- **ST's results and commitment:**
 - Demonstrating competitive advantage at 40nm; strengthening it again at 28nm, then offering most advanced platforms for derivatives/analog as well
 - Moving to 20nm and beyond, with increasing complexity and facing the industry's most challenging major architecture, process, and equipment disruptions
 - Continuing to invest in deep knowledge of process, design enablement, manufacturing and their interactions

Undisputed Leader in Multimedia Convergence and Power Applications



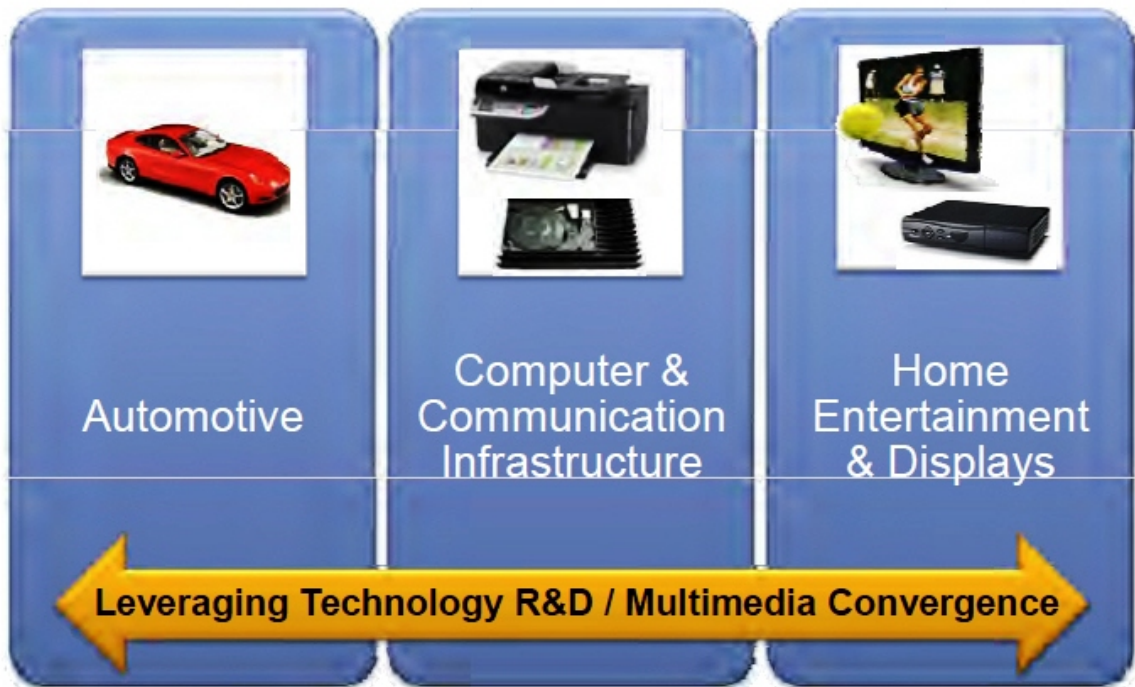
Multimedia Convergence & ACCI Sector Overview

Philippe Lambinet

General Manager, Home Entertainment & Displays Group

STMicroelectronics

ACCI Focus Applications

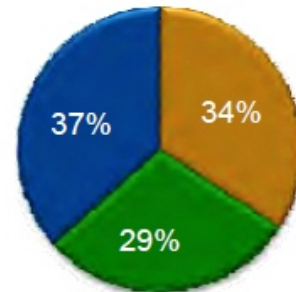
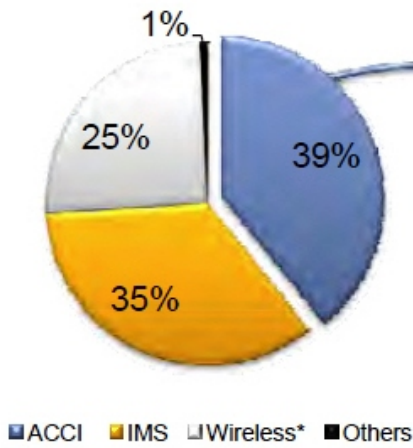


ACCI Revenues



ST Q110 Sales: \$2,325M

ACCI Q110 Sales: \$909M

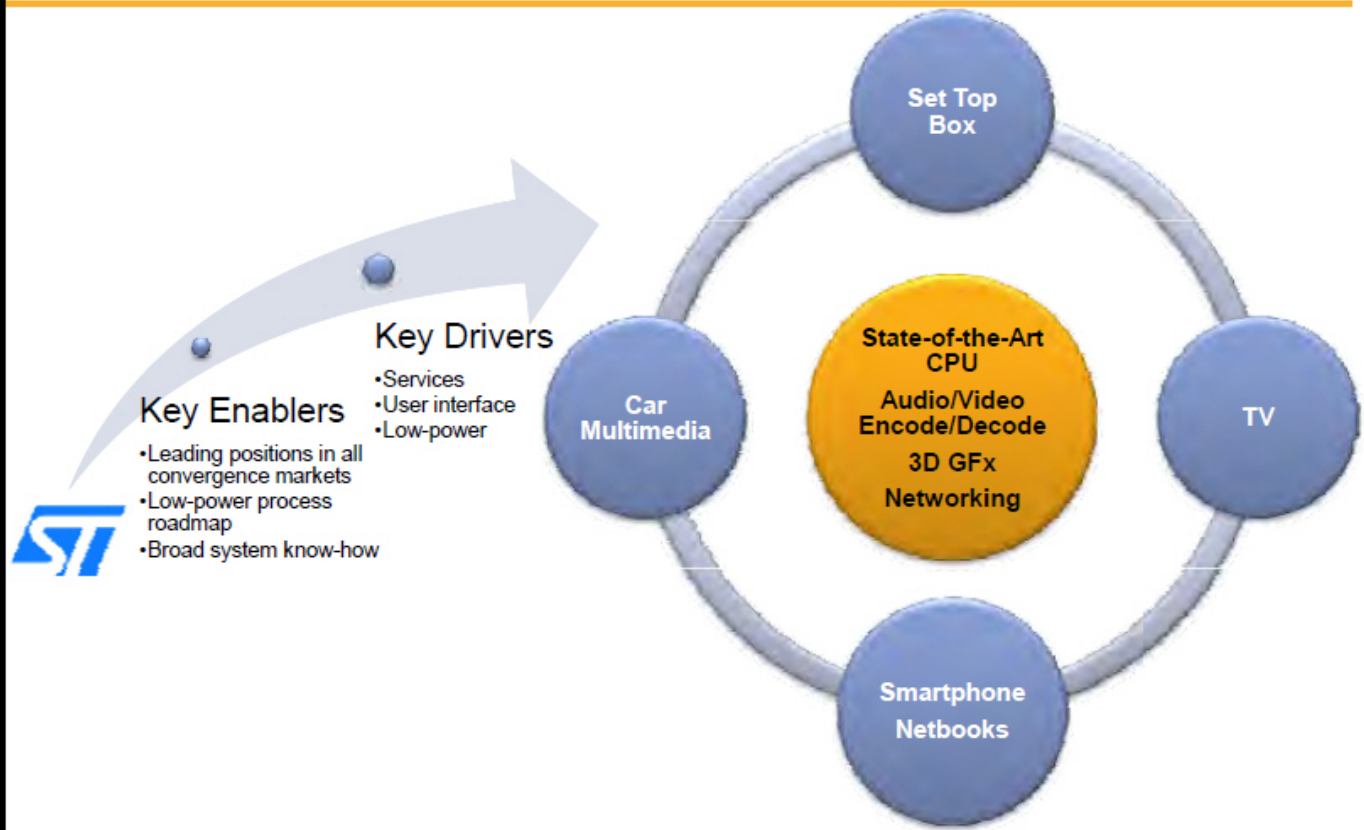


- Automotive (APG)
- Computer and Communication Infrastructure (CCI)
- Home Entertainment & Displays (HED)**

* See appendix

** Includes Imaging business

ST Driving Multimedia Convergence





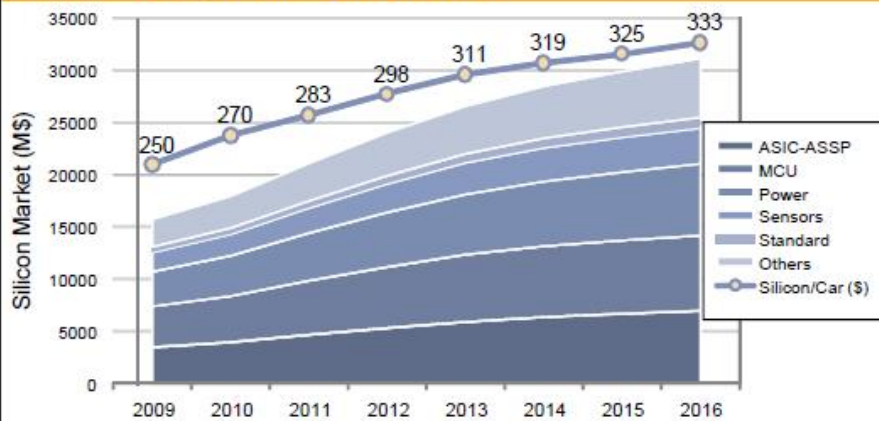
Automotive

STMicroelectronics

Automotive Market Growth Factors



More Cars, More Electronics



CAGR 2009-2016:
 Cars: 6.2%
 Electronics: 8.5%
 Silicon: 10.2%

Electronic ignition
 Central locking
 Car radio



1975
 25M cars

Electronic gearbox
 Air conditioning
 Antilock brakes
 Seat heating
 Automatic mirror



1985
 32M cars

Navigation
 Adaptive cruise ctrl
 Airbags
 Stability control
 Xenon light



1995
 36M cars

Night vision
 Telematics
 Bluetooth
 Start/stop
 Hybrids
 LED lighting



2005
 64M cars

Pedestrian detection
 Lane change
 Driver assist maps
 Car 2 car
 Internet
 Brake-by-wire
 Steer-by-wire
 Electric vehicles



2015
 86M cars

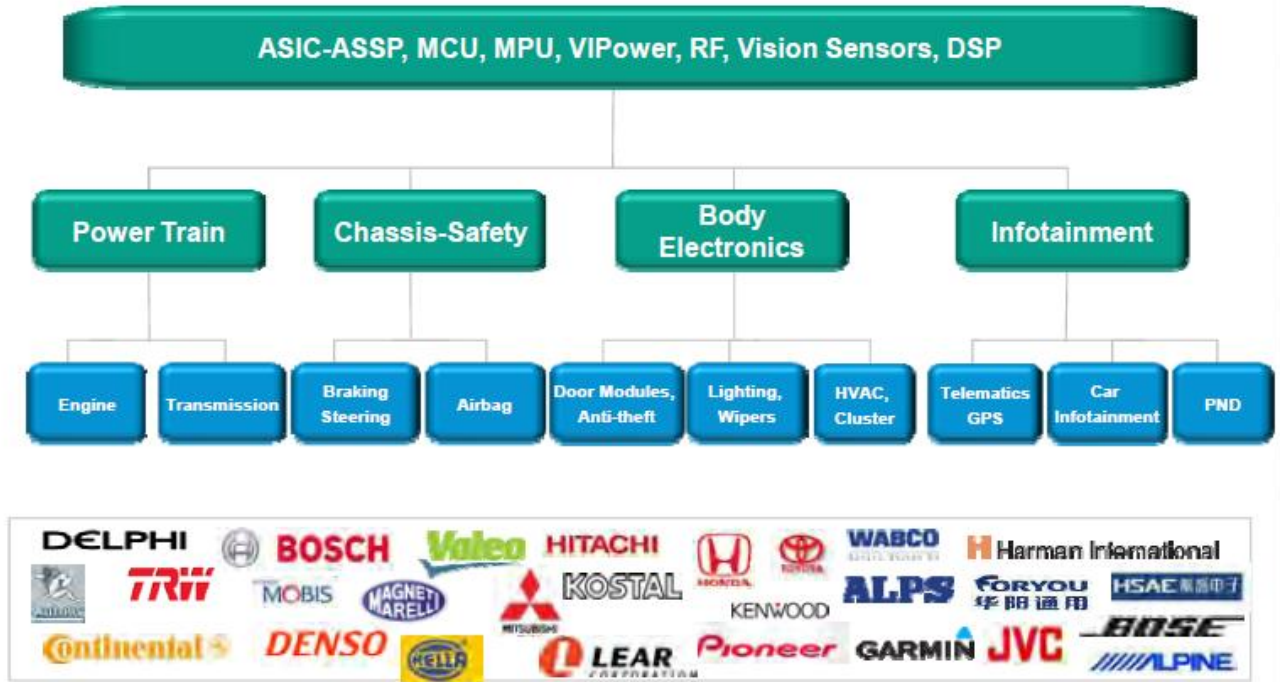
Source: Strategy Analytics

STMicroelectronics

ST: #3 in Global Automotive IC's



Products
Segments
Applications
Customers



Trends and Accomplishments in Automotive

Trend:

Innovation driven by social responsibility

- Emissions, safety, connectivity

ST Strategy:

Innovate with the leaders

Accomplishments:

- 32-bit MCU awarded by North American OEM for a new global transmission platform
- Chosen as a supplier of a next generation powertrain MCU platform with 55nm embedded flash for a major Tier 1
- 1st worldwide Li-Ion battery manager IC in a mass production plug-in hybrid vehicle
- Selected to develop a new radar baseband IC for adaptive cruise control for a US Tier 1



Trend: Large emerging markets with different needs and requirements

ST Strategy:

Fast time to market at different feature and cost points

Accomplishments:

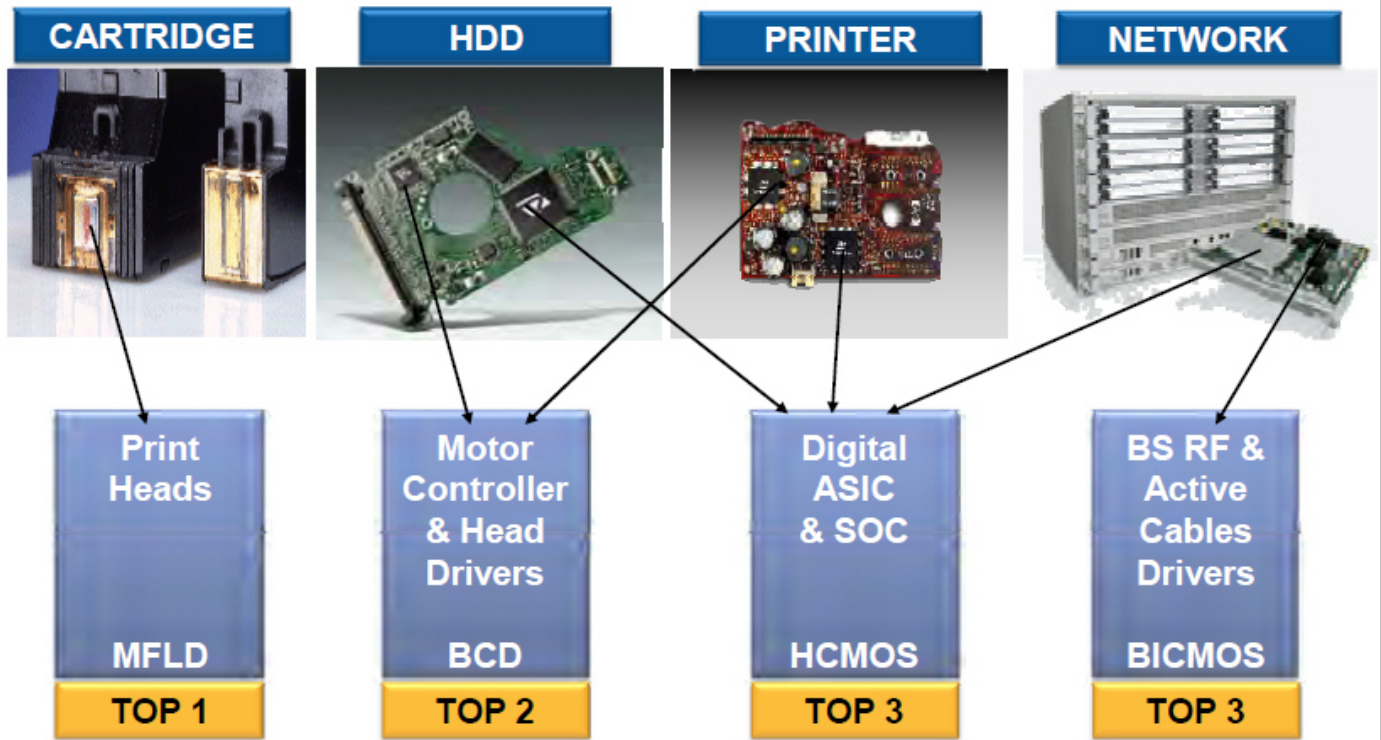
- Chosen to provide a full IC portfolio for Asia airbag platform of major European Tier 1
- MCU award by the fastest growing Chinese carmaker for all powertrain
- Steady #1 in China, doubling revenue in auto electronics every year from 2006 to 2011
- Gained 100% share of car radio tuner for two major Japanese Tier 1s for China



Computer & Communication Infrastructure

STMicroelectronics

Leader in Digital and Analog ASIC



Market Trends and Strategy in ASIC



Cloud Computing



Web Connected



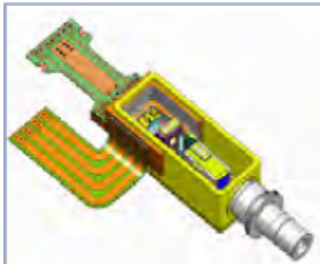
Internet Traffic



Green Systems

- Cloud computing will fuel the next wave, generating increasing demand for (green) infrastructure and transforming all applications in cloud conscious clients
- ASIC continues to be an effective win-win model for CCI customers and ST continues to be committed to it
- The strategy: expanded product offering and flexible business model
- Key achievements
 - Significant design wins in the areas of communication infrastructure and printers in digital
 - Launch of the first 32nm bulk platform for networking applications
 - Expansion of the SPEAr family with the launch of the 1300 series

CCI Growth Drivers



BiCmos ASIC
for AOC and RF



PrintHeads for
InkJet Printers



Digital ASIC for
Networking



Printer SOC and
SPEAr eMPU



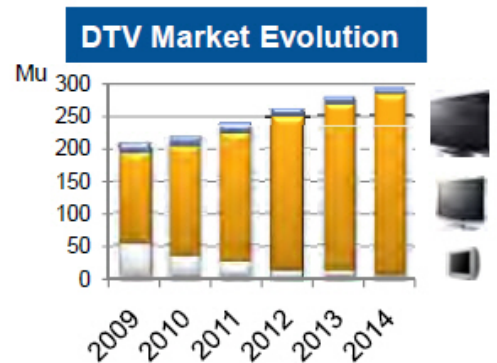
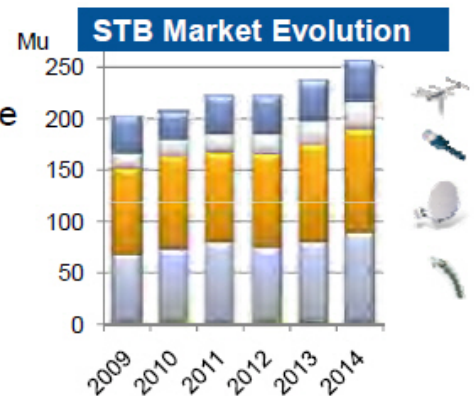
Home Entertainment & Displays

STMicroelectronics

Consumer Electronic Trends





- **Analog switch-off**
 - Increasing demand for Pay TV and FTA satellite
- **New connected services**
 - Content aggregation – broadcast & IP
 - Services across all consumer devices
- **Exciting entertainment experience**
 - 3D stereoscopic TV
 - GUI technologies – 3D graphics, MEMS...
 - LED BLU
- **Environmental factors**
 - Power consumption
 - Green production



Source: iSuppli, IMS

Our Application-Platform Evolution



	Gen. 1	Gen. 2	Gen. 3	Gen. 4
	HD H.264 market enabler	Best performance / cost ratio	New services New UI Client / Server	Fully open connected platform internet TV
	STi7100 7109, 5202	STi7105 7111, 7141, 7200 5211, 5206, ...	STi7108 71xx, 52xx	STi7xxx
	STi7103/FLi106xx MPEG2 H.264 VC1	STi7104/FLi326xxH 1000 DMIPS CPU <u>Introduction of:</u> AVS HD DDR2 e-SATA	FLi7510 Dual CPU & L2 cache >2000 DMIPS <u>Introduction of:</u> 1080p60 decode 3D GL-ES2.0 MOCA 1.x	FLi7xxx Multi-core SMP CPU >5000DMIPS <u>Introduction of:</u> Dual 1080p60 decode HD encode Display Port, MOCA 2
	Mass production Production: 2007 →	Mass production Production: 2009 →	Samples now Production: 2010 →	In design Production: 2011 →

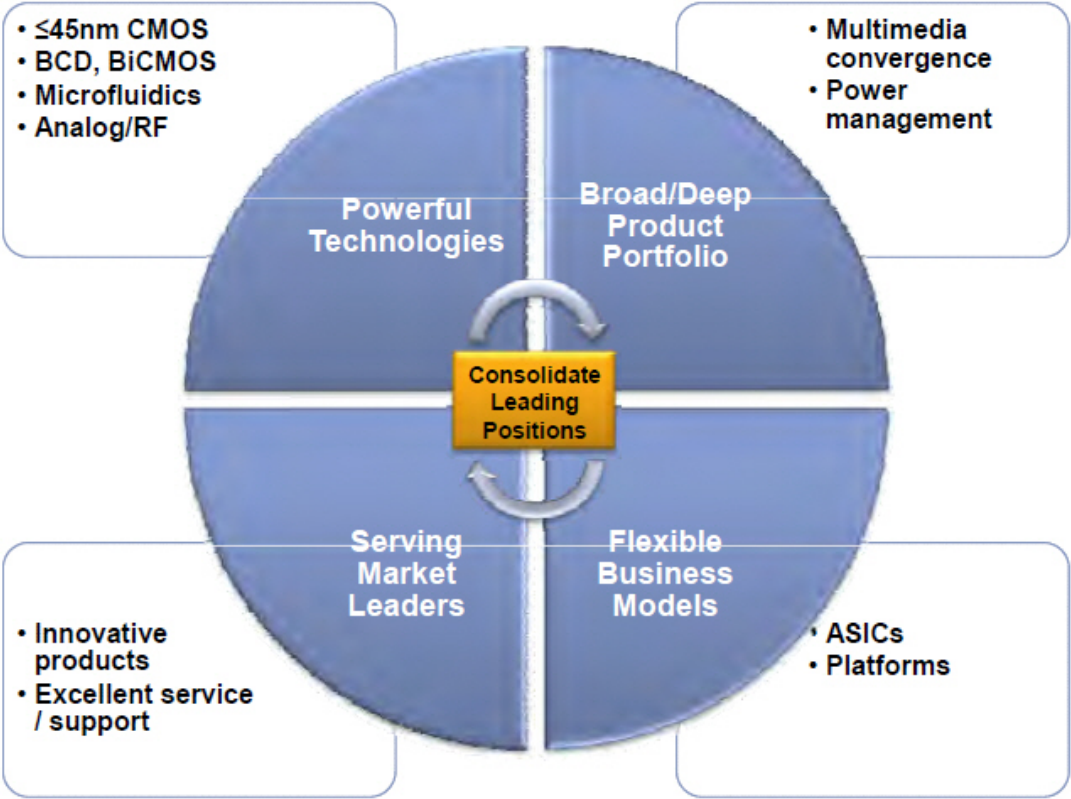
- **Gen. 2 based STB massively deploying**
 - Mass production started in June 2009
 - 55nm process with >10 products families
 - > 50 customers in production now
 - > 50% of ST total STB shipments from 2010

- **Gen. 3 getting ready for ramp up in 2010**
 - Gen. 3 introduced at CES 2010
 - Freeman/FLI7510 solution for DTV designed in at multiple partners
 - >20 partners enabled with STi7108 platform
 - Develop new category of STB & mediacenter
 - Develop new software for new services
 - RIA, GUI, gaming, mediaserver, ...

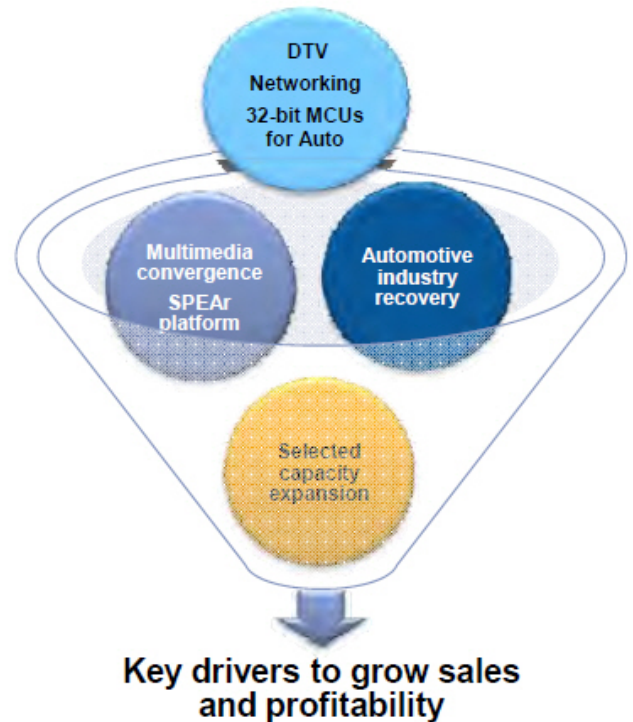


Conclusion

ACCI Key Strengths



- **Expand market share**
 - Leverage key strengths
 - Capture larger share of new markets / new product generations
 - Diversify / grow customer base
- **Participate in market recovery**
 - ACCI still significantly below pre-crisis level
 - Favorable market trends in targeted segments
 - Solid financial position is a competitive advantage
- **Increased focus of R&D effort**
 - Shared platform
 - Innovative ASICs business models
 - Collaborate with key customers, partners and research institutions
- **Optimize manufacturing**
 - Increase manufacturing efficiencies
 - Align capacity with demand
 - Accelerate development / move to new processes
- **Improve profitability towards high single digit operating margin by the end of 2010 and in the teens in the mid-term**





IMS Overview & Advanced Analog & Smart Power

Carmelo Papa

General Manager, Industrial & Multisegment Sector

STMicroelectronics

IMS at a Glance



Innovation Results:

- 5 new products per day
- ~20% of sales with products less than 2 years old
- 2 new system solutions (boards) per week

Technical Resources:

(designers, application engineers, technical marketing)

ANALOG & MEMS
45%

DIGITAL
35%

POWER DISCRETE
20%

2009 IMS key facts

TAM = \$42B

Billing = \$2.66B

Market Share = 6.3%

World Wide Competence Centers



*Technical support located near customers
in all sales regions*

Source: WSTS, ST

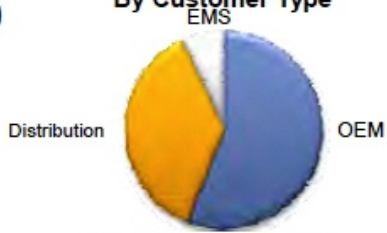
STMicroelectronics

IMS Results & TAM Evolution

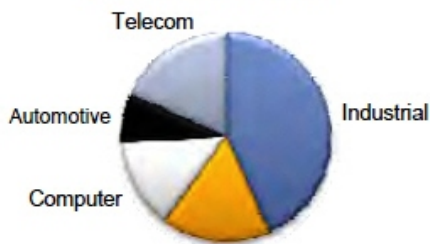


2009

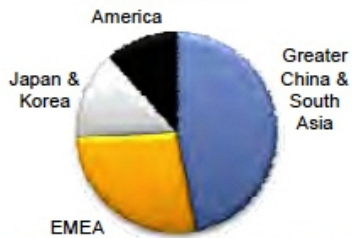
By Customer Type



By Market Segment

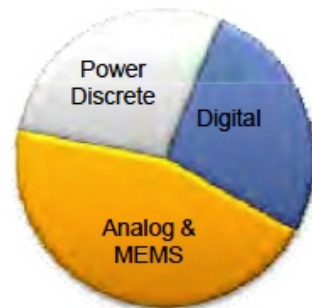


By Region



	2015 (US\$B)	CAGR (2010 ~2015)
Digital	19	5.8%
Analog & MEMS	32	6.4%
Power Discrete	20	5.7%
Total IMS	71	6.0%

2015 TAM Split

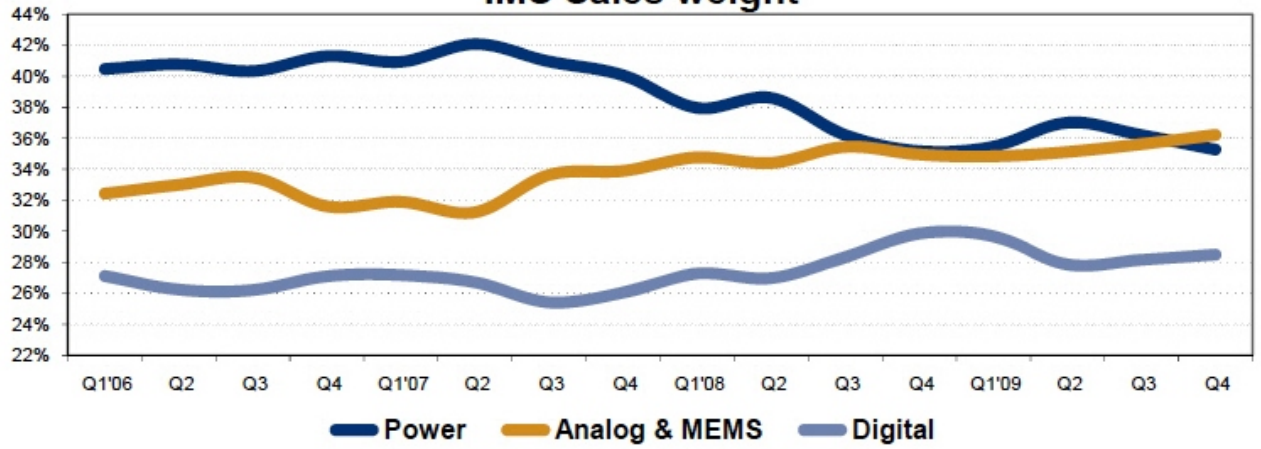


Source: WSTS, STMicroelectronics

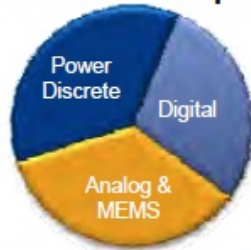
IMS Billing Split & Evolution



IMS Sales weight



2009 Sales Split



Analog Ranking 2009 Analog ICs* # 2

*Ranking refers to total ST Analog ICs sales

Key product family	Key target applications
Power management ICs	Power supply, solar, lighting
Mixed signal ICs	Mobiles, peripherals, portable medical
Battery management ICs	Mobiles, PDAs, e-Books
LED driver ICs	Street lighting, building, panel arrays

Competitive Advantages:

- Ability to integrate analog and power in a single chip or in a single package in power conversion and power management applications
- System know-how enabling the design of dedicated ICs for complex applications and a variety of reference designs for medium and small customers
- Ability to deliver system solutions including sensors, analog ICs, microcontrollers and power discrete
- The world's largest and most cost effective 6" front-end fab in Singapore

Source: iSuppli, ST

MEMS* Ranking 2009
All Segments # 1
(except Automotive)

*MEMS accelerometers & gyroscopes

Key product family	Key target applications
2 or 3-axis Accelerometers	PDAs, mobiles, toys, notebooks, multimedia devices
Gyroscopes	Games, camcorders, camera stabilization, GPS
Microphones	Games, mobile phones, laptops

Competitive Advantages:

- Integration in a single package of **MEMS**, data converters and **RF** transceivers for smart sensor networks
- Proprietary innovative silicon and packaging technologies for miniaturization and ultra-low-power fitting medical and portable applications
- First in the world to adopt an advanced 8" inch wafer fab (Agrate)

Source: iSuppli, ST

Power Discrete Ranking 2009

Power MOSFET (High Voltage)	# 1
Protection & IPAD	# 1
Thyristors	# 1
Rectifiers & power diodes	# 3

Key product family	Key target applications
HV Power MOSFETs	Power supply, lighting, solar
Rectifiers	Power management
ACS switches	Home appliances
Protections & IPAD	Mobiles, USB/HDMI interfaces, wired data transfer

Competitive Advantages :

- The widest range of power technologies and packages from low to very high voltage (MOSFET, IGBT, Bipolar, IPAD, Rectifiers) offering the highest efficiency in the most demanding applications
- Expertise in composite materials (SiC, GaN) for high frequency and very high temperature applications (electric cars, photovoltaic converters, wind generators)
- Extremely competitive manufacturing machine (Singapore, Longgang, Shenzhen)

Source: iSuppli, ST

Digital Ranking 2009

EEPROM, EPROM # 1

Smart Card # 3

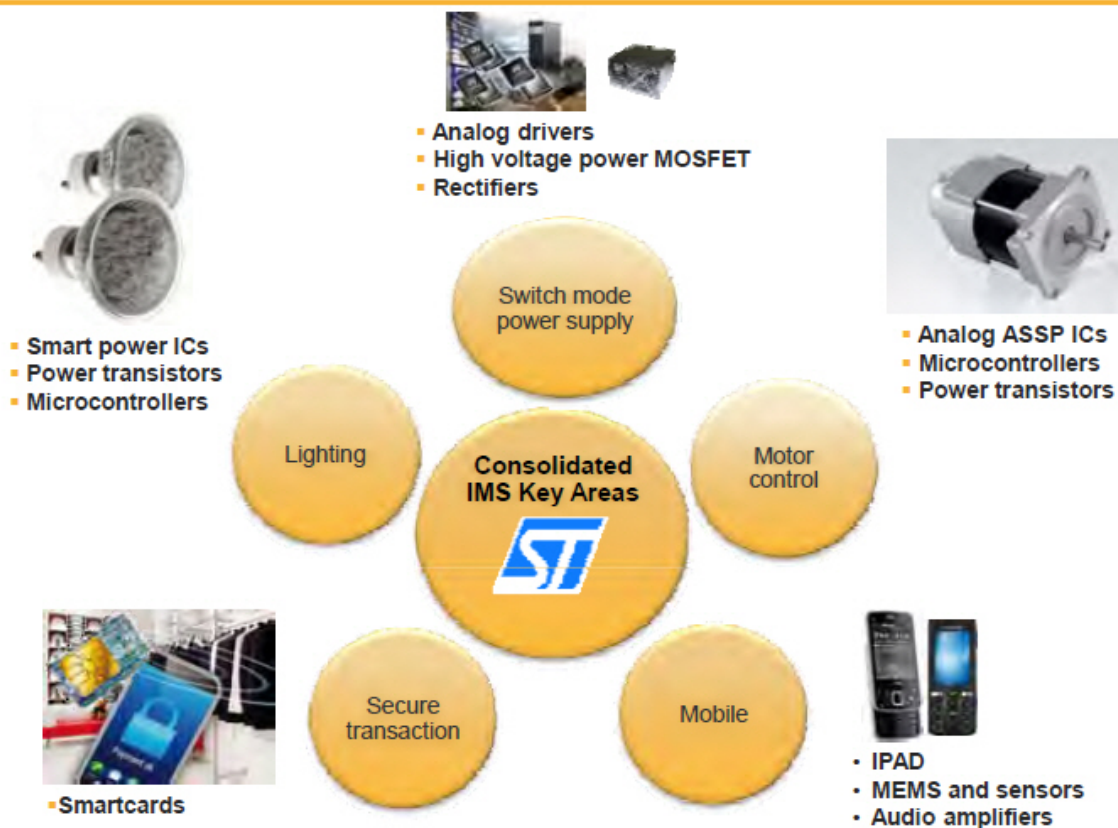
Key product family	Key target applications
RFID & RF EEPROMs	Access control, tracking systems
Microcontrollers	Low-power medical and portable equipment
32-bit smartcard ICs	Mobile phones, data security

Competitive Advantages:

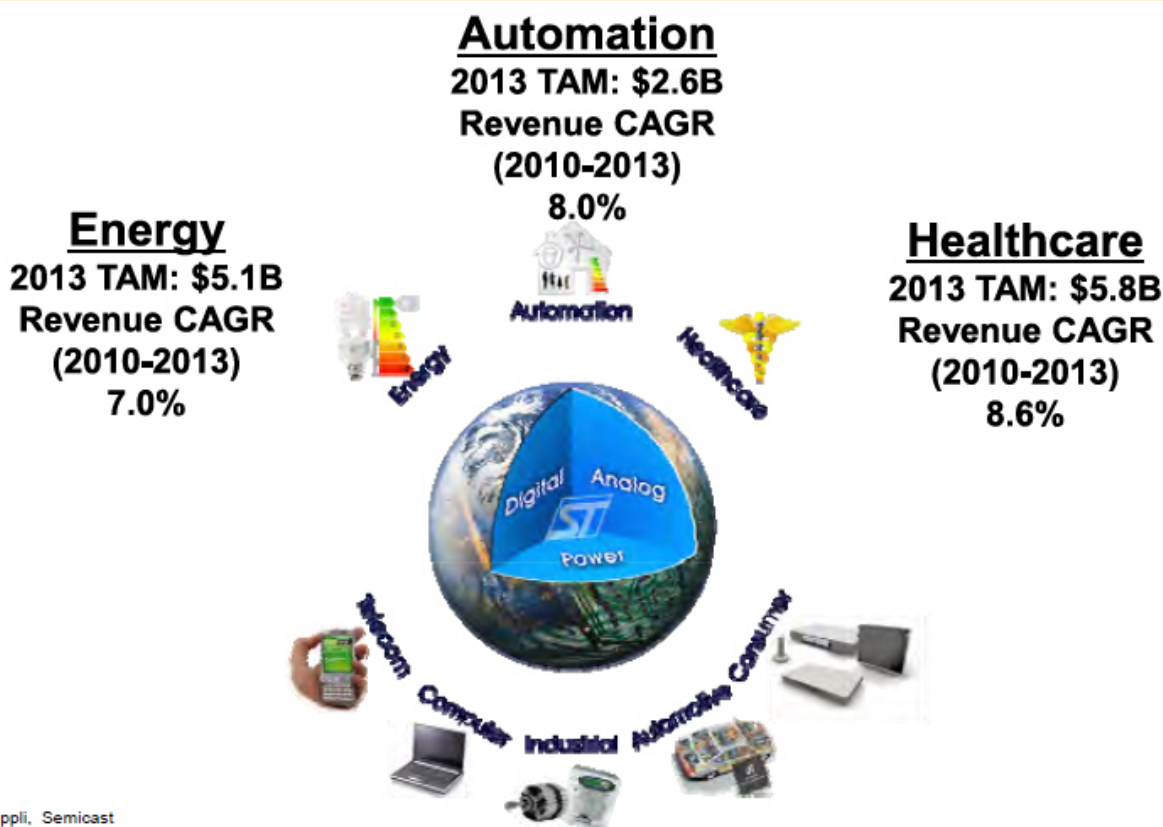
- Common technology and high-performance core (ARM® Cortex™) platforms for smartcards and microcontrollers
- Ultra-low-power technology suitable for battery operated and medical applications
- Complete hardware and software solutions for secure applications (STB, banking, access control, NFC)
- Special set of peripherals for connectivity (RF, ethernet), human machine interface (touch sensing) and real time control (motor control timers)

Source: iSuppli, ST

IMS: Key Strengths



Expanding into New Focus Areas



Innovation is Still IMS Key Driver





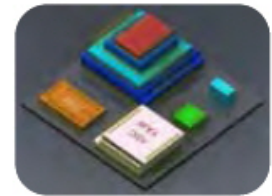
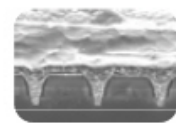
System Innovation

STMicroelectronics

Our System Approach



- **Complete reference designs (Hardware & Software) for medium and small accounts**
- **More than 550 reference designs available to support our worldwide design-in activity**
- **Innovative new product definition thanks to feedback from customer system know-how**



- **Hybrid Electric Traction**
 - Motor drivers
 - Power conversion
 - Battery-cell management
 - Fast battery charger
- **Photovoltaic panel converters**
- **SmartGrid**
 - Smart energy metering
 - Smart appliance plug
 - Power-line modem



- Home automation through advanced wired (200 Mbit/s) and wireless connectivity
- Application Specific Integrated Modules (ASIMs) for robotics and industrial automation
- Sensor networks for building automation
- Low-power energy harvesting and storage



ASIM

Embedded motor drive module, remotely controlled by ethernet

Flexible rechargeable battery



■ Remote patient monitoring

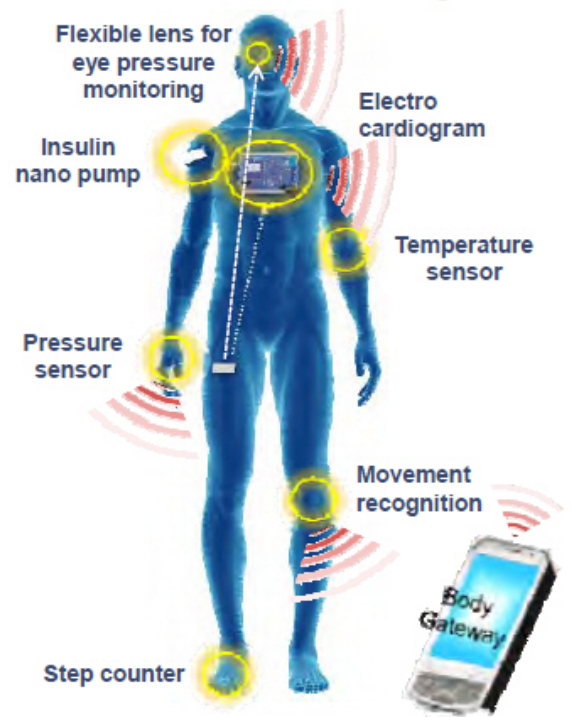
- Blood pressure
- Heart beat
- Electrocardiograph
- Eye pressure sensor

■ Movement reconstruction

- Rehabilitation
- Fitness

■ Patient treatment (i.e. insulin pump)

Portable distributed diagnostics and remote monitoring

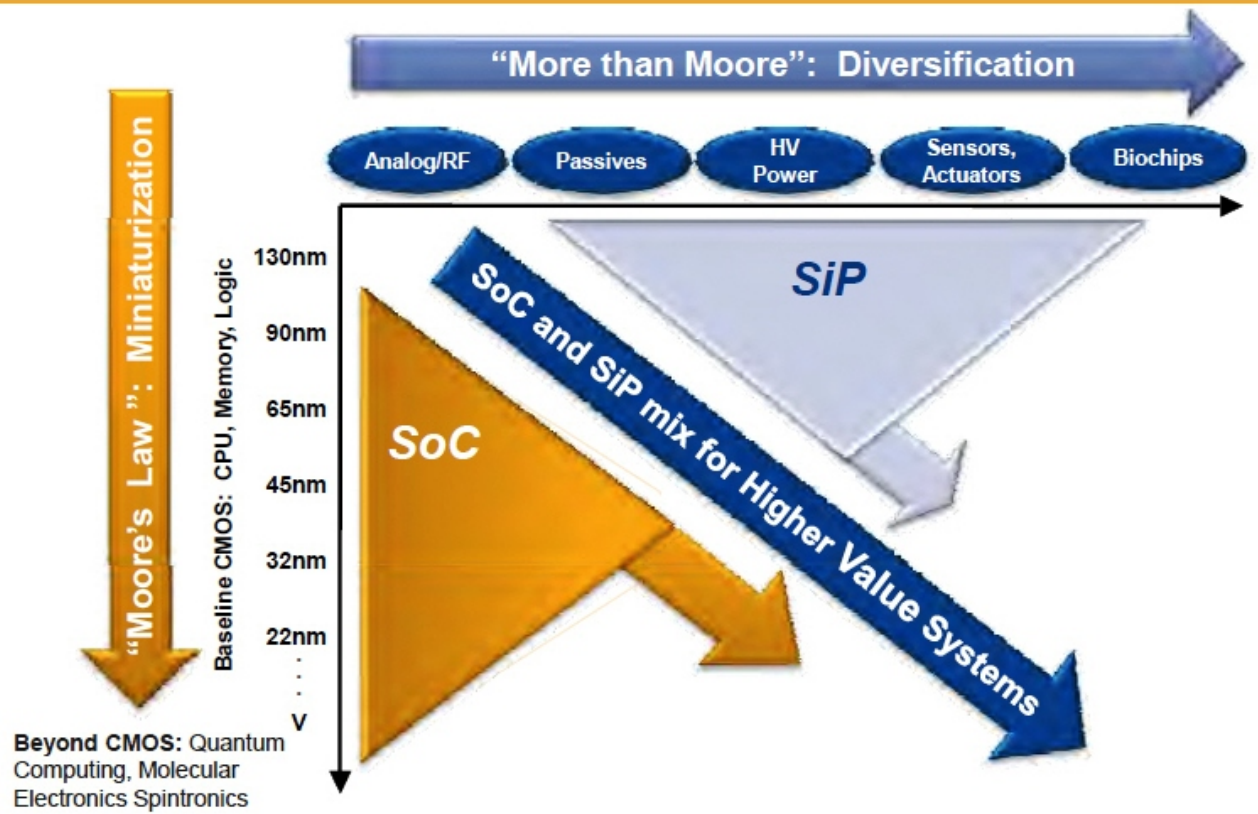




Technology Innovation

STMicroelectronics

Emerging Applications Require Smart Integration: Moore's Law and More than Moore



ST Enabling Technologies: “More than Moore”

- MEMS & smart sensors



- Flexible ICs



- Harvesting & thin film batteries



- New materials: SiC & GaN



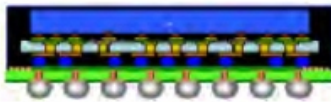
- Advanced BCD, BCD-SOI



- Ultra-low-power technologies



- 3D heterogeneous integration / TSV



- Advanced packaging & system-in-package



- Microfluidics





Product Innovation

STMicroelectronics

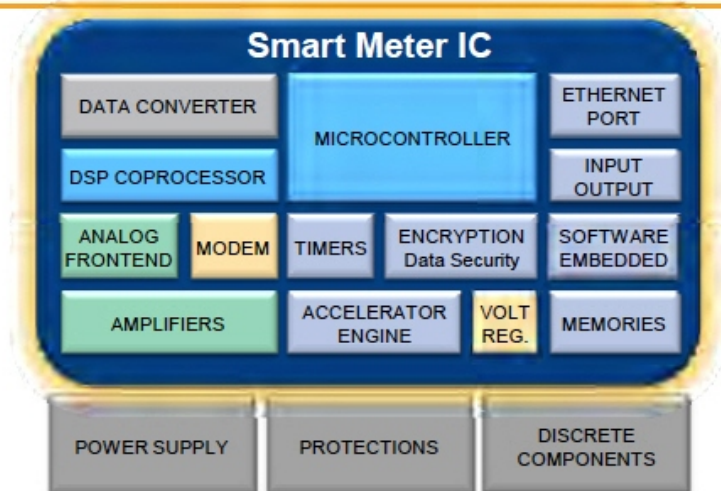
Smart Meters



Target Applications:

- Electricity meters
- Water meters
- Gas meters

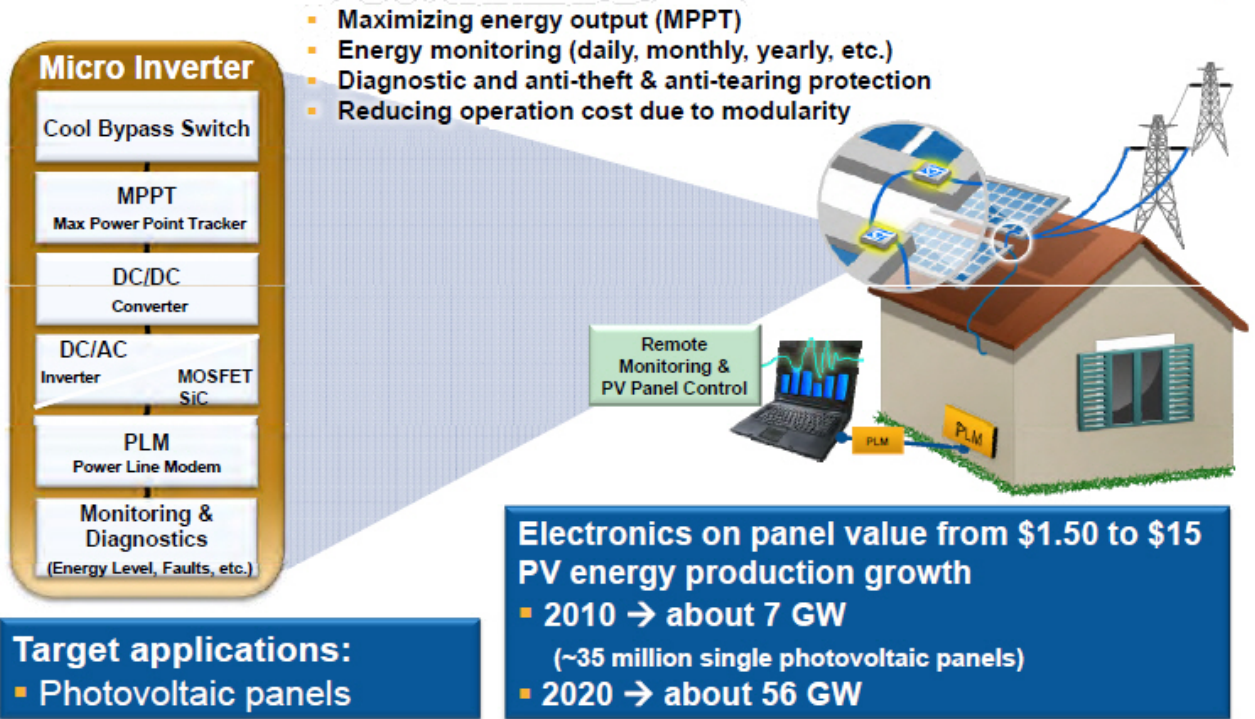
Source: ABI Research, ST



More than 40M smart meters with ST's power-line modem connectivity already installed in the field

Smart electricity meters TAM 2009: 76M units
CAGR 2010-2013: ~18%

Micro Inverter Modules



- Maximizing energy output (MPPT)
- Energy monitoring (daily, monthly, yearly, etc.)
- Diagnostic and anti-theft & anti-tearing protection
- Reducing operation cost due to modularity

Source: European Photovoltaic Industry Association, ST

LED Lighting Driver ICs



Luminous efficacy



... more light with less energy

Target applications:

- Display & signs
- General illumination
- Backlight
- Signal lighting

Source: iSuppli

Driving LEDs using AC-DC solutions



Driving LEDs using DC-DC solutions



LED Array Drivers



LED TAM 2009: 63B units
CAGR 2010-2013: 30%

Motherboard Power Management ICs



- Enabling next generation motherboard power management solutions

Multi Segment ICs	Motherboard Dedicated ICs
Low power consumption switching regulators	CPU power management controllers
Single and multi phase DC-DC controllers	Multi output controllers
High density DC-DC controllers	Multi output regulators
High efficiency switching regulators	LED backlight drivers

Target applications:

- Desktop
- Laptop
- Server



Server

Laptop

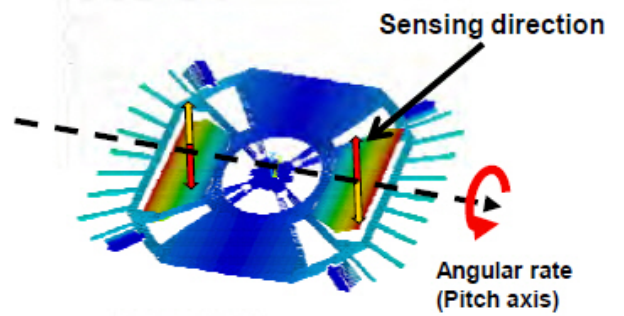
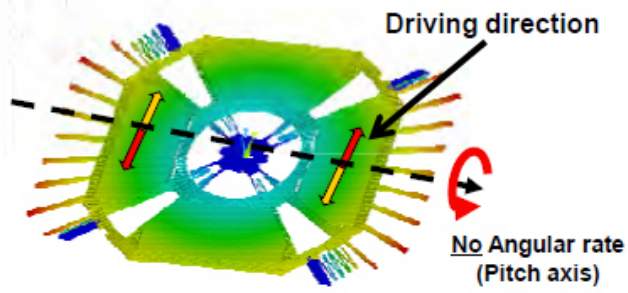
Desktop

TAM 2009: \$2.6B
CAGR 2010-2013: ~12%

Source: iSuppli

STMicroelectronics

MEMS Gyroscopes



- Target applications:**
- Smart phones
 - Robotics
 - Navigation
 - Cameras
 - Gaming



TAM 2009: ~\$526M
CAGR 2010-2013: ~13%

Source: iSuppli

Microcontroller "STM32W"



- IEEE 802.15.4 open flexible reconfigurable platform



Source: WSTS
*Includes Automotive

Flexible Eye Lens for Glaucoma



Flexible Lens IC for wireless sensor for Continuous eye pressure monitor

- Contact lens (30m thickness)
- Pressure sensor
- Continuous remote monitoring
- Very low-power RF data transfer

Target applications:

- Remote patient monitoring

Population and aging increase

Over 7.5 million suffer from age-related macular degeneration

Therapeutic sales for ophthalmology disorders exceeded \$12B in 2009

Source: World Health Organization

STMicroelectronics

3D Ultrasound Scanner ICs



- Miniaturization and low-power ICs allow electronics migration from centralized computer to ultrasound beamer

Old System



New System



3D Image



2D Image

Solution Integrating:

- Power management IC array
- Microcontroller
- Analog front-end and data converter

Target application:

- Echographs with color and 3D Integration

TAM 2010: 83M units
CAGR 2010-2013: 11%

Source: Semicast

- Focus on **high-margin segments** (energy, automation, healthcare)
- **System approach** to deliver complete solutions to the market
- Boost high-performance, high-margin **analog products** leveraging on our strong position in **MEMS** and **power management**
- Pervade the market with **microcontrollers** and **secure access products** based on ARM core leveraging on:
 - Ultra-low-power technologies for portable and healthcare applications
 - Complete set of analog peripherals including wireless connectivity
- Maintain our leadership in **power discrete** supporting:
 - High-volume and **cash-generating products**
 - New high-margin products utilizing new materials (**SiC** and **GaN**)
- Improve profitability towards high teens operating margin by the end of 2010 and above 20% in the mid-term

LET'S
CREATE
IT

TOWARDS TRANSFORMATION

Gilles Delfassy, President & CEO





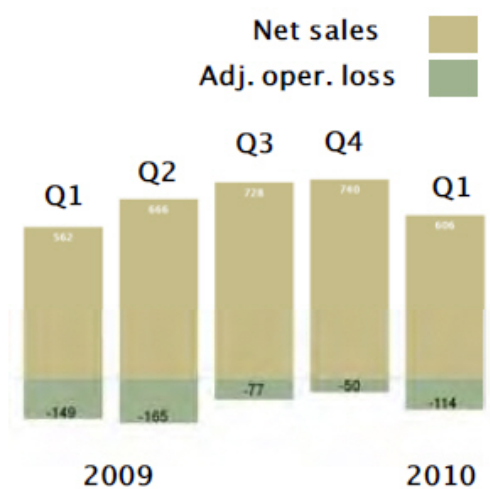
2009: FORMATION

2010: TRANSITION & TRANSFORMATION

FIRST QUARTER SUMMARY

- Net sales \$606 million
- Adjusted operating loss \$114 million
- Net cash \$120 million

- Restructuring plans on track
 - ~50% savings of \$230 million plan
 - \$115 million plan savings from H2 2010
 - R&D efficiency program
 - Integration of IT systems



2009 (Pro-forma):
Net sales: \$2.7B
Adj. operating loss: \$440M

2010 PRIORITIES



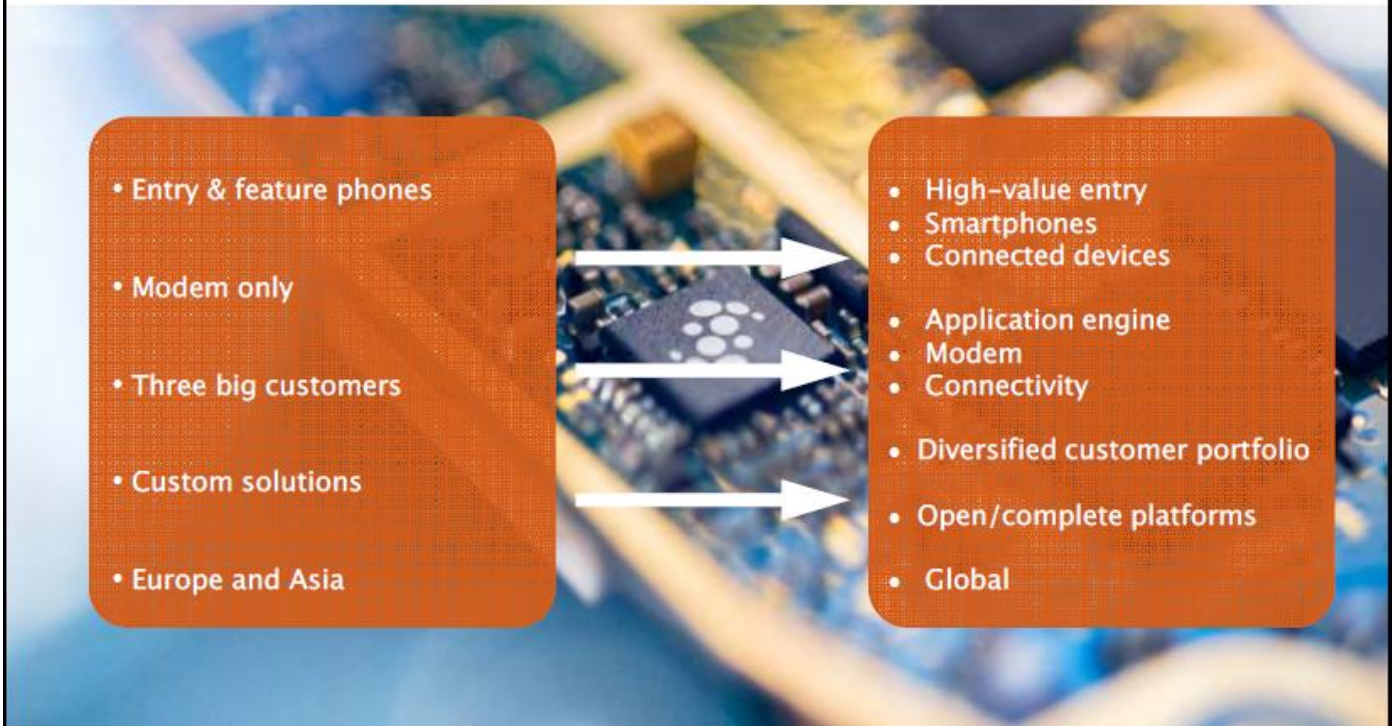
Competitive cost structure

New portfolio

Pursue profitable growth

Focus on priorities and fast transition

TRANSFORMING THE COMPANY

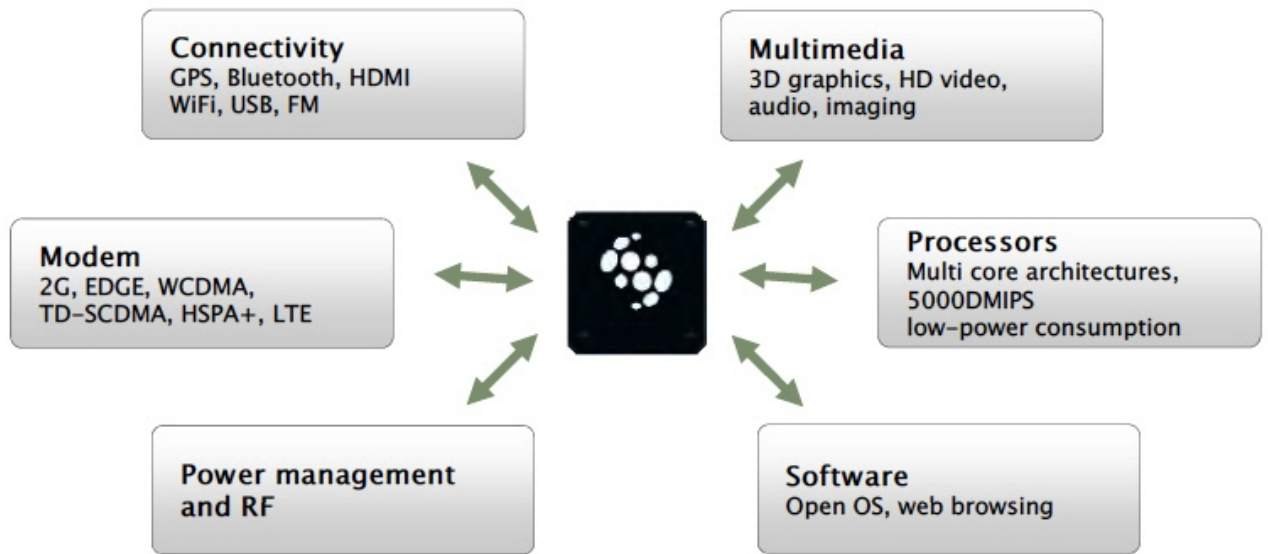


MOBILE PLATFORMS AT THE HEART OF CONVERGENCE



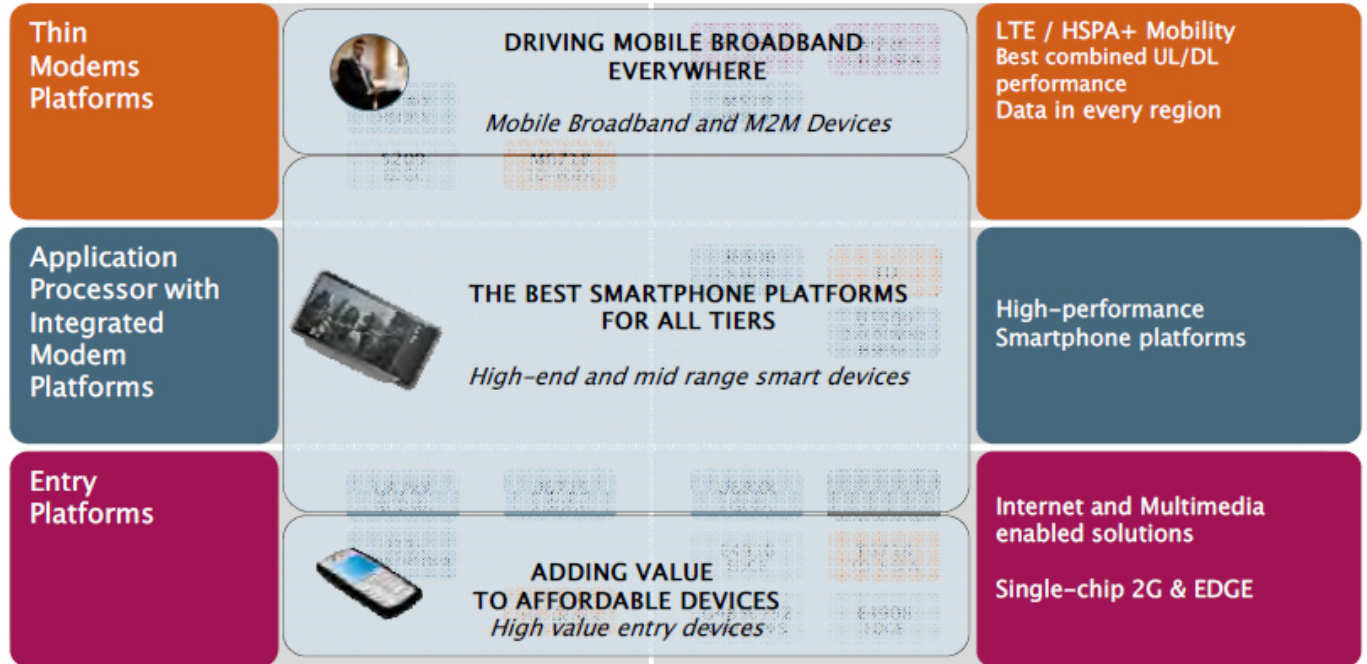
Manage the complexity is crucial

DELIVERING COMPLETE PLATFORMS IS KEY





Requirements on wireless semiconductor players are evolving accordingly

ENABLING A CONNECTED WORLD



PLATFORM PORTFOLIO

 LTE
  TD-SCDMA
 UMTS/HSPA
  2G/EDGE

	In Production	Announced	
Thin Modems Platforms	M340 HSDPA 5209 EDGE M6718 TD-HSPA	M700 LTE M570 HSPA+ M720 LTE/HSPA+	LTE / HSPA+ Mobility Best combined UL/DL performance Data in every region
Application Processor with Integrated Modem Platforms		U8500 HSPA+ TD U5500 HSPA+	High-performance Smartphone platforms
Entry Platforms	U67XX WCDMA U33x HSPA/HSDPA 65XX EDGE U6715 HSDPA T72XX TD-HSDPA E4908 EDGE	U68XX HSDPA E4910 EDGE G4850/52 GSM/GPRS T6718 TD-HSPA	Internet and Multimedia enabled solutions Single-chip 2G & EDGE
Connectivity and Enhancements	CG2900 BGF CW1200 WLAN	AV8100 HD TVout AV5230 Audio PTE	Complete Platforms

ADDING VALUE TO AFFORDABLE DEVICES

High-value entry devices

More features at low cost

Enhanced connectivity and multimedia

Integration to single-chip

Best-in-class power consumption

Smart multimedia for all

Linux/Android™ support

WQVGA screens, touch-screen and H.264 video

HSDPA for fast content sharing



G485X

Single-chip ultra low cost
Dual SIM/Dual standby
USB charging

E49XX

Single-chip Quad-band
EDGE
Low power, MM touch-screen
QVGA & 3Mpixel camera

T6718

TD-HSPA
Quad-band EDGE
WQVGA & 5Mpixel camera

U6715

Affordable
Linux/Android
HSDPA
WQVGA & 5Mpixel camera

HIGH VALUE ENTRY GAINING MOMENTUM

U6715

- Ramping with four new customers in Asia
 - multiple models
- Interest from operators across the globe

E49xx

- Two top customers for EDGE & GPRS versions



U6715

Affordable
Linux/Android
HSDPA
WQVGA & 5Mpixel
camera

E49XX

Single-chip Quad-band
EDGE
Low power , MM touch-
screen
QVGA & 3Mpixel camera

CONNECTIVITY INTEGRATED INTO COMPLETE PLATFORM SOLUTIONS

- Selected by two additional U8500 customers
- Further momentum coming from Asia



CG2900

BT/FM/GPS
First 45nm Combo
Leading footprint size

CW1200

802.11a/b/g/n
< 50mm² BOM
Integrated FEM, SMPS

AV8100

HDMI/CVBS combo
Full HD 1080p
7.1 audio surround

AV5230

102 dB SNR
Integrated headset AMP
Playback Time Extender

THE BEST SMARTPHONE PLATFORMS FOR ALL TIERS

High and mid-end smart devices

U8500: Top performance at low power

- Dual-core processors >1GHz
- HD-multimedia 1080p
- Full web-browsing experience
- Mobile broadband with HSPA+
- Powerful 3D graphics – OpenGL ES 2.0
- Touch displays, dual screen
- Complete solutions with Open OS



U8500

Dual-core SMP Cortex A9
HSPA+
1080p HD & advanced 3D
Dual-screen support

U5500

Dual-core SMP Cortex A9
HSPA+
720p HD
Advanced 3D

U6715

Affordable Linux/Android
HSDPA
WQVGA & 5Mpixel camera

Thin modems

TD-HSPA
HSPA+
LTE

U8500

THE MOST ADVANCED SMARTPHONE PLATFORM

U8500

- Selected by two additional customers
 - Four customers overall since launch
 - Supporting various OS
 - Symbian and Linux, incl .Android



U8500

Dual-core SMP Cortex A9
HSPA+
1080p HD & advanced 3D
Dual-screen support

DRIVING MOBILE BROADBAND EVERYWHERE

Connected devices and embedded mobility

Advanced modems

HSPA+ mobile broadband for all devices

LTE, the next evolution for high-speed data

TD-HSPA broadband modems for China

Optimized modems for numerous applications

Modem technology from GSM to LTE

Supporting devices from smartphones and netbooks to consumer electronics and M2M



M720

LTE /HSPA+
Proven hand over
100 Mbps

M570

HSPA+ 21 Mbps
Simultaneous full speed
UL/DL
Best in class thermal heat

M6718

Dual mode
TD-HSPA & quad band
EDGE

DRIVING MOBILE BROADBAND EVERYWHERE

M570 – M720

Multiple design wins for our advanced modem solutions



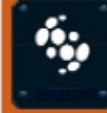
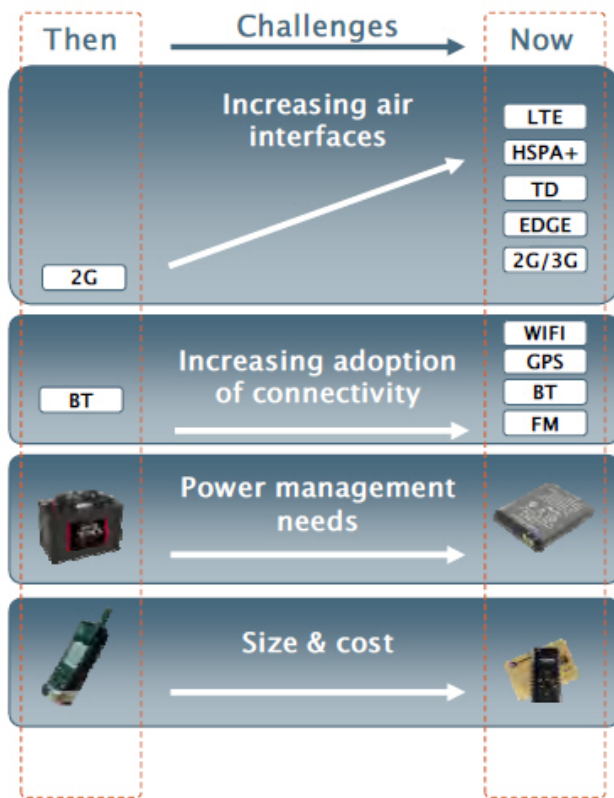
M570

HSPA+ 21 Mbps
Simultaneous full speed UL/DL
Best in class thermal heat

M720

LTE /HSPA+
Proven hand over
100 Mbps

ADDRESSING MODEM EVOLUTION



New ST-Ericsson multi-mode modem architecture

- Software-defined radio access
- LTE 100Mbps, HSPA+ 42Mbps
- Target >2X power improvement
- Scalable for cost
- Building on existing LTE solution
- Single SW and HW platform
- Drastic reduction of testing

2010 PRIORITIES



- Competitive cost structure
- New portfolio
- Prepare the company for future, profitable growth

Focus on priorities and fast transition

LET'S
CREATE
IT





Region Americas: The Land of Opportunity

Robert Krysiak

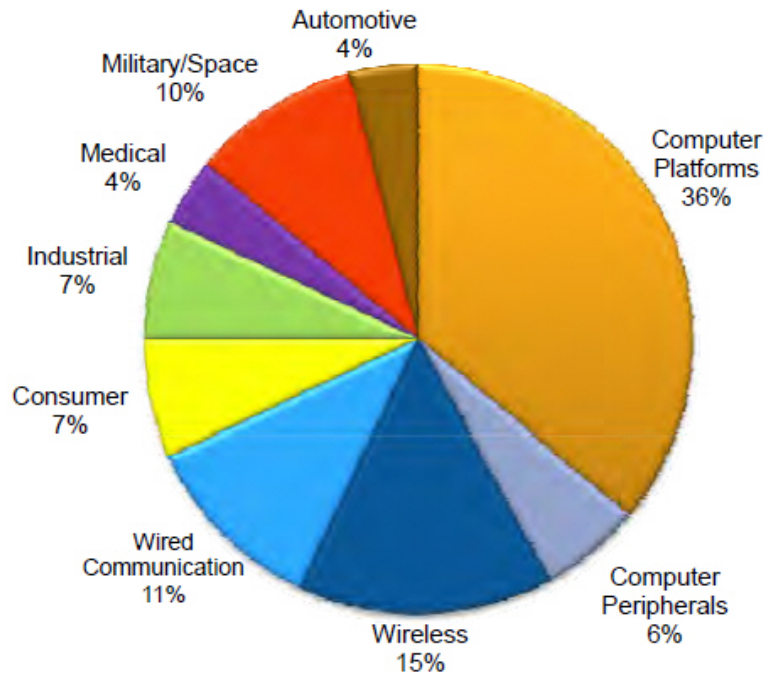
General Manager, Americas Region

STMicroelectronics

Americas 2009 TAM: \$35B



Top 10 Americas OEM 2009 Spending



Top 10 OEMs: ~62% of TAM

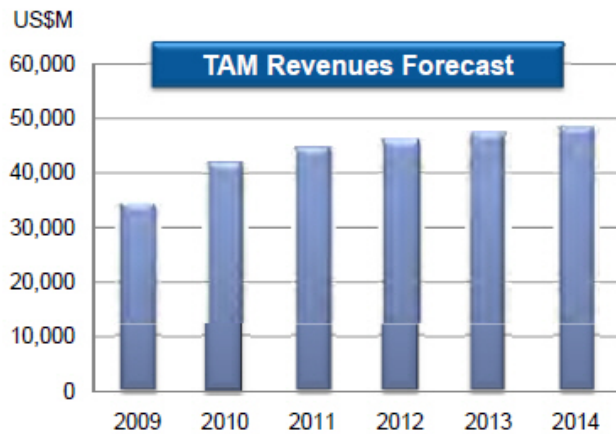


Source: iSuppli

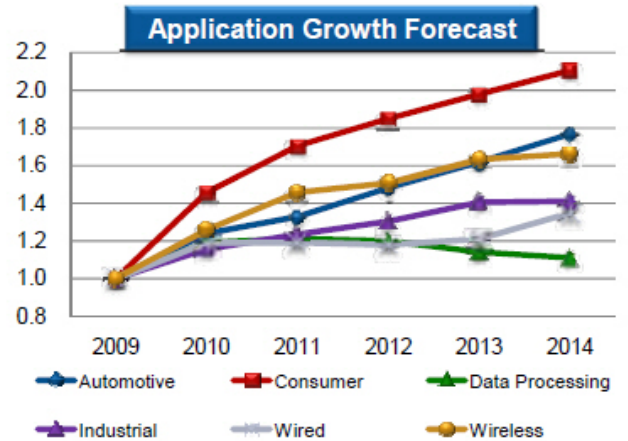
Americas Forecast



- Americas TAM
 - 2009-2014 CAGR ~ 7%



- Consumer CAGR ~ 16% driven by:
 - Game consoles
 - LCD TV
- Automotive CAGR ~ 12%

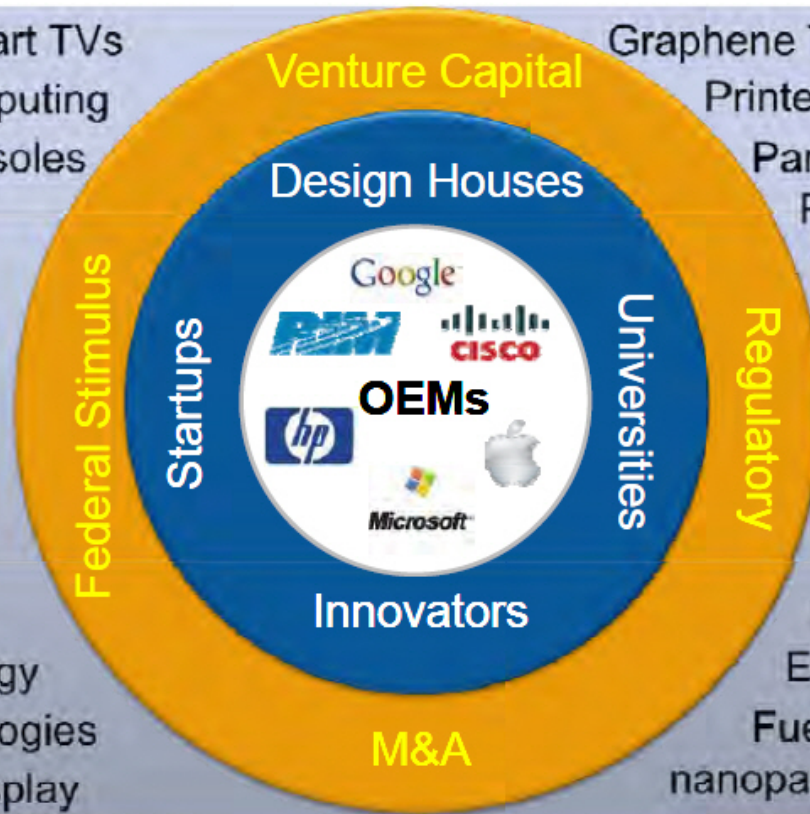


Source: iSuppli

Americas Ecosystem Strength



IPTV – Smart TVs
Cloud Computing
Game Consoles
eBooks
HEVs
Smart Grid
Tablets
Medical Devices
Sensor Networks
Clean Energy
PV Technologies
Flexible Display



Graphene Transistors
Printed Electronics
Parallel Processing
Through Si Vias (TSV)
MEMS
Gyros
Memristors
Lab on Chip
Wireless ECG
Fuel Cells with nanoparticle catalyst



US Trade Deficit

- Deficit growth is validating the evidence of recovery from the worst global recession since World War II
- US exports grew faster than imports in 2010 despite a stronger \$ vs. € driven by industrial supply, farm products, semiconductors and strong expansion in China



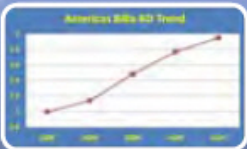
US Imports

- Impacted by lower crude oil prices



US Unemployment

- Rose to 9.9% in April from 9.7% in March

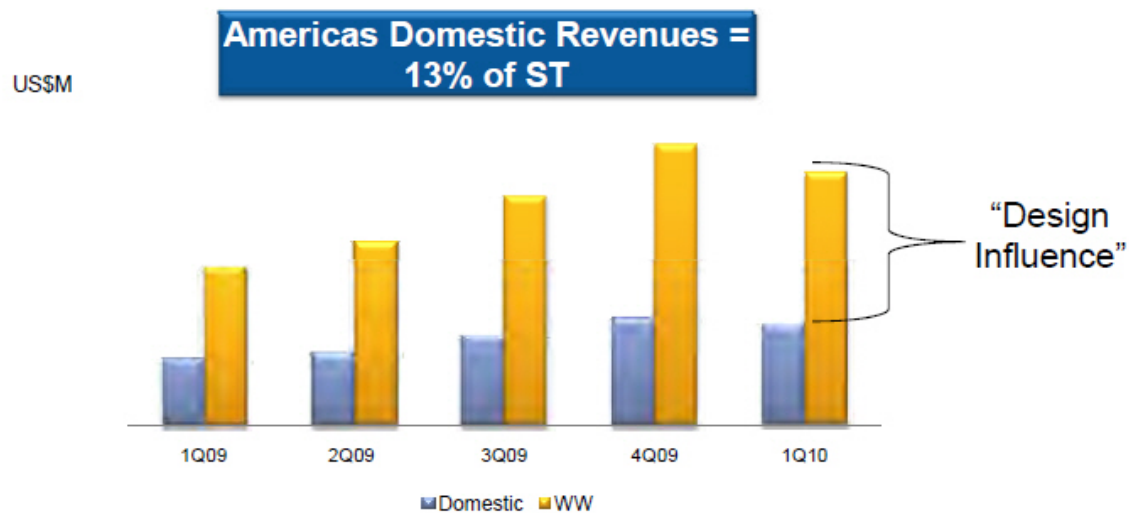


**ST Americas end-of-quarter BiBA:
doubled from Q1 2009 to Q1 2010**

ST Americas: Revenues Trend



- ST Americas is growing the Domestic market while leveraging the “Design Influence” to expand offshore growth
- Bridging Americas with China and A/P on common strategic plans
- 1Q10 affected by seasonality





Americas

Computer Peripherals & Communications
Infrastructure

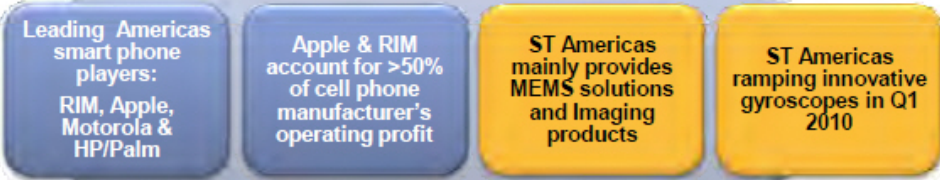
STMicroelectronics

Communications Infrastructure



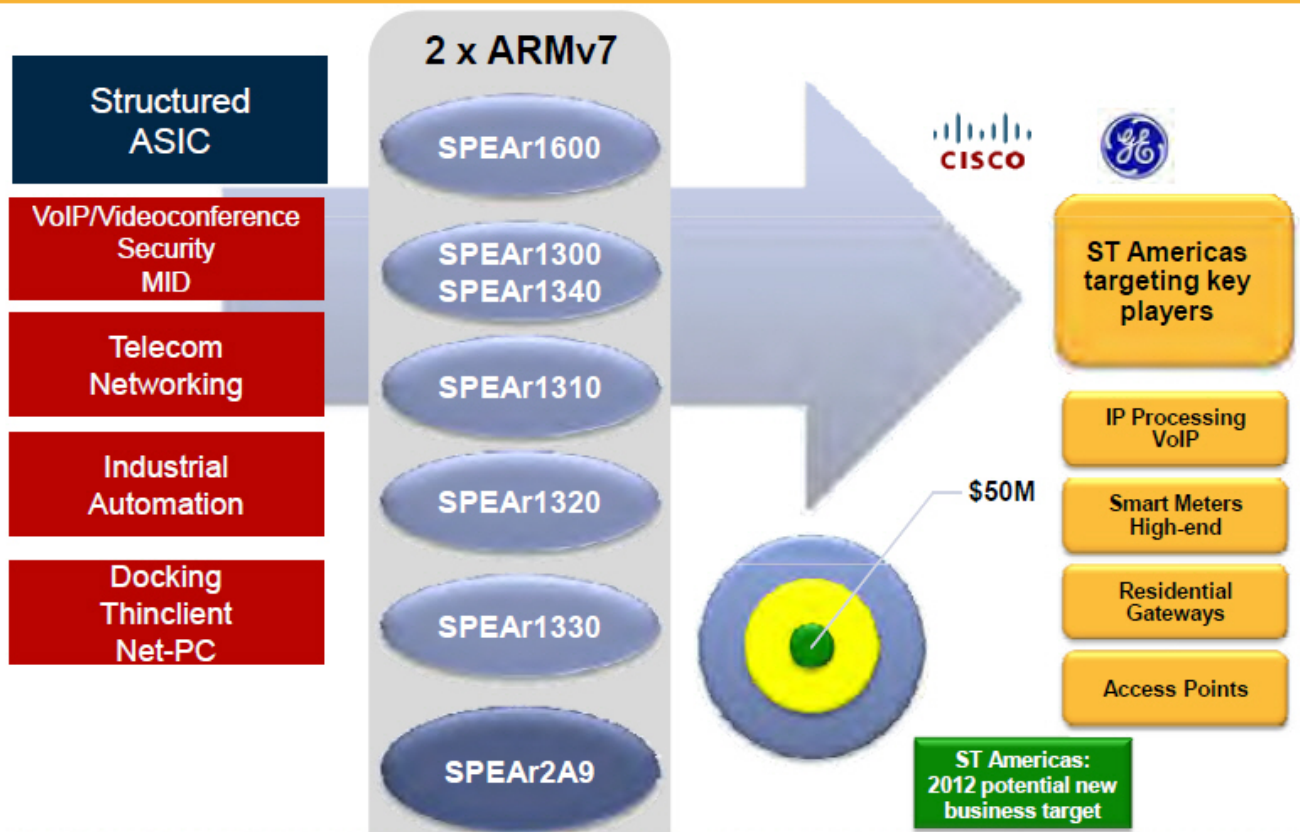
ST Americas:
2012 potential new
business target

Smart Phones



Source: Cisco

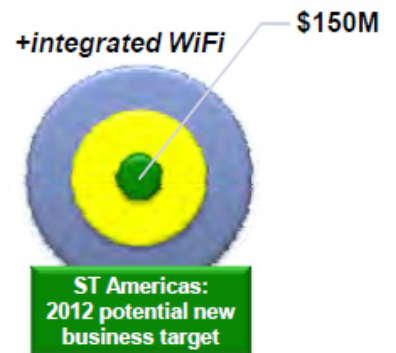
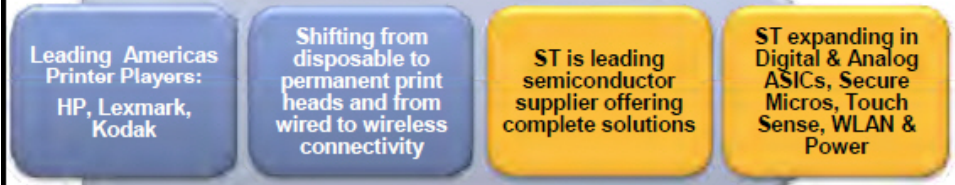
SPEAr – New Flexible ARM Cortex Platform



Computer Peripherals



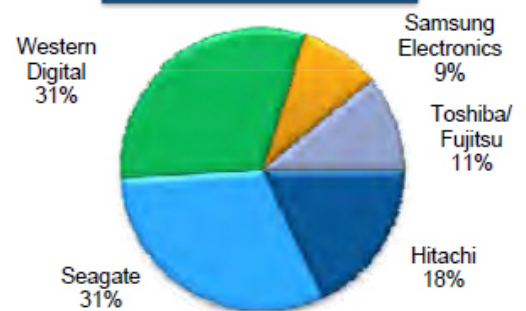
Printers



Data Storage



Top 5 HDD OEMs – Q110*



Source: iSuppli



Americas:

Consumer

STMicroelectronics

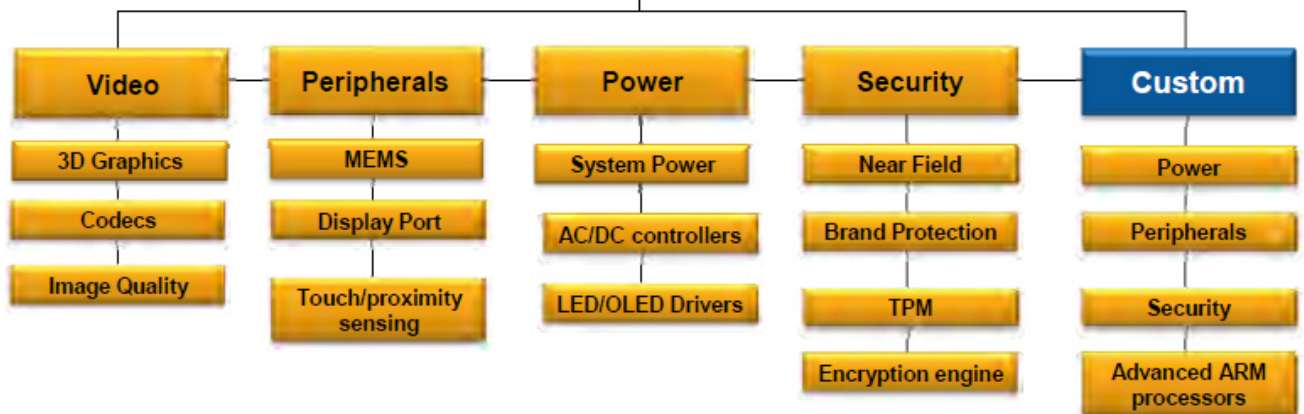
Consumer Convergence



- **Mobile Internet Devices (MID); Smartbooks, Tablets, Netbooks...transforming the way consumers work/play**
 - In 5 years MIDs will dominate the semiconductor TAM in the new PC/Consumer market
- **Apple, PC OEMs, Microsoft, Google, and their ODMs will be the dominate players in the MID market**



ST Selected Products



Set Top Box



- **STi7108: Best-in-Class H.264 SoC for STB**
 - 2000 DMIPS host performance
 - Integrated 3D Graphics GPU
 - Enhanced Video
 - 1080p60
 - Full motion HD 3DTV



1st ST product with ARM Cortex-A9 due in H2 2010



STMicroelectronics

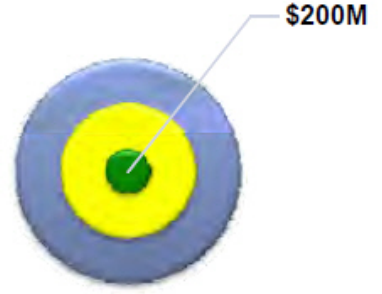
MEMS

Pervasion of MEMS in consumer devices continues to significantly increase

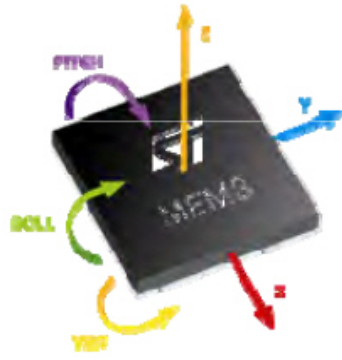
Motion sensor market CAGR (2009-13) of 15% and 19% for accelerometers & gyros, respectively

Integration of MEMS, data converters & RF transceivers is competitive advantage

ST Americas shipping large volumes of accelerometers & ramping gyroscopes in Q1 2010



**ST Americas:
2012 potential new
business target**



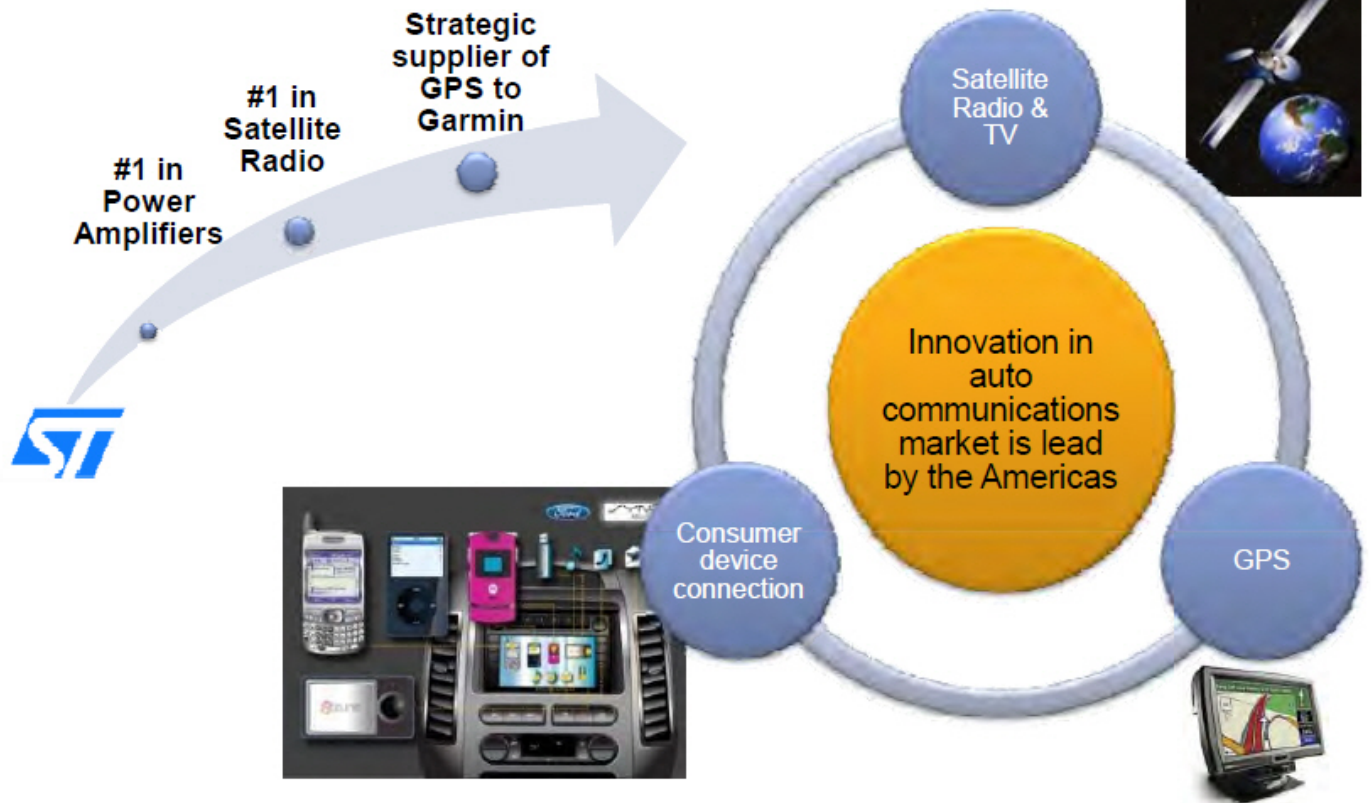


Americas:

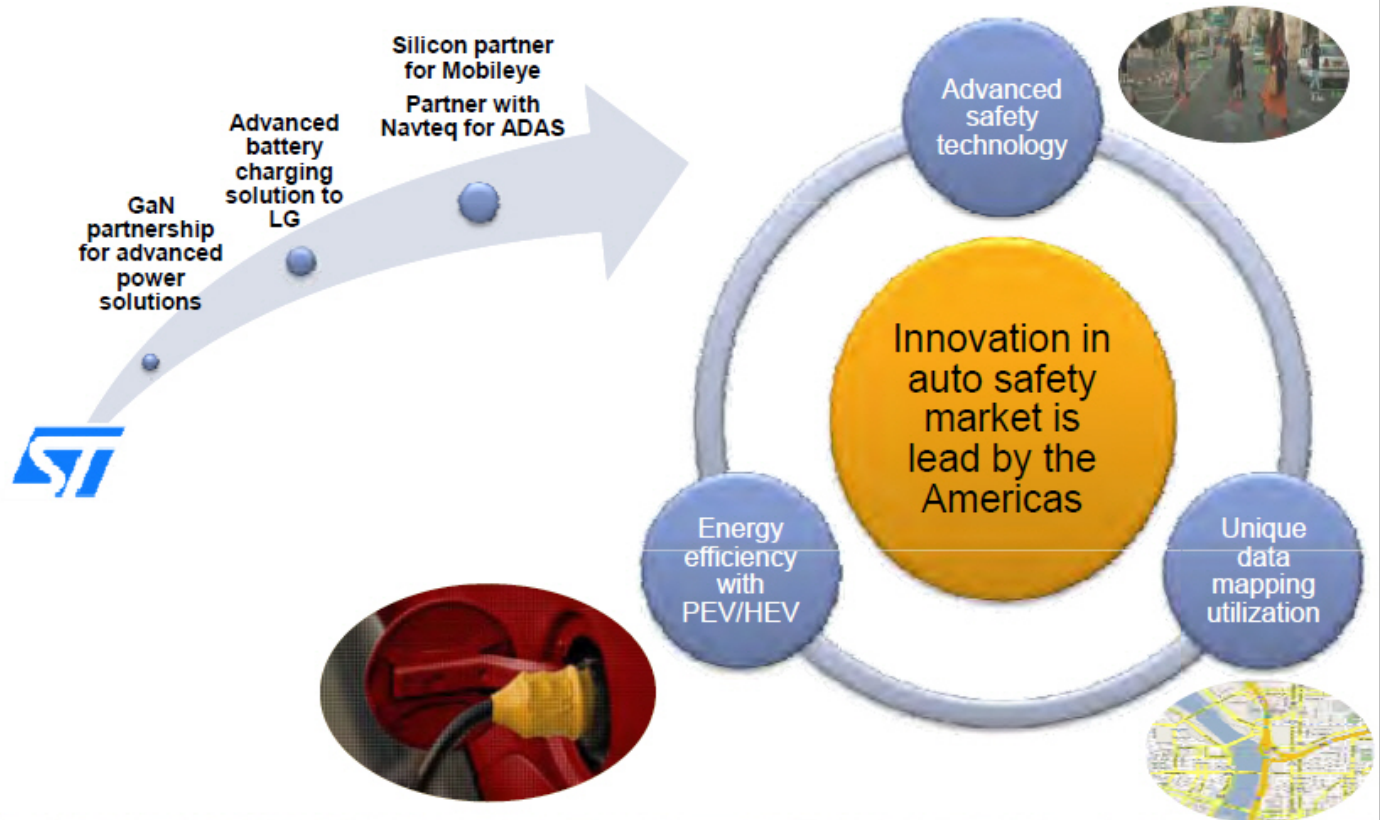
Automotive

STMicroelectronics

Auto Communications



STMicroelectronics



Automotive Market



Automotive

US autos are leaders in silicon content and vehicle production

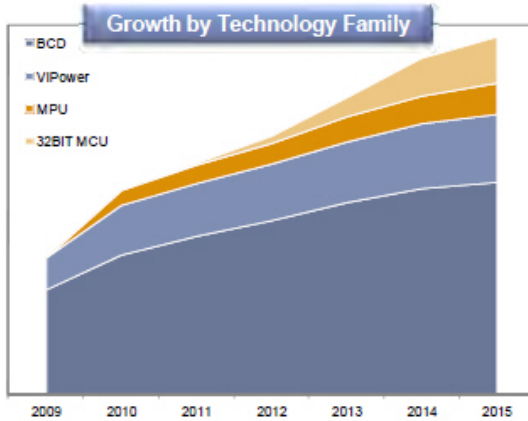
Advanced concepts utilizing GPS, car-to-car and grid communications

Build on our strong positions via partnerships and offer a full range of system components.

ST Americas gaining market share in MCUs and achieved major powertrain MCU win at a US OEM



ST Americas:
2012 potential new
business target





Americas:

Industrial & Medical

STMicroelectronics

LED Lighting



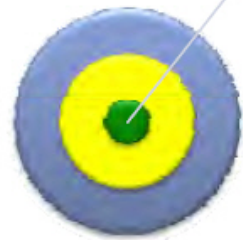
LED Lighting

Great potential in general illumination with 2009 to 2012 CAGR>90%

9.5W LED replaces 80W incandescent: market price <\$35, payback time <1yr & 15 year bulb life

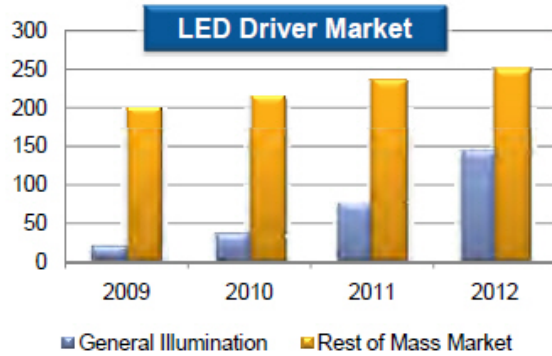
ST is #1 supplier at top 5 lighting worldwide manufactures

Major design wins in US region generating potential billing growth with CAGR>300%



\$45M

ST Americas:
2012 potential new business target



Source: iSuppli



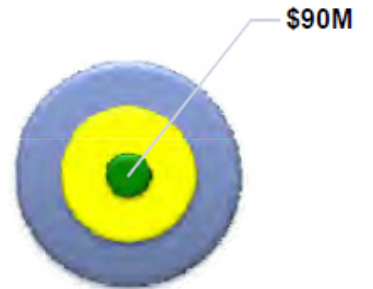
STMicroelectronics

SmartGrid:

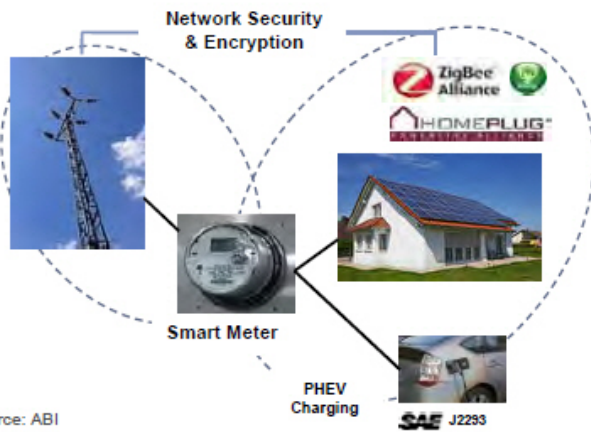
Stimulus and Innovation Driving Growth



SmartGrid



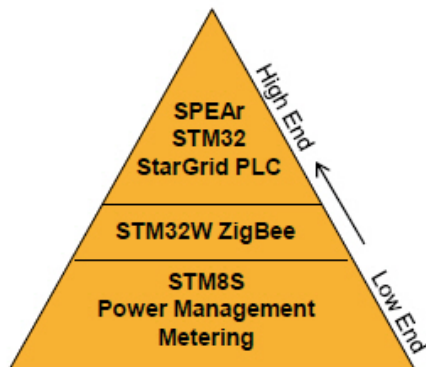
ST Americas:
2012 potential new business target



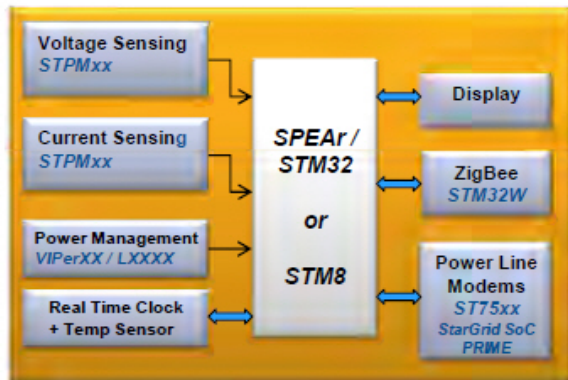
Source: ABI

STMicroelectronics

Smart Meter Solutions & Deployment



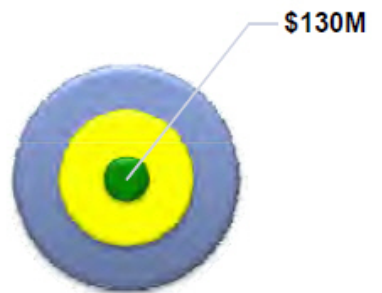
Country (Utility)	Customers (deployment)
Italy (Enel) – ST7538/40 PLM-based meters	27M (complete)
US (SCE, Duke, SDG&E, AEP, PG&E, FPL, etc)	40M (2015), 70M total
China	200M (2015)
Mexico (IUSA) – STM32/STPM01-based	3.5M (2009), 4M (2010), 20M total
Spain (Endesa, Iberdrola) – ST7570/90-based	22M (2015)
Brazil (ELO) – Echelon PLM-based	60M (2021)
France (ERDF) – ST7570-based	35M (2015)



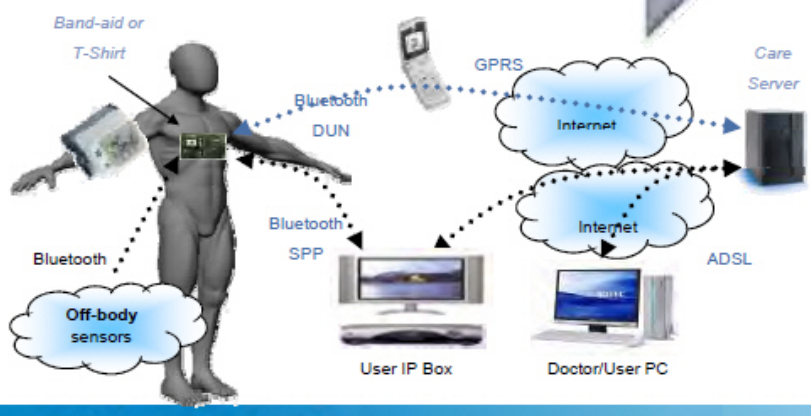
Model	BOM (\$)	Features
Low End	5	Manual read
Mid Range	10	AMR (1-way)
High End	>15	AMI / IP Interactive Energy Management

Healthcare: e-Health/Remote Monitoring

Healthcare

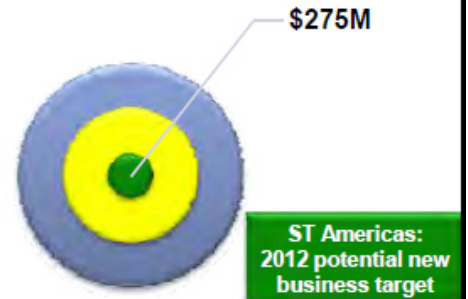
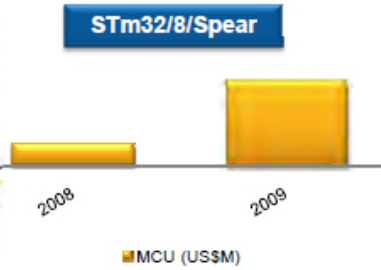
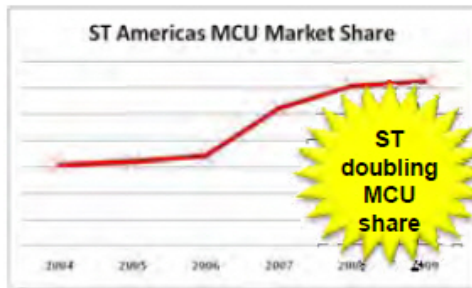
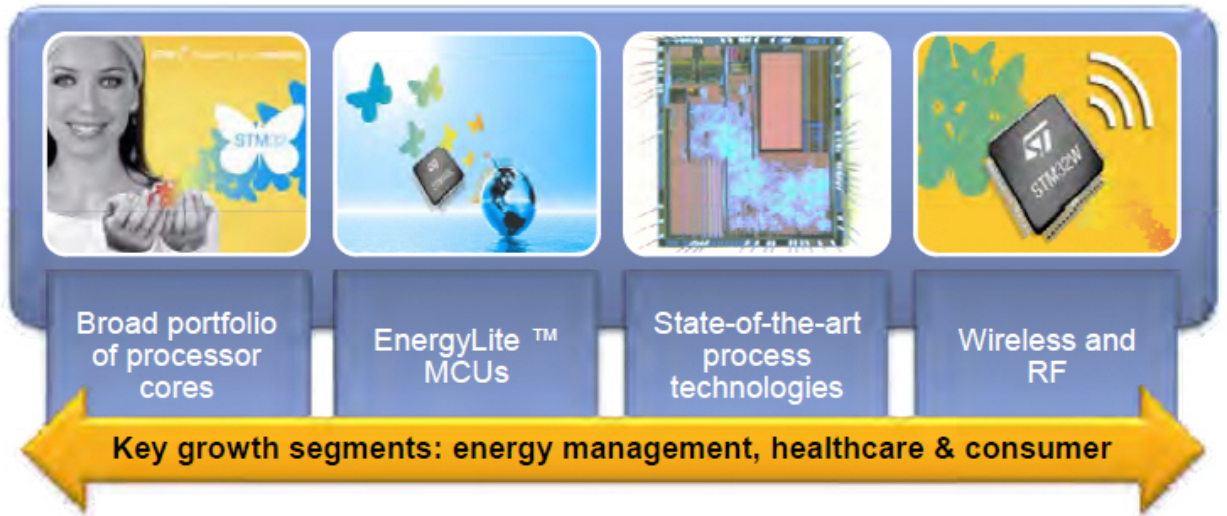


ST Americas:
2012 potential new
business target



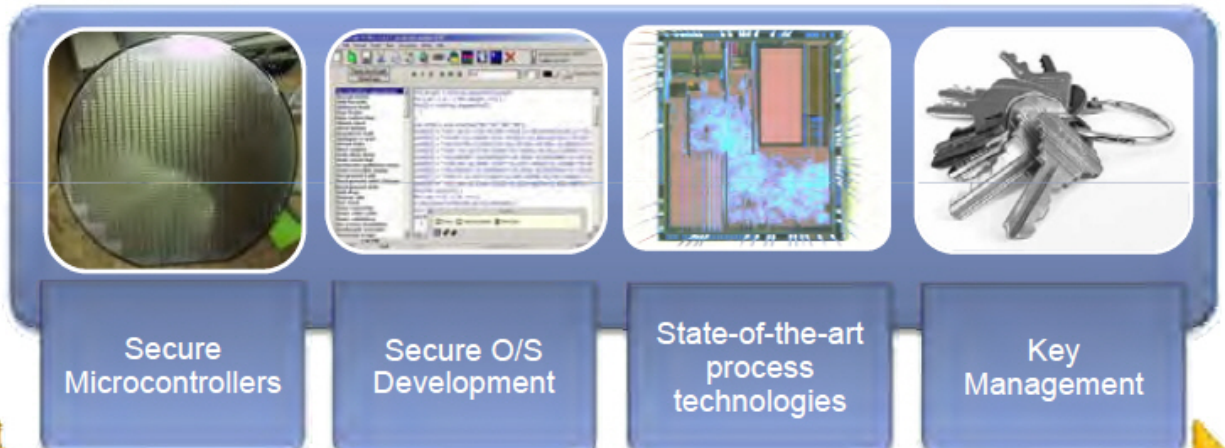
STMicroelectronics

Embedded MCU



Brand Protection Solutions:

Counterfeiting, a Growing Financial Loss



Key growth segments: Computer Peripherals, Accessories and Medical



\$100M

ST Americas:
2012 potential new
business target

Sense & Power Strategy Outlook

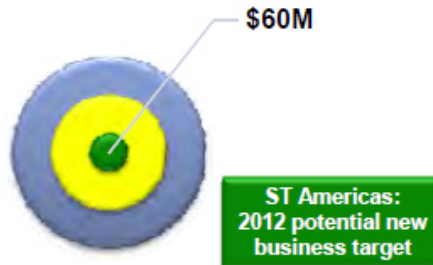


A vast portfolio of analog products, from sensors to power management and power actuation

Sense & Power
A World of Analog

- Power Management SoC for Battery Packs
- Connectivity
- Innovative Audio Amplifiers with embedded CODEC
- Application Specific Data Converters
- High Voltage Switches

Growth across multiple segments: Computer, Consumer, Communication & Healthcare





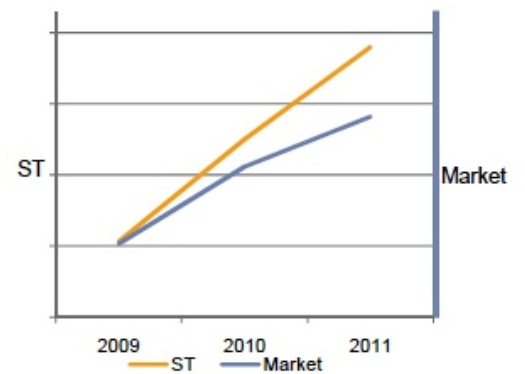
Americas:

Distribution

STMicroelectronics

- **Customer Reach**
 - North American Distribution network: 90% of the market
 - 3 global distributors
 - Merchant Distributors: 15,000 customers
 - Catalog Distributors: 60,000 customers
 - ST is #2 broad-line supplier in NA
- **Sales Growth**
 - #6 ranking in Q110
 - +80% growth of sales to Distributors over 2009
- **Profitability**
 - Systematic price increases accelerating margin growth
- **New Product Design in**
 - #1 in Sales and Design in of ARM 32bit
 - 70% Growth in Power MOS
 - +100% Growth in High Reliability/Space
- **New Market Penetration**

ST Sales Growth vs. Market



Source: Lively Report, Shared Market Data

- **Increasing Demand Creation**
 - Reshaping the team, adding more local design
 - Defining new products for the local market
- **New Products**
 - New generation of MCU's
 - Advanced digital and analog ASIC's
 - New generation of MEMS
 - Connected platforms (WiFi, MoCA, PLM) like 7108M and SPEAr
 - Brand protection secure micros
- **New Markets and Applications**
 - Smart energy
 - Cloud computing
 - Healthcare
 - Internet-based devices
 - Gadgets & gaming



Automotive Products Group

Paul Grimme

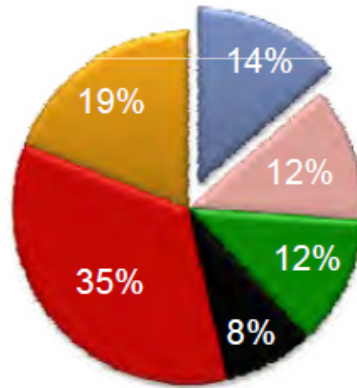
General Manager, Automotive Products Group (APG)

STMicroelectronics

Automotive Inside ST



ST Q1 2010 sales
100% = US\$2.325B



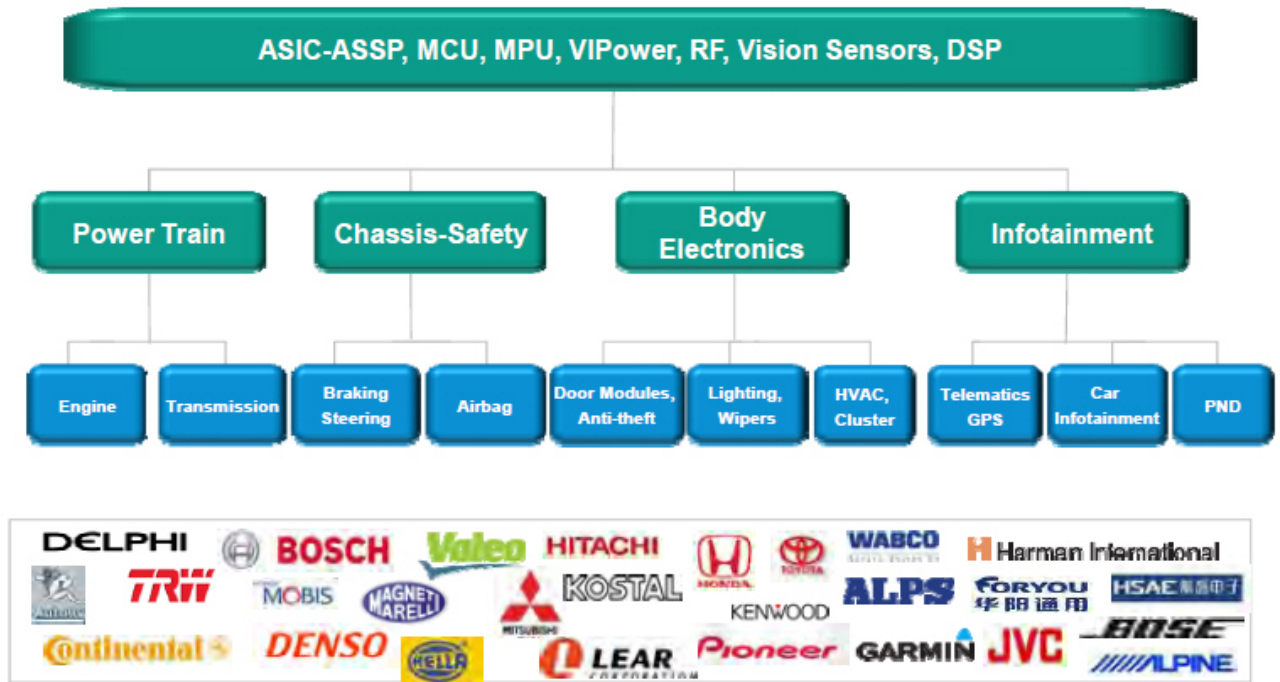
- Automotive
- Computer
- Consumer
- Industrial & Other
- Communications*
- Distribution*

* Sales recorded by ST-Ericsson and consolidated by ST are included in Communications and Distribution

ST: #3 in Global Automotive IC's



Products
Segments
Applications
Customers



Automotive Competitive Environment



Ranking

- Inside its specific perimeter, APG became WW leader in 2009

Rank	Company
1	Infineon
2	Freescale
3	ST
4	NEC
5	Renesas



Restricting to power + analog + digital

Rank	Company
1	ST
2	Freescale
3	Infineon
4	Renesas
5	NEC

Competition

- Common enablers for leadership
 - Broad range offer
 - Quality and relationships
- ST is recognized as having a strong, wide range network of Tier-1 customers

ST	
General	Stability
Technology + Products	BCD, VIPower ASIC portfolio MCU roadmap Infotainment
Strategy	Innovation Partnerships

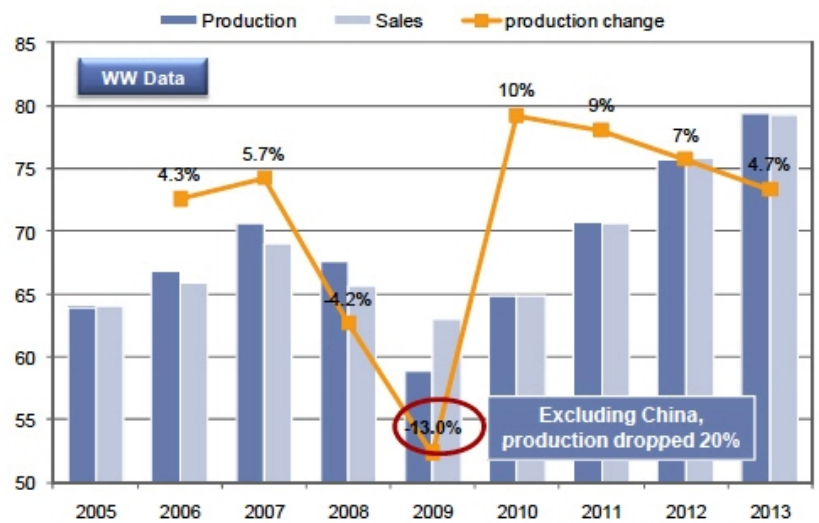
Vs.

Source: Strategy Analytics

Car Market: After the Crisis



- 2009 consumption was strongly incentivized by the world's governments
- Production fluctuation was much bigger than that of sales
- Positive signals now seen
 - Very positive Q1 pace in NAFTA and Asia
 - Platform developments restarted
- Developing countries are growing faster than EU and developed Asia

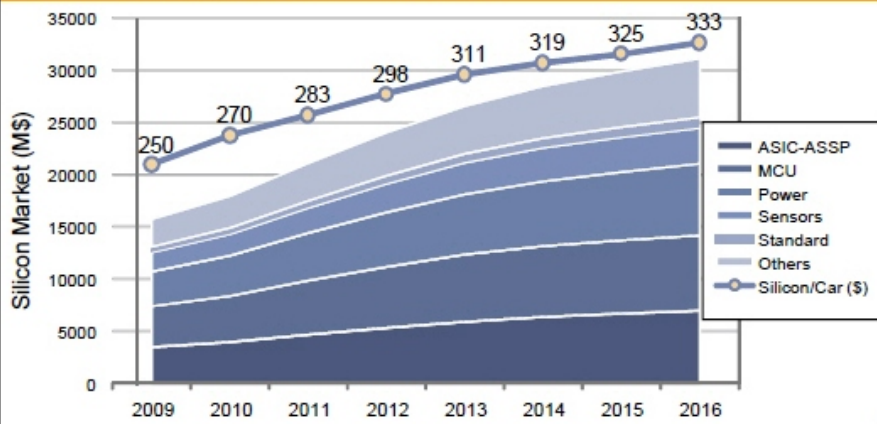


Source: Global Insight

Automotive Market Growth Factors



More Cars, More Electronics



CAGR 2009-2016:
 Cars: 6.2%
 Electronics: 8.5%
 Silicon: 10.2%

Electronic ignition
 Central locking
 Car radio



1975
 25M cars

Electronic gearbox
 Air conditioning
 Antilock brakes
 Seat heating
 Automatic mirror



1985
 32M cars

Navigation
 Adaptive cruise ctrl
 Airbags
 Stability control
 Xenon light



1995
 36M cars

Night vision
 Telematics
 Bluetooth
 Start/stop
 Hybrids
 LED lighting



2005
 64M cars

Pedestrian detection
 Lane change
 Driver assist maps
 Car 2 car
 Internet
 Brake-by-wire
 Steer-by-wire
 Electric vehicles



2015
 86M cars

Source: Strategy Analytics

STMicroelectronics

2010-2015 – Macro-trends in Automotive



Innovation fueled
by social
responsibility

Saving energy, saving lives



Innovate

Car electrification
The safe and connected car



A Global, Cost-
Driven Market

New automotive concept, fast
moving markets for cars &
electronics



**Simplify, Speed
up**

The Small Car
The Low Cost Car
A Global Supply Chain

Future winners shall be leaders of both processes
Join innovation eco-systems, Manage new market dynamics and standards

Innovation fueled
by social
responsibility

Saving energy, saving lives



Innovate

Car electrification
The safe and connected car



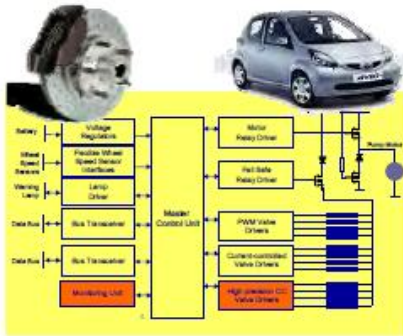
Leveraging partnerships with the industry leaders
Co-development as a model matching technology with know how

Innovation Fueled by Social Responsibility

ST Response: A Test Case

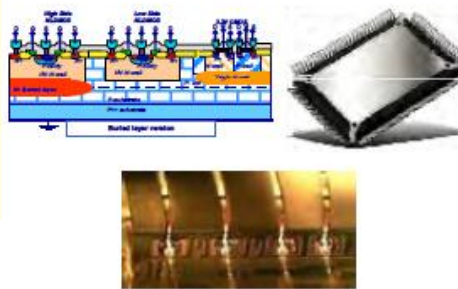
Application: stability control for Japan

- Target is to allow an optimized ESC for all car segments
- Super-integrated IC with power (>5W) + logic (>100K gates)
- Tough requirements on performance, price, timing



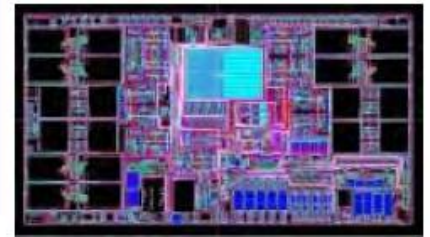
ST strategy: win with innovation

- Silicon technology: BCD8, 0.18um, copper metalization
- Package: HiQuad110™, copper wires, life guaranteed @175°C
- Re-use of consolidated, successful architectures



Result: a first silicon success

- Joint development team with customer
- First silicon fully functional, able to run winter test in Q110
- Over \$100M lifetime value

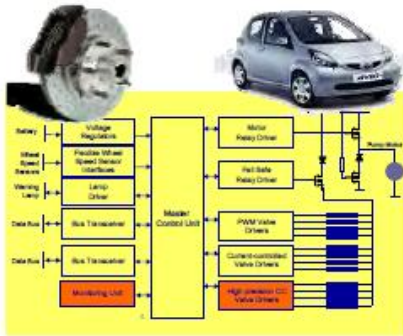


Innovation Fueled by Social Responsibility

ST Response: A Test Case

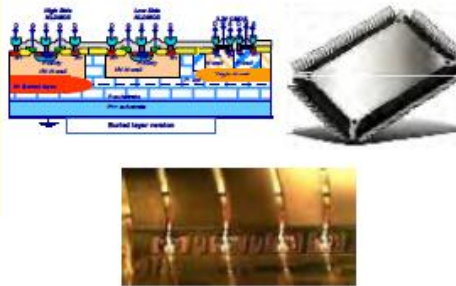
Application: stability control for Japan

- Target is to allow an optimized ESC for all car segments
- Super-integrated IC with power (>5W) + logic (>100Kgates)
- Tough requirements on performance, price, timing



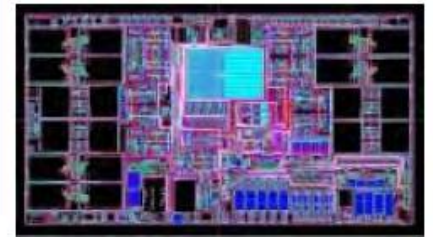
ST strategy: win with innovation

- Silicon technology: BCD8, 0.18um, copper metalization
- Package: HiQuad110™, copper wires, life guaranteed @175°C
- Re-use of consolidated, successful architectures



Result: a first silicon success

- Joint development team with customer
- First silicon fully functional, able to run winter test in Q110
- Over \$100M lifetime value





A Global, cost-driven market

New automotive concept, fast moving markets for cars and electronics



Simplify, speed up

The small car

The low-cost car

A global supply chain

Adapting to the “new” world of Automotive

Different support needs, cost positions, geographies

A Global, Cost-Driven Market

ST Response: Ease Of Use For Cost, Time to Market



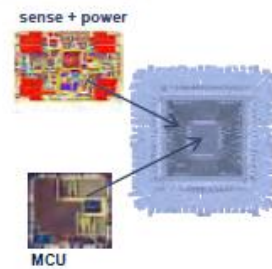
Strategy

- Engineer the portfolio to decrease system cost/complexity

ST advantages and actions

- Strong partnership with market leaders
- Unique and strong ASIC history
- Action: local development in geographies where growth is occurring

Integration



Systems-in-package
Systems-on-chip
Target to grow WW leadership in airbag and small engine control

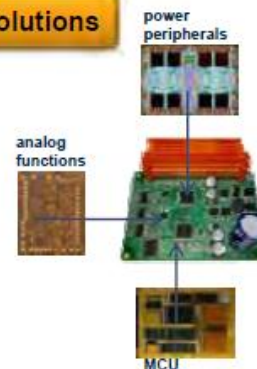
Strategy

- Support market newcomers with standard solutions to allow fast and low-risk time-to-market

ST advantages and actions

- Unique ASSP portfolio covering all segments
- System understanding of basic applications
- Action: engineering and starter kits

Full Solutions



Full IC kit
HW + SW support
Target to grow leadership in BRIC engine control

A Global, Cost-Driven Market

ST Response: A Test Case



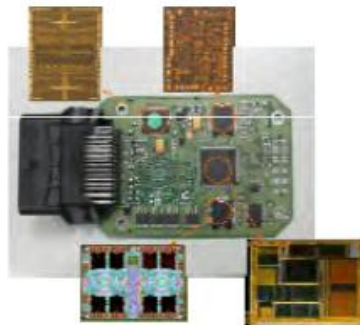
Year 2005: start of new partnership

- Target: engine control for China 4-cylinder car
- Fully Chinese system development team
- Requests to ST: support, speed, value



Year 2007: new system ready

- Production begins
- ST provided all semiconductors, plus SW / HW support
- Joint technical team co-worked for two years



Year 2009: reached 60% of internal market share

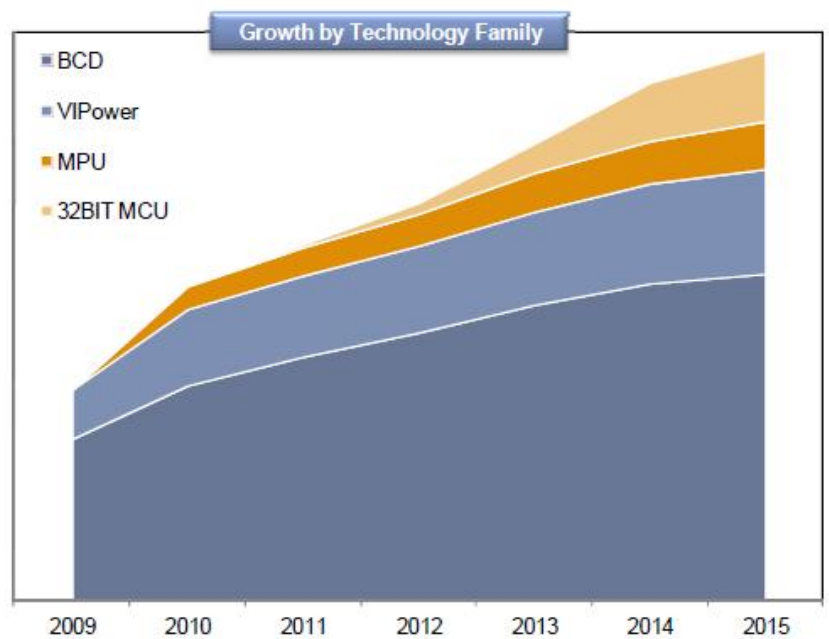
- ECU is present on successful Chinese vehicles
- Solution proved to be competitive in other regions



STMicroelectronics

APG – Main Growth Drivers & Expectations

- Above market growth
- Smart Power technologies will continue to be a main driver
- Digital products add growth
 - MCU
 - MPU (ADAS, Infotainment)
- New market enablers are now being added to APG traditional portfolio
- In the future, further leverage in new technologies is planned
 - PMOS, IGBT
 - Sensors



- Automotive electronics will be a continuing growth market, driven by vehicle demand and content per vehicle
- The market crisis in 2009 did not change the fundamentals, however it accelerated existing trends
- Innovation and ease of use solutions will be critical components of growth for automotive electronics
- The global supply chain is being re-shaped by shifting tastes and geographic locations of consumers
- ST is among the few companies having all assets in place to turn this changing period into one of decisive growth



Digital and Analog ASICs

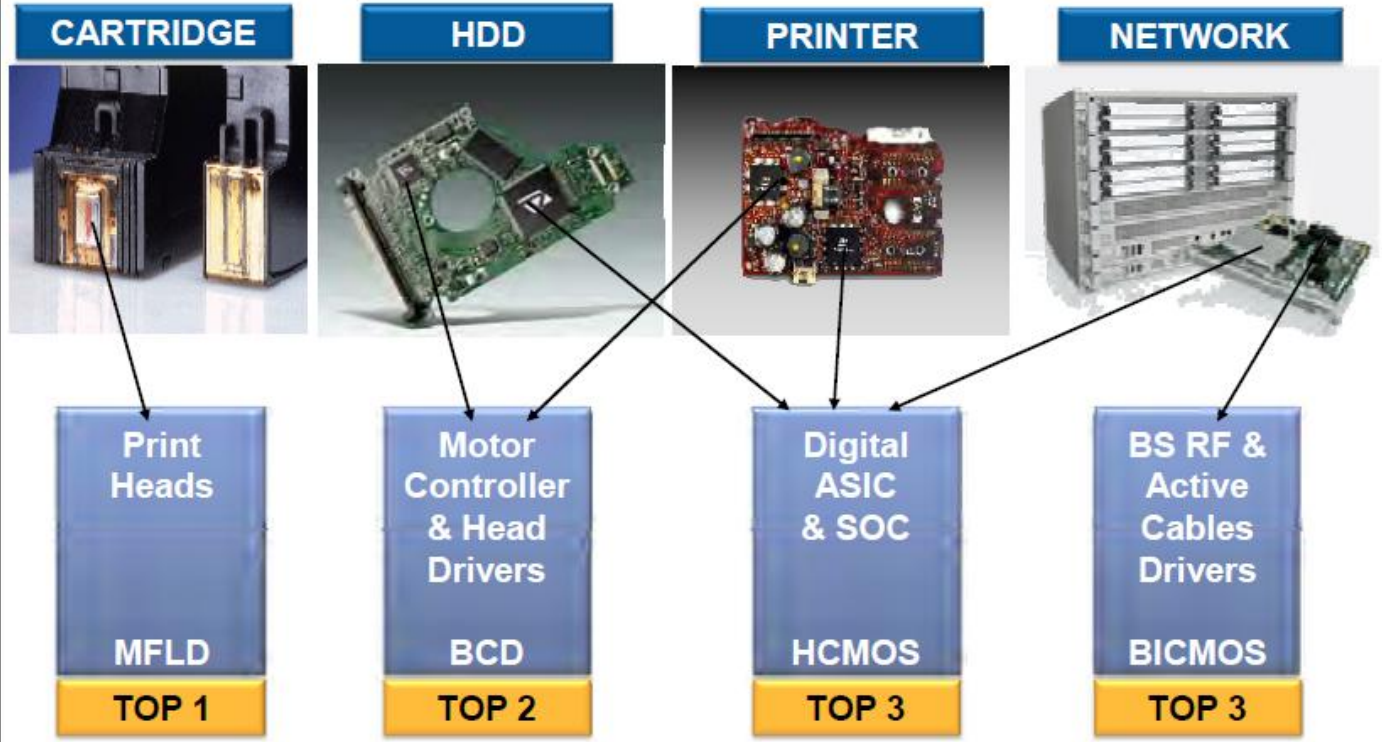
Gian Luca Bertino

General Manager,

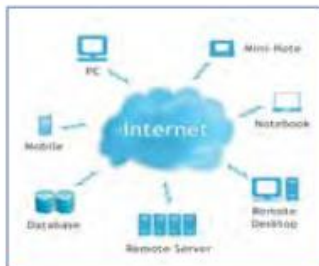
Computer and Communication Infrastructure Product Group (CCI)

STMicroelectronics

Leader in Digital and Analog ASIC



Market Trends and Strategy in ASIC



Cloud Computing



Web Connected



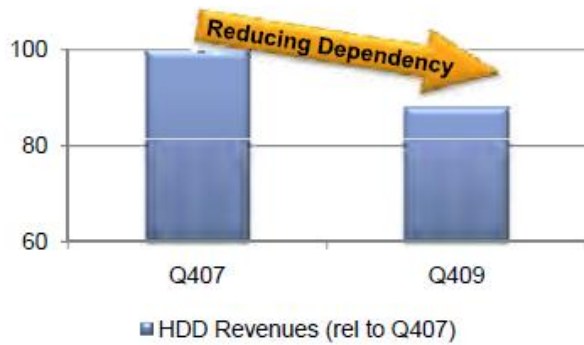
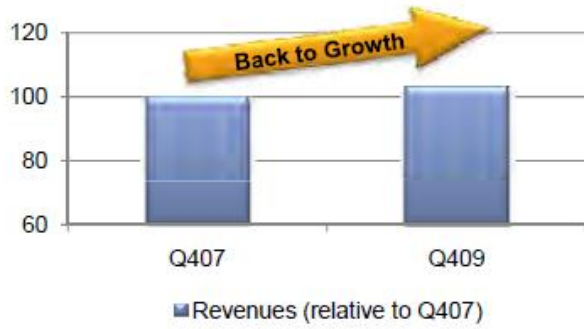
Internet Traffic



Green Systems

- Cloud computing will fuel the next wave, generating increasing demand for (green) infrastructure and transforming all applications in cloud conscious clients
- ASIC continues to be an effective win-win model for CCI customers and ST continues to be committed to it
- The strategy: expanded product offering and flexible business model

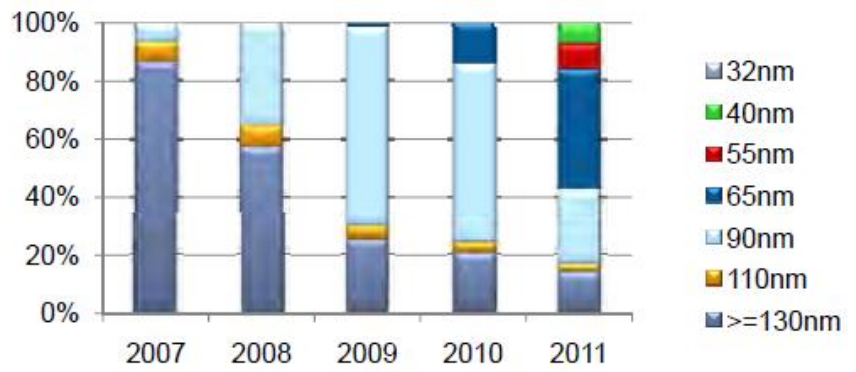
CCI Performance Through the Crisis



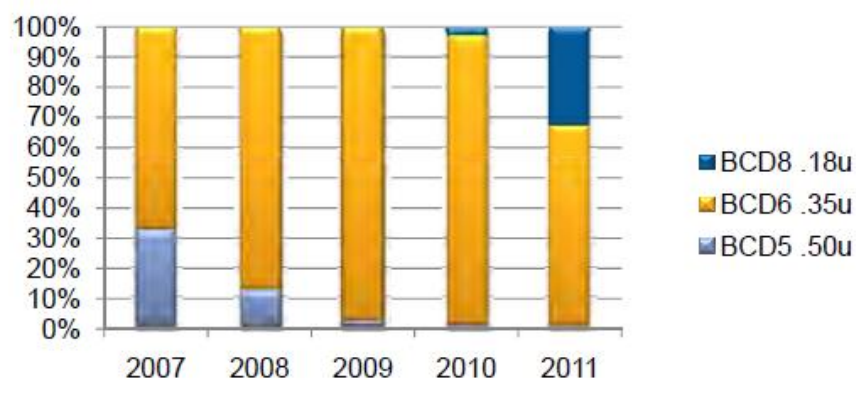
Leading by Technology Acceleration



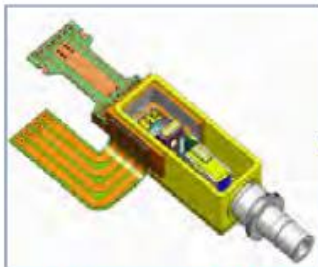
System-On-Chip



Motor Controllers, Head Drivers



CCI Growth Drivers



BiCmos ASIC
for AOC and RF



PrintHeads for
InkJet Printers

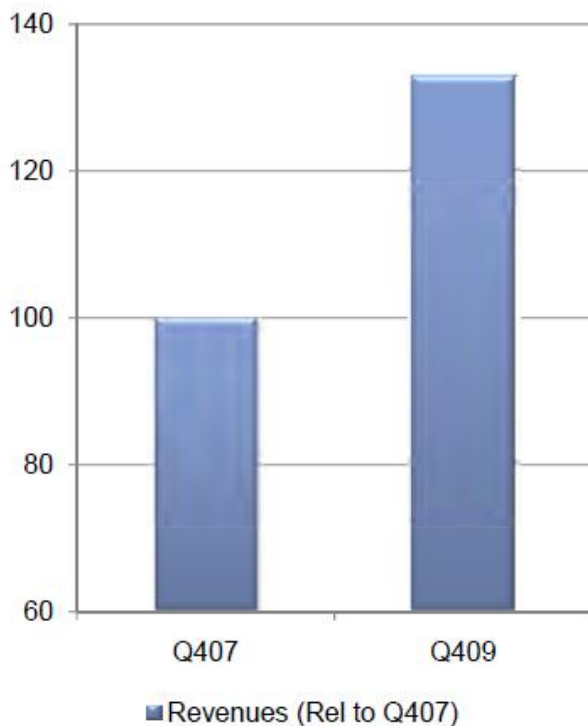


Digital ASIC for
Networking



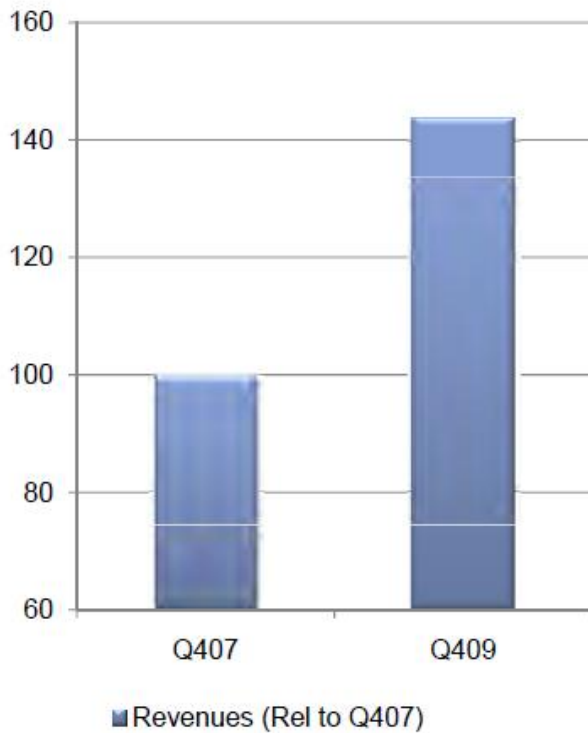
Printer SOC and
SPEAr eMPU

BiCmos ASICs for Networking

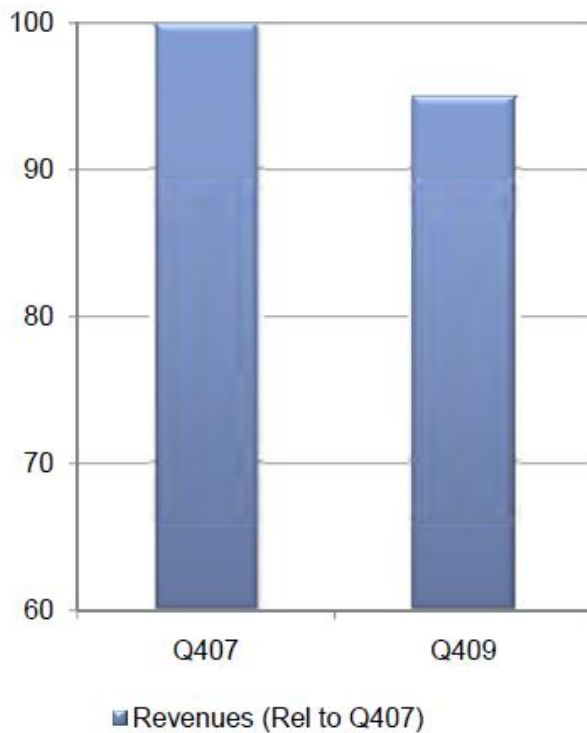


- Leveraging best-in-class BiCmos technologies from ST technology portfolio
 - BiCmos7RF: State-of-the-art performances for both noise and linearity
 - BiCmos9MW: 100G Ethernet Optical Link successfully demonstrated
- Consolidating ST presence in RF COTs for application in wireless base-stations
- Growing in the area of active cables

PrintHeads for InkJet Printers



- Expanding ST leadership in thermal printheads
- Best-in-class microfluidic technology
- Strategic partnerships with multiple customers
- Revenue growth very material in 2009
- Investing in Piezo technology to address new markets



- Enterprise market slower than consumer to go back to pre-crisis
- Anticipating strong growth from 2010 onwards, fueled by multiple wins in 65nm reaching production
- Launching 32LPH, first 32nm bulk process for networking applications
- Launching S12, first 12.5Gbit/sec SerDes in 32nm bulk process

ST's Next Generation Platform



STMicroelectronics Announces 32nm Design Platform for Next-Generation System-on-Chip ICs for Networking Applications

Geneva, May 25, 2010 - STMicroelectronics (NYSE: STM), a world leader in high-performance System-on-Chip (SoC) ICs, today announced full availability of a 32-nanometer (nm) technology platform for the design and development of leading-edge application-specific integrated circuits (ASICs) for networking applications. Central to the new 32nm SoC design platform, which implements ST's 32LPH (Low-Power High-performance) process technology, is the industry's first Serializer-Deserializer (SerDes) IP available in 32nm 'bulk' silicon.

Enabling very large ASIC designs, greater than 200mm², ST's new 32nm 32LPH ASIC design platform enables an unprecedented mix of high performance, high complexity, low power consumption and reduced silicon real estate per functional block. The platform is designed to accelerate the development of next-generation networking ASICs used in high-performance applications such as enterprise switches, routers and servers as well as optical cross-connect and wireless infrastructure applications.

"With the introduction of the 32LPH platform, ST is enabling the next generation of equipment for communication infrastructure applications, which requires highly integrated ASICs that can satisfy the increasing demand in performance, while also meeting extremely challenging power consumption and silicon integration goals," said Riccardo Ferrari, Group Vice President and General Manager of ST's Networking and Storage Division. "We are extremely encouraged by the strong interest that customers are demonstrating for this platform, which has already gained key design wins."

ST's SerDes IP, called S12, is a key piece of intellectual property that has already been successfully demonstrated in labs at selected key customers. The S12 IP is vital for the development of ASICs for networking applications and enables chip-to-chip, chip-to-module and backplane communications in networking equipment designs.

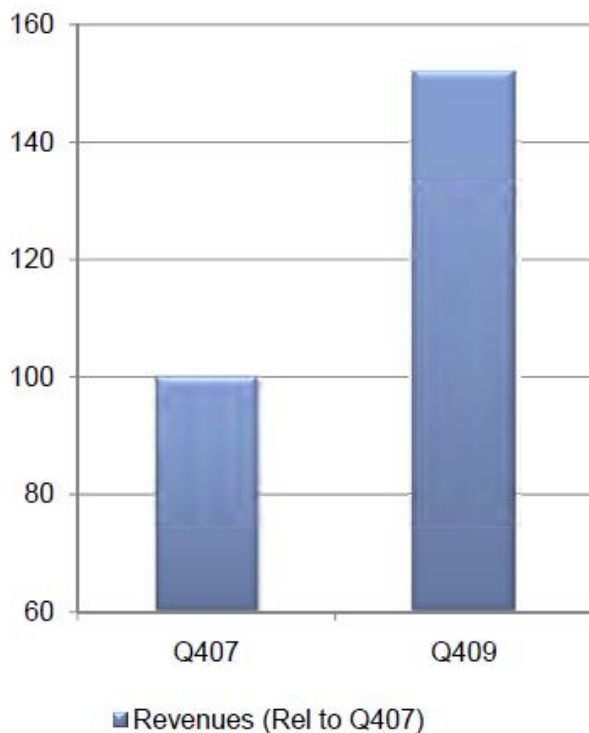
"ST is the first silicon supplier to bring a full design platform in a 32nm bulk-silicon process technology to the communication infrastructure market, including a next-generation predictive ASIC top-down design methodology, together with a full set of proven IP, such as a SerDes and embedded DRAM, successfully developed over many years by ST in previous technology nodes," said Philippe Magarshack, Technology R&D Group Vice-President, Central CAD & Design Solutions GM, STMicroelectronics. "ST's Technology R&D center in Crolles, France, has been instrumental in accelerating the completion of the 32LPH platform where low-power technology meets the high-performance requirements of networking applications, while still enjoying all the cost benefits of high-volume manufacturing. In addition, we have partnered with selected EDA vendors to offer networking customers the benefits of a predictable ASIC turnaround time, including fast virtual physical prototyping, and 32nm-class timing, signal and power integrity sign-off."

The first ASIC prototypes implemented in ST's 32LPH process technology are expected early in 2011 with production ramp-up in the second half of 2011.

Further Technical Information

ST's 32LPH (Low-Power High-performance) design platform for networking applications supports up to 10 metallization layers to increase routing efficiency. The platform is based on the 32nm High-K Metal Gate process developed within the framework of the ISDA alliance, but also incorporates specific IP and devices from ST, such as embedded DRAM with 10-Mbit per square millimeter density and Ternary Content Address Memory (TCAM).

Printer SOC and SPEAr



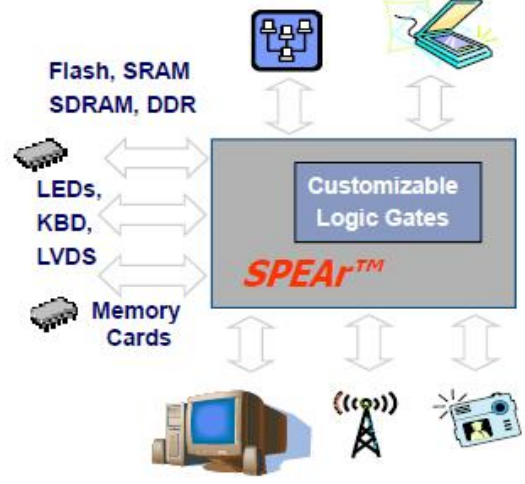
- SPEAr family now expanding with the launch of the 1300 series
- Enabling flexible ASIC models into multiple applications
- Decreasing cost of ownership to customers
- State-of-the-art SOC architecture
- Anticipating continuous growth moving forward fueled by recent wins in printer SOCs and increasing revenues from the SPEAr family

SPEAr Enables Multiple Business Models

Traditional
ASIC



Flexible
ASIC



Embedded
Processing



Decreasing Cost of Ownership to Customers

Expansion of SPEAr Family



STMicroelectronics Expands its SPEAr® Microprocessor Family for High-Performance Applications

New advanced symmetrical multiprocessor architecture from ST delivers cost efficiency, computing power and customizability for multiple embedded applications

Geneva, May 27, 2010 - STMicroelectronics (NYSE: STM), a world leader in system-on-chip technology, today revealed the new architecture that will be the backbone for the new members of its popular SPEAr® (Structured Processor Enhanced Architecture) family of embedded microprocessors, targeting high-performance connectivity and embedded applications.

Leveraging its experience of the production-proven SPEAr300 and SPEAr600 lines, the new SPEAr1300 product line couples powerful dual ARM Cortex-A9 processors with a DDR3 memory interface and is manufactured in ST's low-power 55nm HCMOS (high-speed CMOS) process technology. The dual ARM Cortex-A9 processors support fully symmetrical operation, at speeds up to 600MHz/core for 3000 DMIPS equivalent.

The SPEAr1300 makes use of ST's innovative Network-on-Chip technology for internal peripheral interconnect, assuring support for multiple different traffic profiles, while maximizing data throughput in the most cost-effective and power-efficient way. Initial sampling has already started to early adopters.

The new architecture offers industry-leading performance in terms of DMIPS/MHz and power consumption/DMIPS ratios, in addition to cost efficiency and customizability advantages. The availability of integrated DDR3 memory controller and a full set of connectivity peripherals like PCIe, SATA, USB and Ethernet, among other features, make the SPEAr1300 the ideal choice for high-performance applications including networking, thin client, videoconferencing, NAS (Network-Attached Storage), computer peripherals, and factory automation.

"This new architecture for the SPEAr family builds upon the unrivalled low power and multiprocessing capabilities of the ARM Cortex-A9 processor core" said Loris Valenti, General Manager of ST's Computer Systems SoC Division. "Upcoming SPEAr embedded microprocessors will deliver an unprecedented combination of processing performance, memory throughput, flexibility and low power for next-generation connectivity appliances."

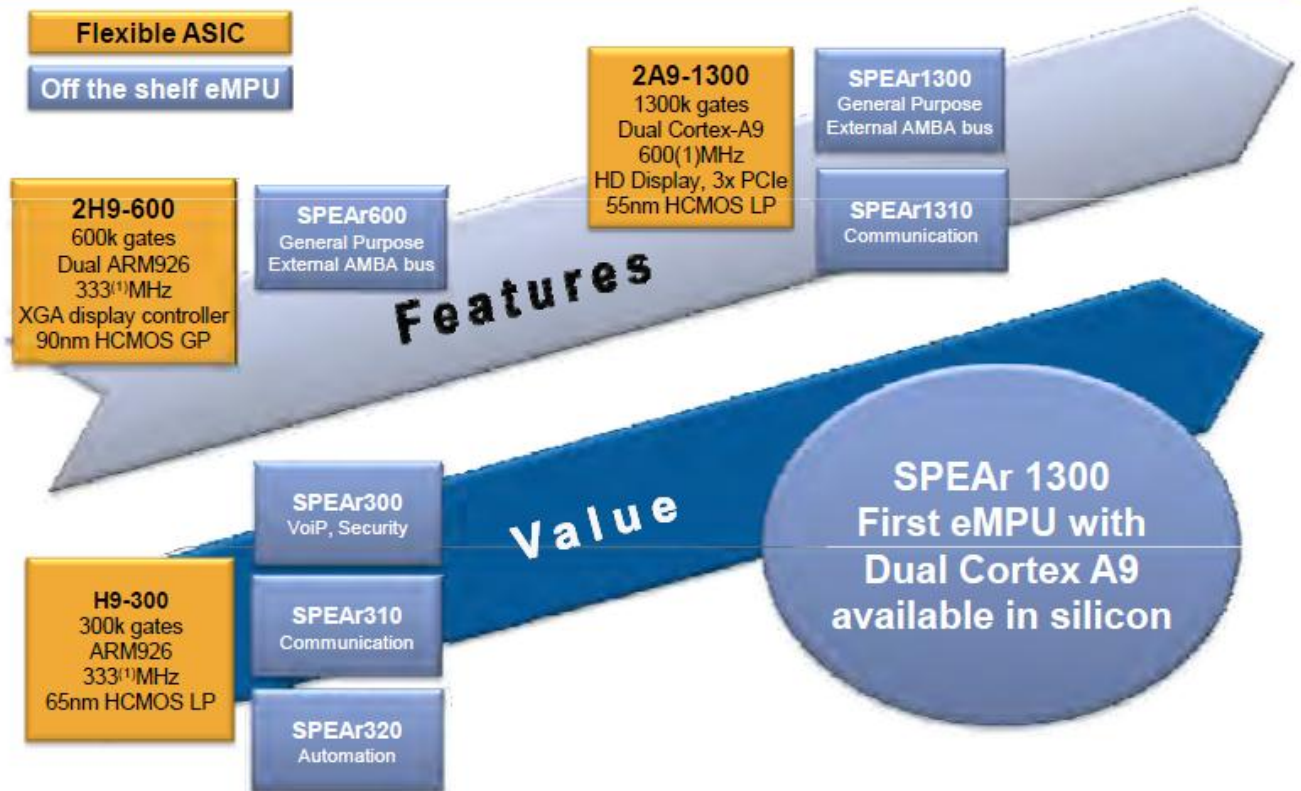
Key features of the new SPEAr1300 architecture include:

- Dual ARM Cortex-A9 cores, running at 600MHz for 3000 DMIPS equivalent
- 64-bit AXI (AMBA3) bus Network-on-Chip technology
- DRAM and L2 cache with Error Correction Code (ECC)
- 533MHz 32-bit DDR3 memory controllers with ECC; 16-bit DDR2 also supported
- Accelerator coherence port
- Gigabit Ethernet
- PCIe 2.0 supporting 5 GT/s (Gigatransfers/second)
- SATA II 3 Gbit/s
- USB 2.0
- 256-bit key hardware encryption/decryption
- 1.3 million gates of configurable logic

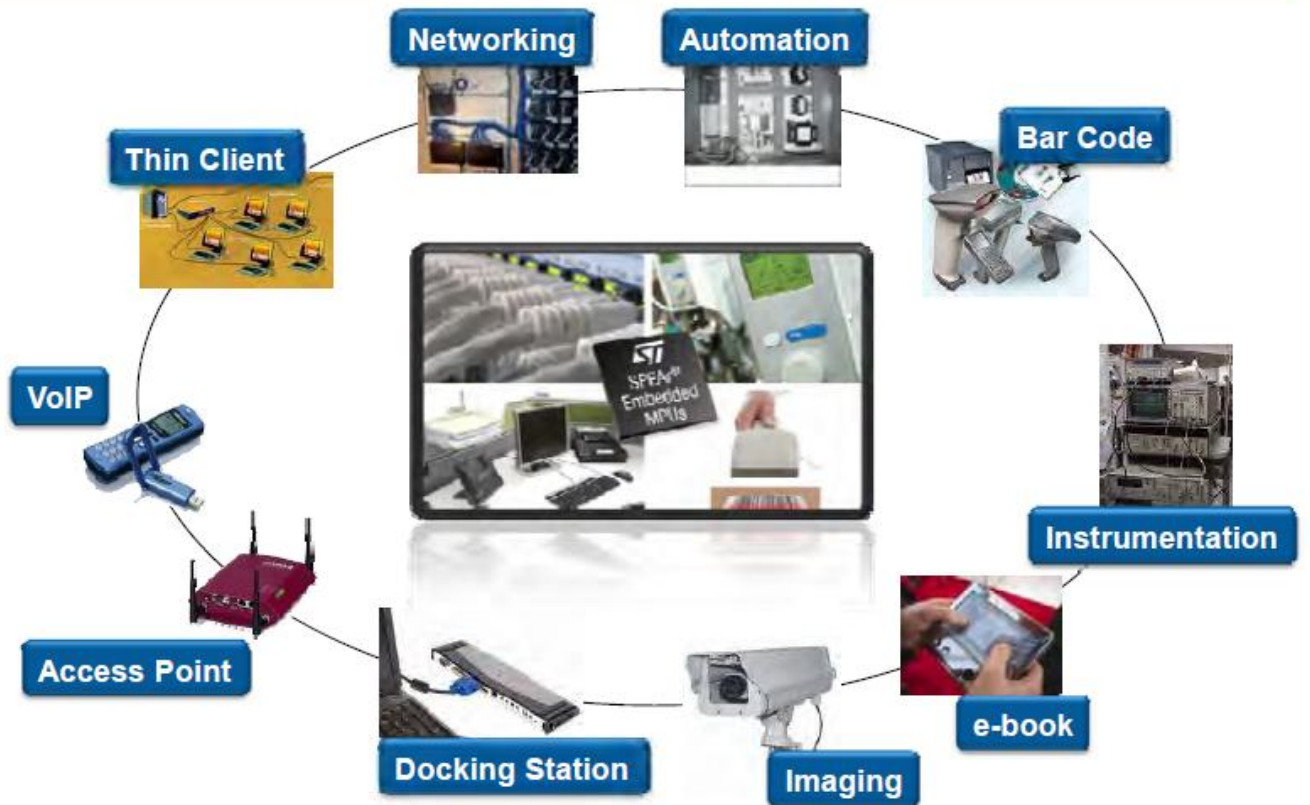
Embedded microprocessors from the new SPEAr1300 product line will be announced over the next few months, expanding ST's SPEAr family and providing an extensive choice for leading customers.

Further information on ST's SPEAr family of embedded microprocessor System-on-Chip ICs is available at www.st.com/spear

SPEAr Roadmap



Addressing Multiple Applications



Key Takeaways



- CCI product group is delivering solid results
 - Revenues in excess of \$1B
 - Operating margin in the low double-digit range
- CCI product strategy centered on traditional ASIC, flexible ASIC and eMPU
- Strategy to grow in Analog
 - Continue to be a market leader in motor controllers for HDD and printers, and in printheads for inkjet printers
 - Now accelerating BiCmos ASICs for both active optical cables and RF interfaces
- Strategy to grow in Digital
 - Significant design wins in the areas of communication infrastructure and printers
 - Launch of the first 32nm bulk platform for networking applications
 - Expansion of the SPEAr family with the launch of the 1300 series
 - Tactical participation in HDD SOC



Home Entertainment & Displays

High on Entertainment – Low on Power

Philippe Lambinet

General Manager, Home Entertainment & Displays Group (HED)

STMicroelectronics

HED Driving Multimedia Convergence



Set-top boxes



TVs / Monitors



Audio



Sensors

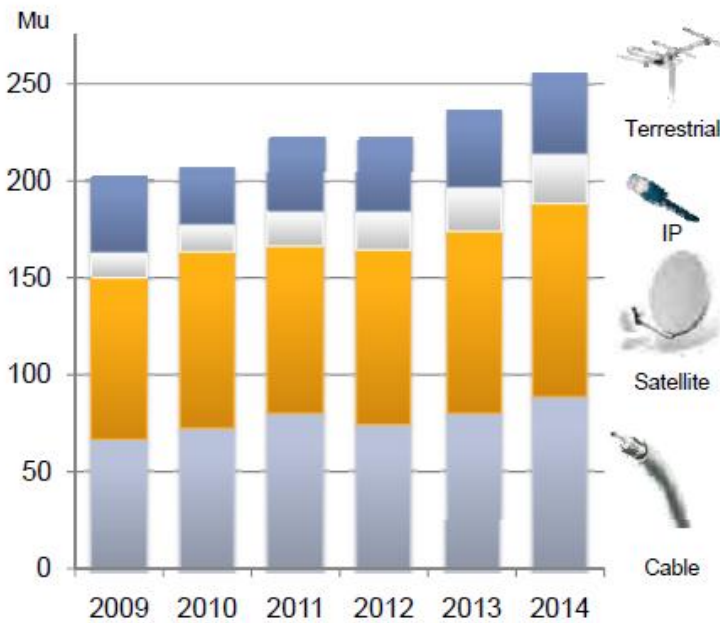


Consumer Electronic Trends



- **Analog switch-off**
 - Increasing demand for Pay TV and FTA satellite
- **New connected services**
 - Content aggregation – broadcast & IP
 - Services across all consumer devices
- **Exciting entertainment experience**
 - 3D stereoscopic TV
 - GUI technologies -- 3D graphics, MEMS...
 - LED BLU
- **Environmental factors**
 - Power consumption
 - Green production





STB Market Evolution

Source: IMS

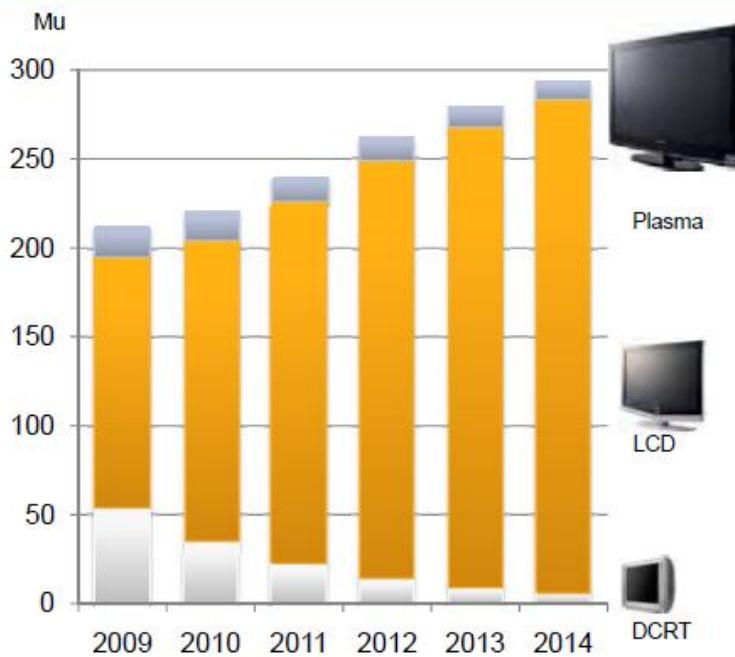
- New value-added services in EU and USA
 - Broadband & broadcast
 - Monetized with advanced security
 - Combined with home networking

- China market is the largest market with growth in cable & IP

- Brasil, India, deploying on SD H.264 essentially starting to commoditize

- MPEG2 commoditization

DTV Market





- Larger share of screen size for 40" and above
- More internet services & content targeting connected TV
- Faster migration rate to digital reception
- Fast technology pace
 - 120Hz to 240Hz
 - LED BLU
 - 3DTV

DTV Market Evolution

Source: iSuppli

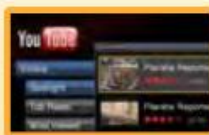
Our Application-Platform Evolution



	Gen. 1	Gen. 2	Gen. 3	Gen. 4
	HD H.264 market enabler	Best Performance/ cost ratio	New services New UI Client/server	Fully open connected platform internet TV
	STi7100 7109, 5202	STi7105 7111, 7141, 7200 5211, 5206, ...	STi7108 71xx, 52xx	STi7xxx
	STi7103/FLI106xx MPEG2 H.264 VC1	STi7104/FLI326xxH 1000 DMIPS CPU <u>Introduction of:</u> AVS HD DDR2 e-SATA	FLI7510 Dual CPU & L2 cache >2000 DMIPS <u>Introduction of:</u> 1080p60 decode 3D GL-ES2.0 MOCA 1.x	FLI7xxx Multi-core SMP CPU >5000DMIPS <u>Introduction of:</u> Dual 1080p60 decode HD encode Display Port, MOCA 2
	Mass production Production: 2007 →	Mass production Production: 2009 →	Samples now Production: 2010 →	In design Production: 2011 →

- **G2 based STB massively deploying**
 - Mass production started in June 2009
 - 55nm process with >10 products families
 - > 50 customers now in production
 - > 50% of ST total STB shipments from 2010

- **G3 getting ready for ramp up in 2010**
 - G3 introduced at CES 2010 in January 2010
 - Freeman/FLI7150 solution for DTV designed in at multiple partners
 - >20 partners enabled with STi7108 platform
 - Develop new category of STB & media center
 - Develop new software for new services
 - RIA, GUI, gaming, mediaserver, ...



▪ Merging broadcast and internet TV



Client/server
Open internet

New Services



User Experience



- Graphics
- Video/audio quality
- Gaming
- Remote control

European Environment Agency



Green



- Low-power
- Sustainable excellence



Why Reduce Power in CE ICs?

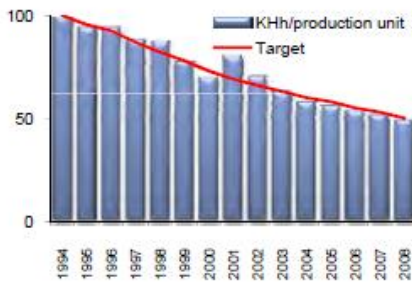


- Governmental regulations compliance
- End customer demand: a consumer selection criteria
- Optimized product cost
 - Bill of material
 - Product reliability
- ST vision: ST's environmental engagement to sustainable excellence



Energy

Electricity consumption per unit of production - normalized values



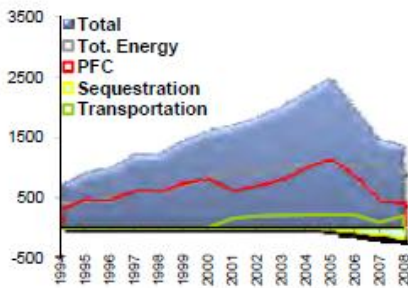
Water

Water consumption per unit of production - normalized values



CO² emissions

Absolute values

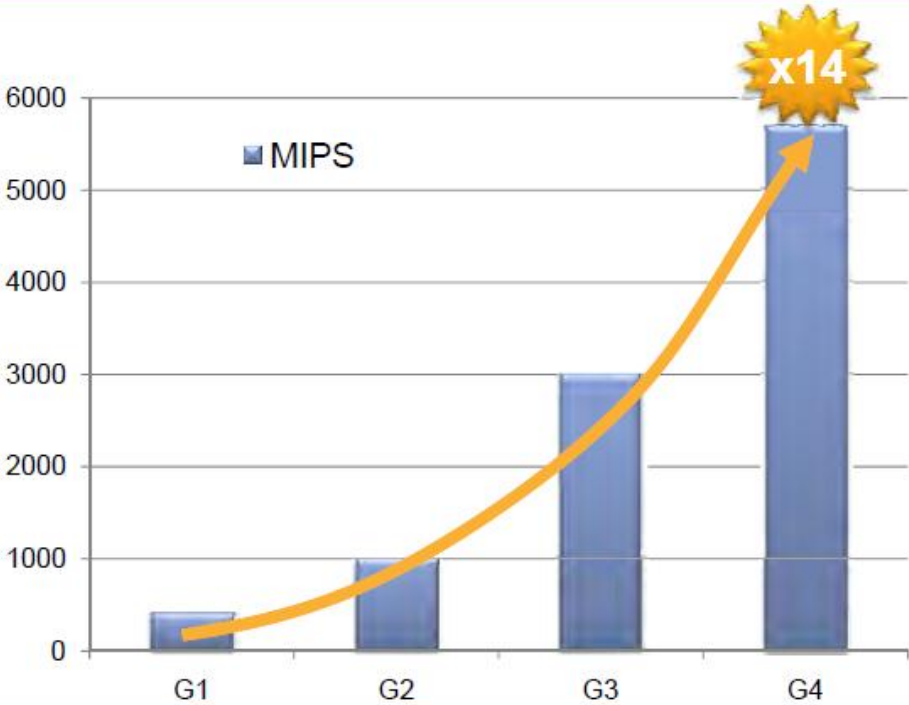


Reduction of waste



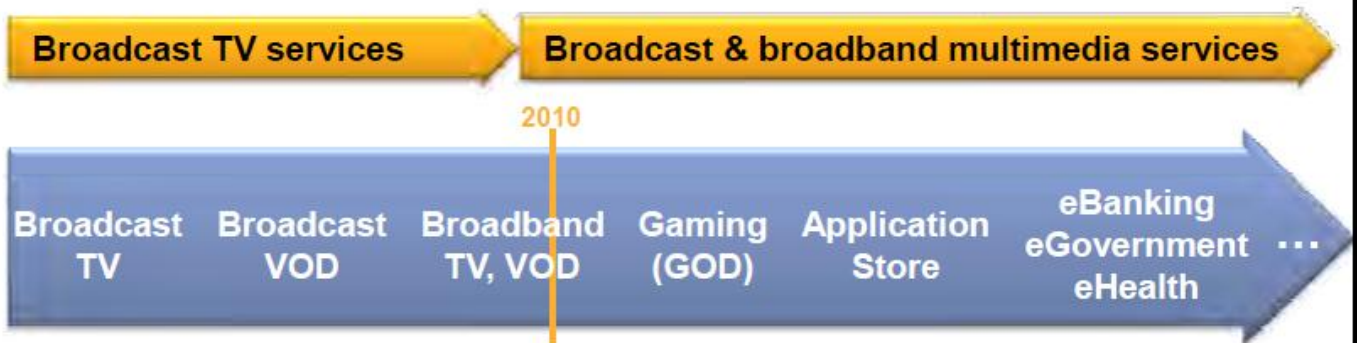
Landfill: from 71% in 1994 to 4% in 2008

Processing Performance Evolution



> 240% performance increase over 3 product generations

STB Security Requirement Evolution

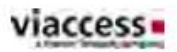


- New value-added services require increasing security resilience
- Rapidly increasing service choices accessible by users requires increased security flexibility without compromise on robustness

ST's Strength in CA & Security



- Long-time partnerships with leading security vendors



and more

- Mastering security from end-to-end

- Security technology developed internally allows for faster adaptation as security evolves
- Full support for smartcard and internal CA



- Late security customization in manufacturing flow

- Delivery flexibility and reduced inventory



Audio & Image Quality Enhancement



- Leveraging years of excellence
- Internet-driven content requires extensive video processing to meet customer's quality expectations
- Sound terminal for high quality low cost speakers



FAROUDJA
VIDEO / AUDIO / AUDIENCE

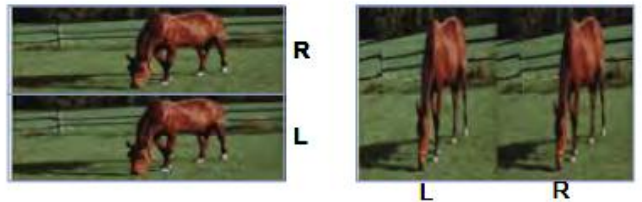


ST is Ready for 3DTV



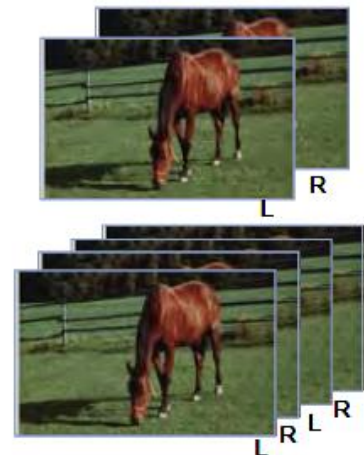
Deployable now!

- Side-by-side support (SbS)
- Top-and-bottom support (TaB)
- ½ resolution 1080p
- Available on all G1 & G2 platforms



Ready for the future

- Frame sequential support added
- Full HD resolution
- Frame rates increasing
 - 60fps on G3 platforms
 - 120fps on G4 platforms



3D Graphics on G3 and G4



- Standards-based: OpenGL-ES 2.0 and OpenVG 1.1
- Optimized for new class of user interfaces
- Paves the way for gaming services

Summary



- **ST has an established position in the home entertainment market**
 - OEM, Ecosystem familiar with ST
 - Proven solutions
- **ST provides complete solutions for a wide range of consumer services:**
 - STB, DTV and other CE devices
- **Unmatched user experience, services and energy-efficiency**
- **ST deploys new technologies for home entertainment to grow revenue**
 - 3D video, 3D graphics, image quality, ...
 - Compelling internet convergence
 - Casual and full gaming ...
- **ST helps build greener products**



FAROUDJA
VIDEO / AUDIO / AUDIENCE





Microcontrollers, Memories, Secure Solutions

Claude Dardanne

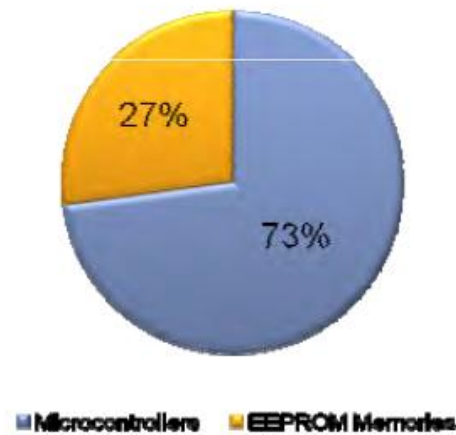
General Manager, Microcontrollers, Memories & Secure Solutions Group (MMS)

STMicroelectronics

- **EEPROM memories**
 - #1 Worldwide supplier
 - 31% share Q409*

- **Microcontrollers**
 - #8 Worldwide supplier
 - 5.8% share 2009*
 - # 3 Secure MCUs
 - # 8 GP MCUs

MMS 2009 Business by Activities



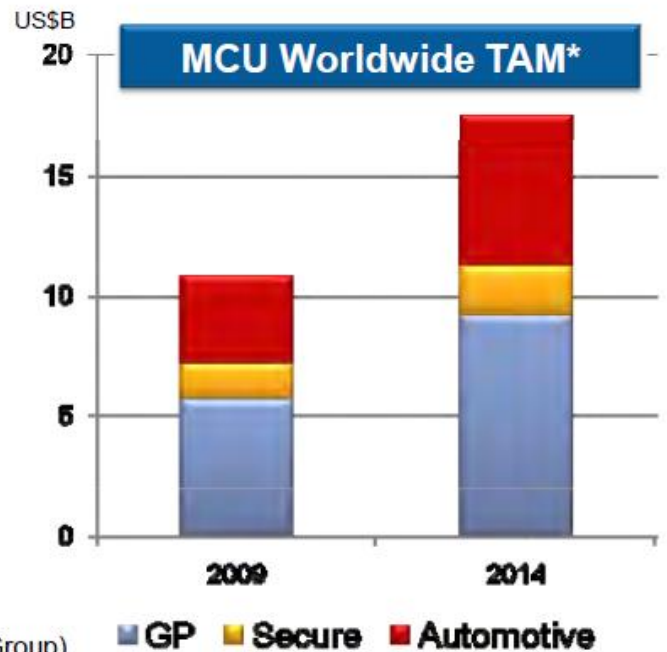
MCU TAM CAGR 2010-14*
+6.4%
→ Key opportunity for growth

Source: iSuppli & WSTS

MCUs Market Drivers



- **General Purpose MCUs**
 - Industrial market
 - Energy management: metering...
 - Consumer: user interface...
 - Healthcare: glucose meter...
 - Automotive: car body, safety...
- **Secure MCUs**
 - Smartcards: SIM...
 - Pay TV
 - Brand protection
 - IT: Trusted platform...
- **Dedicated Automotive MCUs**
(Focus from ST dedicated Automotive Products Group)



Source: WSTS

- **\$8B business opportunity in 2011**
 - Multi-segments market
 - Steady growth foreseen in the next 5 years
 - Well established and profitable business model
 - Migration to 32bit CPU based on advanced e-NVM technology

- **Customers**
 - Tens of thousands of customers worldwide
 - Broad, multi-applications and fragmented business
 - Customer investment in software ensures higher business stability and strong commitment to a family of products

- **Complementary to ST's advanced analog portfolio**

- **\$2B business opportunity in 2011**
 - Smartcard applications driven (SIM, Banking, Government, ID, Transport)
 - Global shift to digital electronics requires more and more embedded security functions
 - Migration to Flash based e-NVM technology embedding advanced security features

- **Customers**
 - In addition to key Smartcard suppliers, other customers are recognizing the value of embedded security functions
 - Strong commitment to a family of products due to software investment, better business stability

- **Technology driver for microcontrollers products**



MCUs Shared Platforms

- **State-of-the-art embedded NVM technologies**
 - e-Flash
 - E-EEPROM

- **High-performance CPU cores**
 - 8-bit
 - 32-bit

- **System know-how**
 - General purpose
 - Security

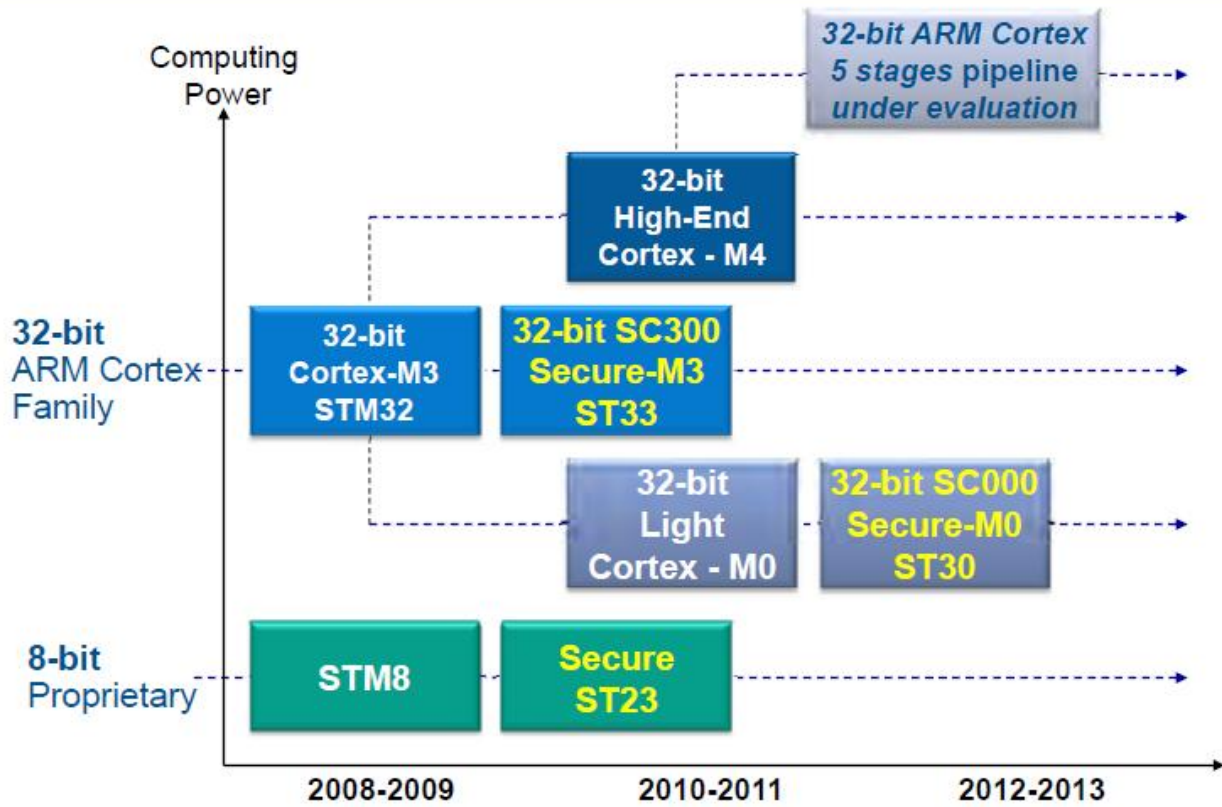
State-of-the-Art e-NVM Technology



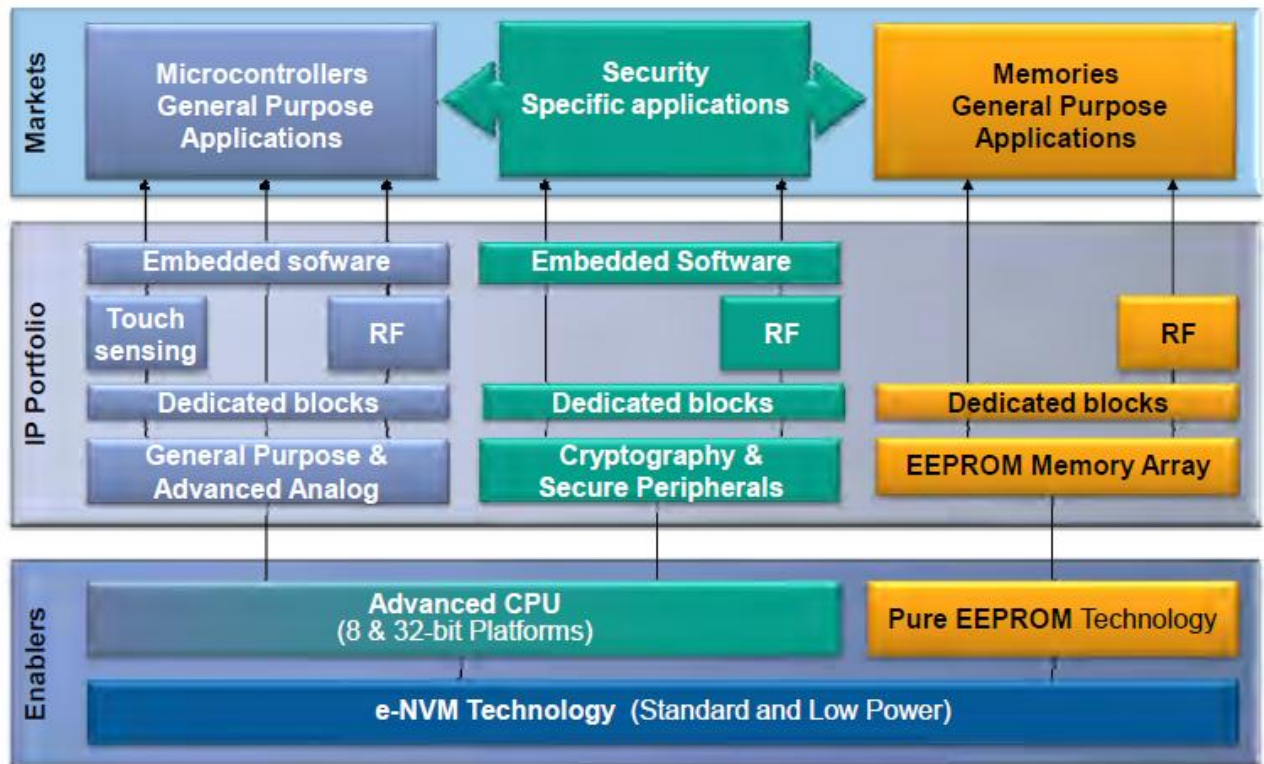
	2008-09	2010-11	2012-13
e-Flash	90nm	80nm	55nm
e-EEPROM	130nm	90nm	

→ High speed
→ Ultra low power
→ Advanced Analog functions

High Performance CPU Platforms



From Enablers to Markets



From Societal Needs to Solutions



System & product know-how

Integrated Controllers

- Ultra-low-power
- A/D converter
- Connectivity

Secured solutions

- Trusted processing
- Tamper resistance
- Cryptography

Contactless & RF

- ZigBee & RF4CE
- NFC solutions
- Contactless cards



Needs

Energy efficiency

Aging & Health care

Communication/Entertainment

Transportation

Solutions

- Smart metering
- Appliance control
- Sensors network

- Home monitoring
- Therapy control
- Drug traceability

- Pay TV, touch control
- Brand protection
- M2M, NFC & SIM

- Fare collection
- e-Passport
- Real-time monitoring



MMS Growth Strategy

STMicroelectronics

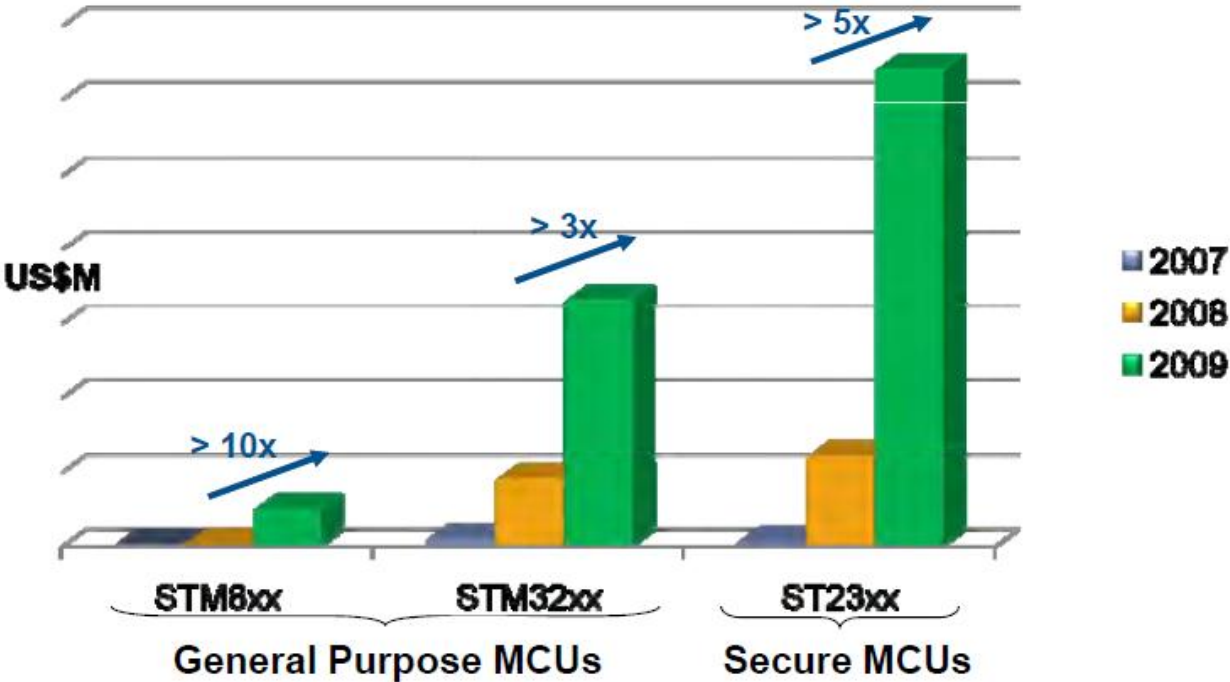
- **General purpose MCU strengths**
 - Leadership position on the 32-bit market based on STM32 (ARM Cortex) platform
 - Advanced e-NVM roadmap (ultra-low-power & RF focus)
 - Advanced Analog capabilities

- **Secure MCU strengths**
 - Market acceptance of ST23 & ST33 platforms
 - Advanced e-NVM roadmap
 - Advanced security features know-how
 - 20% market share with limited participation to the SIM market

New MCU Platforms Deployment



Revenues



- **General Purpose Microcontrollers**
 - Capitalize on solid market acceptance of the STM32 platform
 - Broaden STM32 microcontrollers portfolio to ensure huge pervasion and improve market coverage
 - 16-bit market coverage with ARM M0 32-bit light Cortex
 - High end 32-bit market coverage with ARM M4
 - Increase x5...x10 the number of customers using STM32 platform

- **Secure Microcontrollers**
 - Expand ST23 & ST33 secure platforms to new applications
 - Trusted computing...
 - Maintain leadership position in advanced security features

- **EEPROM**
 - Long-term commitment to stand alone EEPROM products
 - >2B units shipped per year, up to 2Mb density
 - Create a new market standard with dual mode EEPROM (RF + contact)



MMS Product Highlights

STMicroelectronics

STM32 for Appliance (Motor) Control

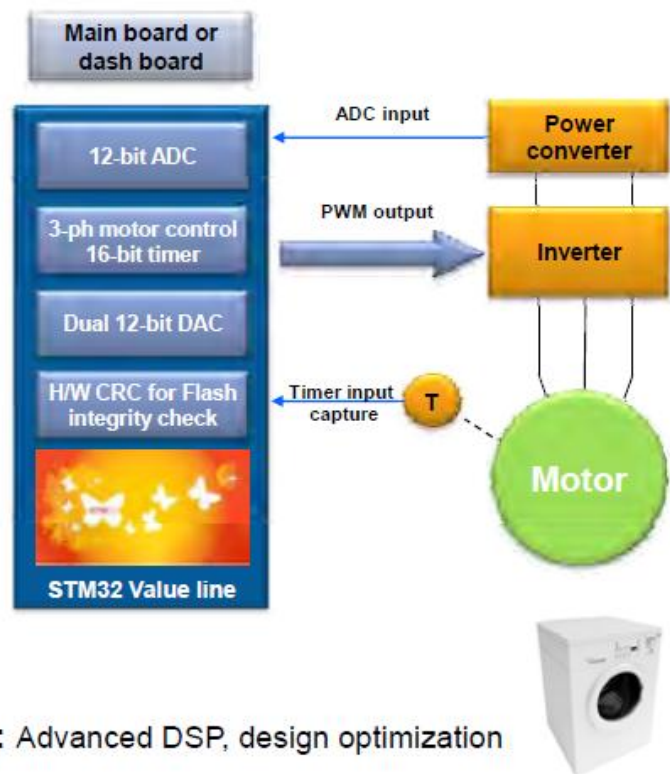


- **Environment friendly**

- Energy efficiency
- Noise reduction

- **Key features in STM32**

- High-performance CPU
- Embedded Flash memory
- ADC, MC timer
- Control software libraries
- Cost effective



- **Key Technologies for evolution:** Advanced DSP, design optimization

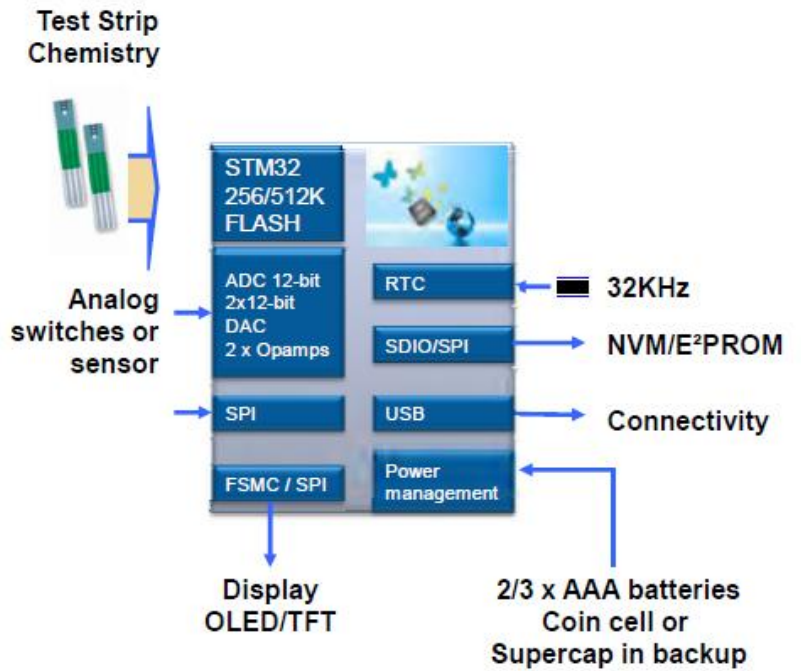
STM32L for Health Applications



Key features in STM32

- High-performance CPU
- Extended portfolio
- Ultra-low-power STM32L

Glucose Meter



STM32W for Wireless Sensor Networks



Security

Shock sensor, anti-theft, anti-intrusion



Infrastructural monitoring

Buildings, bridges



Energy management

Smart metering



Healthcare/ assisted living

Rehabilitation,
balance control



Sport & Wellness

Sport monitoring,
pedometer,
fall detection



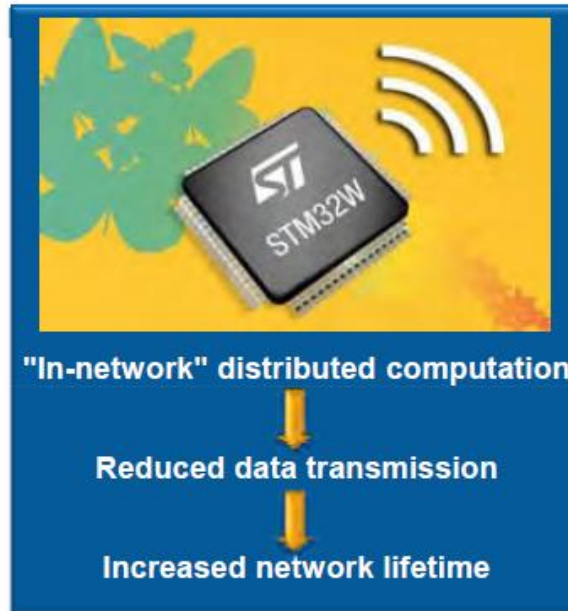
Games & remote

Consumer control

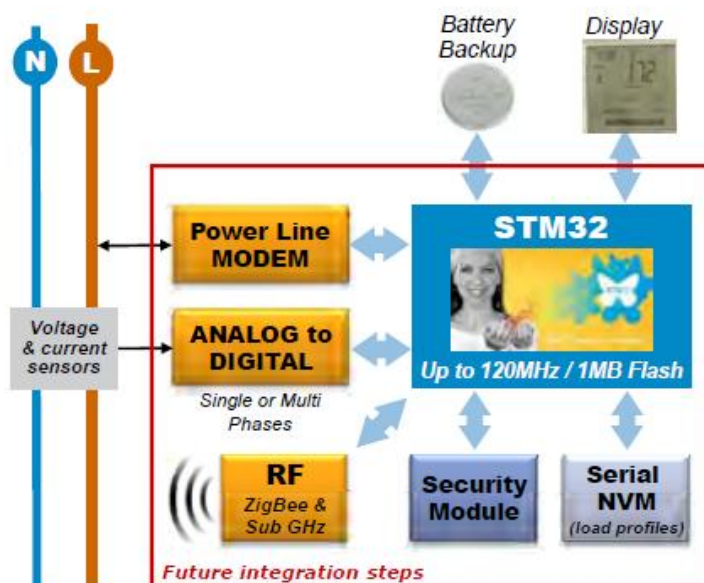


Industrial

Vibration & tilt
remote
measurement



STM32 for Smart Electricity Metering



- **Energy efficiency**
 - Global trend to SmartGrid
 - Smart meter as central element
- **Key features in STM32**
 - High performance CPU
 - Low power & Real Time Clock
 - Embedded Flash memory
 - Extended portfolio

- **Key Technologies for evolution:** Power line, RF connectivity, ADC, Tamper resistance

ST33F1M for High-end Secure SIM Card



■ Pay with your SIM

- Visa & Mastercard payment applications
- Banking security level



■ Travel with your SIM

- Mifare, Felica, Calypso applications
- "Over The Air" reloading & management



■ Multimedia on your SIM

- Integrated webservice
- Enriched content & applications on the SIM



ST21NFCA & ST33F1M for NFC solutions

- Bring contactless capability to a handset



ST33ZP24 SoC for Trusted Platform



- Leading-edge secure 32-bit CPU
- State-of-the art 90nm e-EEPROM technology
- Embedding in-house TPM Firmware
- Supporting multiple hardware interfaces
 - LPC for PC platforms
 - SPI, I2C for embedded platforms



ST23YR for Contactless Solutions



- ST23YR designed for advanced security and high-speed contactless solutions
 - ST23YR80:
biometric passport transaction < 3 seconds
 - ST23YR18:
EMV Paypass DDA transaction < 300ms
 - ST23ZR08:
secure transport solution



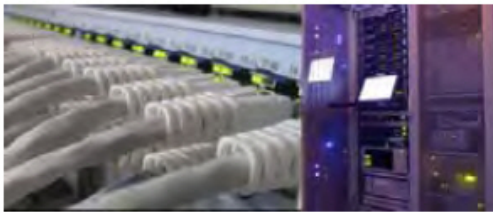
AuKey Solution for Brand Protection



- Turnkey solution based on highly secure operating system running on ST23 platform

- **AuKey to authenticate securely:**

- Printer cartridges
- Game peripherals
- Docking station
- Network accessories



Dual Interface Serial EEPROM



- Application parameters are accessible from the *inside* (I²C) & the *outside* (RF) of electronic equipment
- Passive (ISO15693) RF interface
- 32-bit password protection

Parameters such as settings, traceability, maintenance logs, firmware... can be read and updated:

- Anywhere in the supply chain
- At no on-board power cost
- During the entire product lifetime
(*manufacturing, shipping, maintenance ...*)
- Even when the device is turned off or in its shipping box



Allows extra flexibility for supply chain management



Conclusion

- General purpose microcontrollers market
 - Very large and well established market
 - Market migration to 32-bit well synchronized with STM32 platform introduction
 - Early success of the STM32 ramp-up
 - New business opportunities allow for increased market share
- Secure microcontrollers
 - Electronics market moving to digital
 - Early success of ST23 & ST33 ramp-up

Great business opportunities for ST



MEMS & Advanced Analog

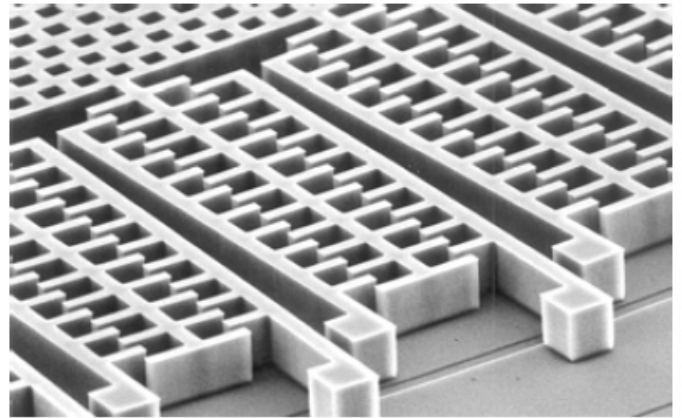
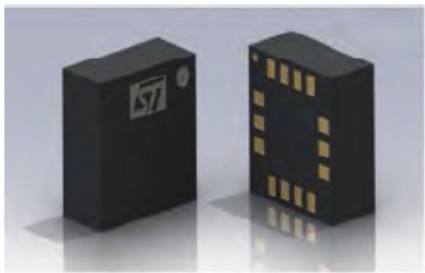
Benedetto Vigna

General Manager, MEMS, Sensors and High-Performance Analog Division

STMicroelectronics

MicroElectroMechanical Systems (MEMS)

- **MEMS** take advantage of the electrical and mechanical properties of silicon
 - Electronic circuits
 - Mechanical structures
- Semiconductor manufacturing
 - High volume
 - Small size
 - Low cost



- Leadership in MEMS for consumer market
 - Extended customer base
 - Nimble product development
 - Timely investment in state-of-the-art manufacturing

 - In 2009, expanded accelerometer portfolio with
 - Gyroscopes, microphones, compasses
 - Smart sensors: iNEMO™
- ...toward the “One-Stop MEMS Supplier” goal
-
- Leverage leading MEMS position and strong competence to increase presence in advanced analog

MEMS Leadership



ST is # 1 in MEMS for consumer electronics and mobile handset market
2009 ST revenues = \$218M; Market TAM = \$1,170M*

ST leads accelerometer business in all market segments

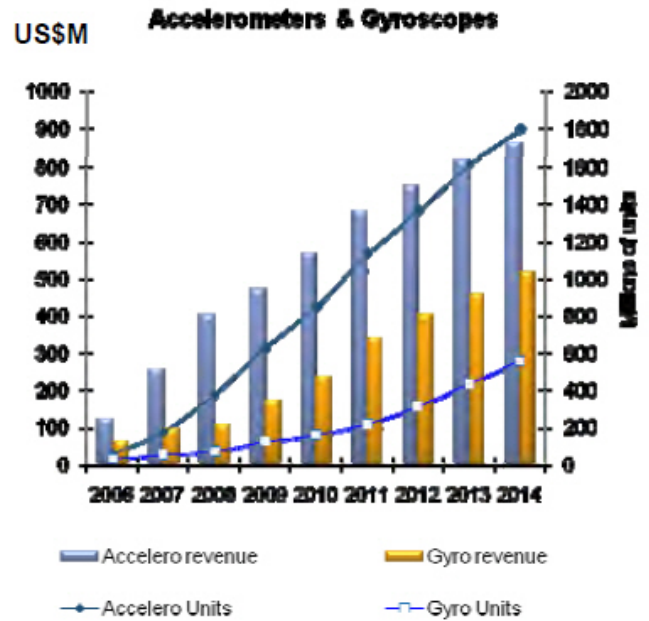
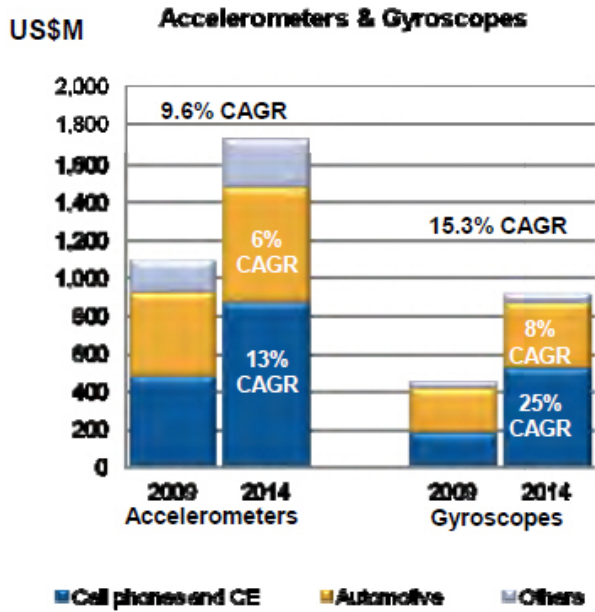
Consumer electronics and mobile handsets*
2009 ST Market Share = 50%

All markets, including automotive and industrial*
2009 ST Market Share = 21%

Manufactured > 750M
accelerometers and gyroscopes

* Source: iSuppli

MEMS Motion Sensors



Consumer Markets Exceeding Automotive Markets in Units and Revenue

Source - iSuppli

ST Drives MEMS Avalanche



- **2005:**
We entered PCs
- **2006:**
We entered Gaming
- **2007:**
We entered Phones



ST Continues to Drive MEMS Avalanche

- **2008:**
We entered Pockets
- **2009:**
We entered Cameras
- **2010:**



Source: iSuppli reverse analysis of Apple iPad

STMicroelectronics

MEMS Enable New Applications



Optical Image Stabilization

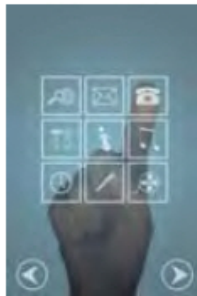
Point Of Interest



Location Based Services



Enhanced User Interface & On Line Gaming



Augmented Reality

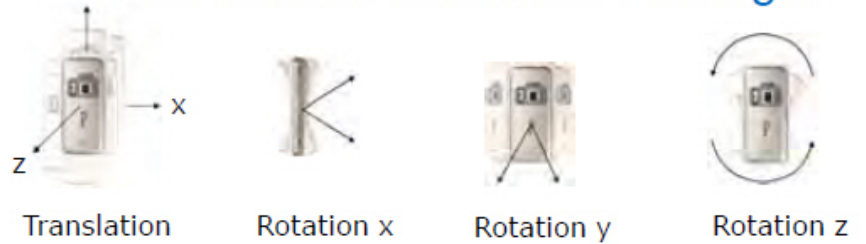


STMicroelectronics

MEMS for Optical Image Stabilization



Hand tremors cause blurred images



Gyroscope senses tremors and the micro-actuator compensates



OIS OFF



OIS ON

How much is that shirt?



Point Of Interest

POI



No compass

POI_Filtering



With compass

*Augmented Reality**



Source: www.apple.com (Wikitude)

Navigators

Dangerous driving detection

Crash recording

Post-crash door unlock system

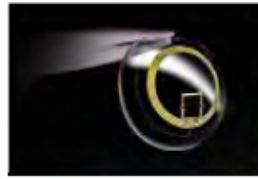
Anti-theft systems

... and much more...

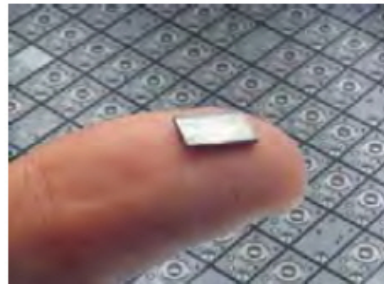


■ Sensing

- Body motion
- Pressure
- Acoustic signals
- Bio signals (ECG, BGCM)
- Biosensors

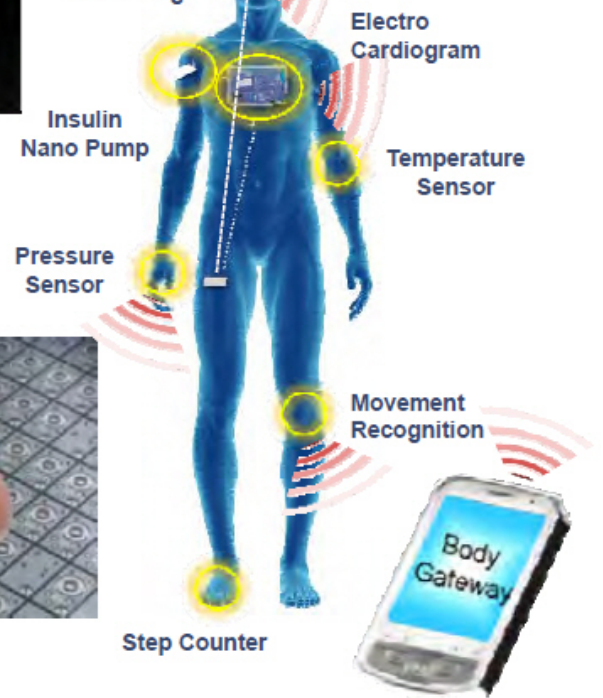


Flexible Lens for Eye Pressure Monitoring

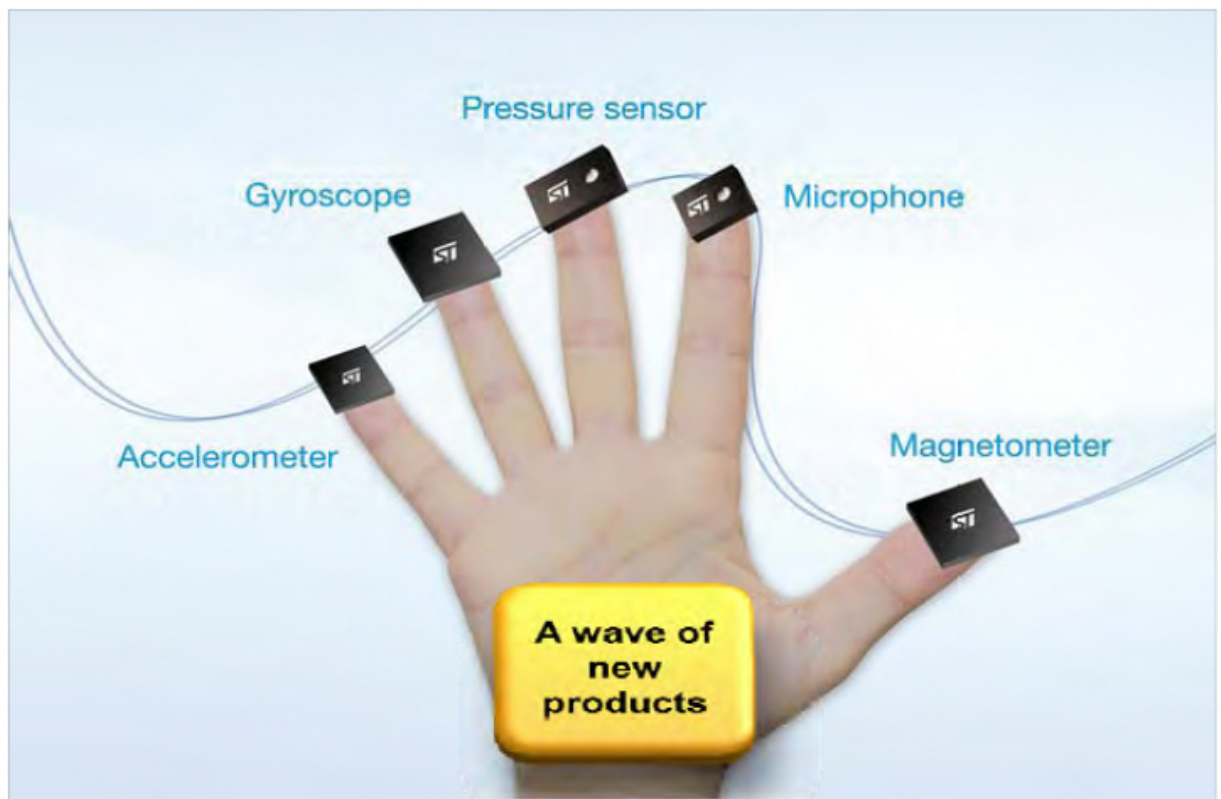


■ Drug Delivery

- Pumps
- Valves
- Nozzles



2009: Not Only Accelerometers.....



Cristallo:

Ultra-Low-Power and High Performance Accelerometer



Higher flexibility at lower current



100X Lower Power



Advanced power management

- Wide supply voltage down to 1.8V
- Ultra low current

High versatility

- Extended FS range (2/4/8/16g)
- Multiple configurable interrupt sources

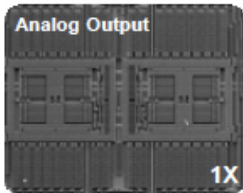
Embedded features

- Programmable FIFO (32 levels)
- 3 auxiliary ADC channels

Gyroscopes: We Are On Time



In 2009, we announced more than
30 Multi-axis Gyroscopes



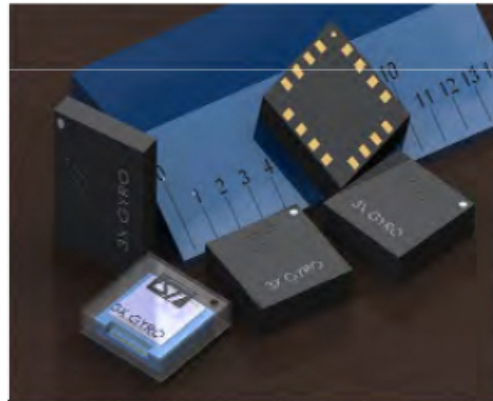
2008



2009



E Jan 2010



- Application Segments:**
- Enhanced motion user interface
 - Image stabilization
 - Gaming
 - Navigation

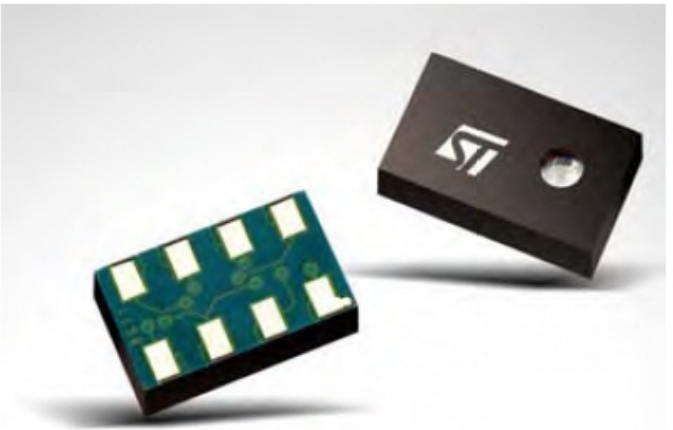
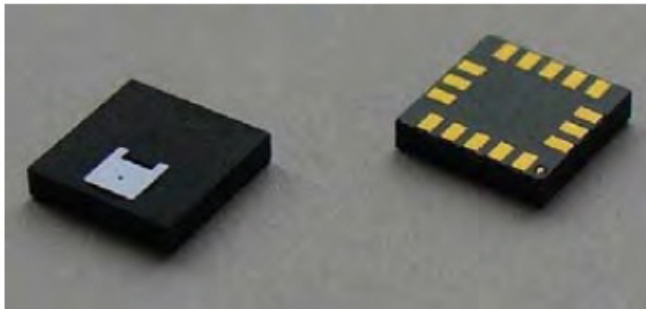
Gyroscopes market for mobile and consumer TAM 2010: \$246M CAGR 2010-2013: ~20%

Source: iSuppli

Pressure Sensors as Altimeters



Absolute, temperature-compensated, ultra-compact pressure sensor with digital output



... make it small; make it accessible

Application Segments:

- Blood pressure sensors
- Navigation system
- Water level management

**Pressure sensors market for mobile and consumer TAM 2010: \$47M
CAGR 2010-2013: ~27%**

Source: iSuppli

STMicroelectronics

Microphones Enhance User Experience



Your mobile phone becomes your conference-call solution



Application Segments:

- Mobile phone
- Digital camera/camcorder
- Laptop PC
- Gaming

- Excellent sound quality
- Superior reliability and robustness
- Small size (3 X 4 X 1mm)

Microphone market for mobile and consumer TAM 2010: \$176M
CAGR 2010-2013: ~24%

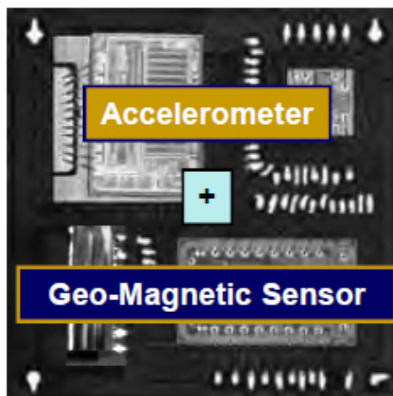
Source: iSuppli

STMicroelectronics

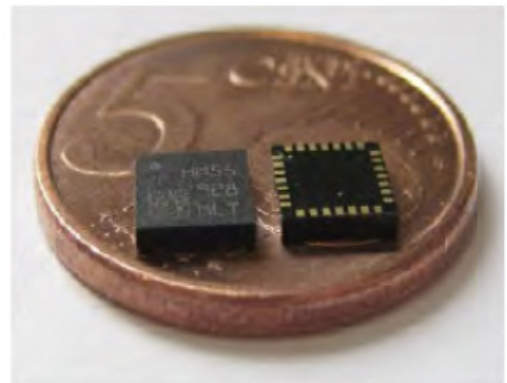
Compass Shows Heading



A look from the Inside...



...and from the Outside



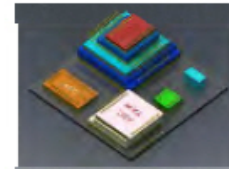
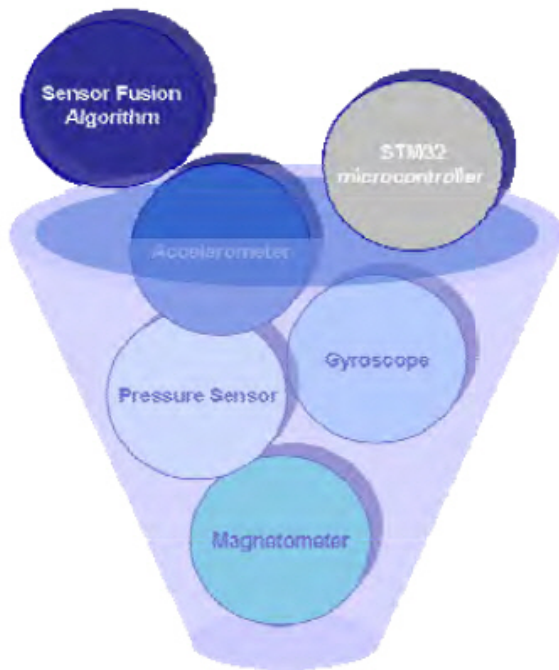
Application Segments:

- Navigation
- Mobile phone
- Pictures geo-tagging
- Location based services



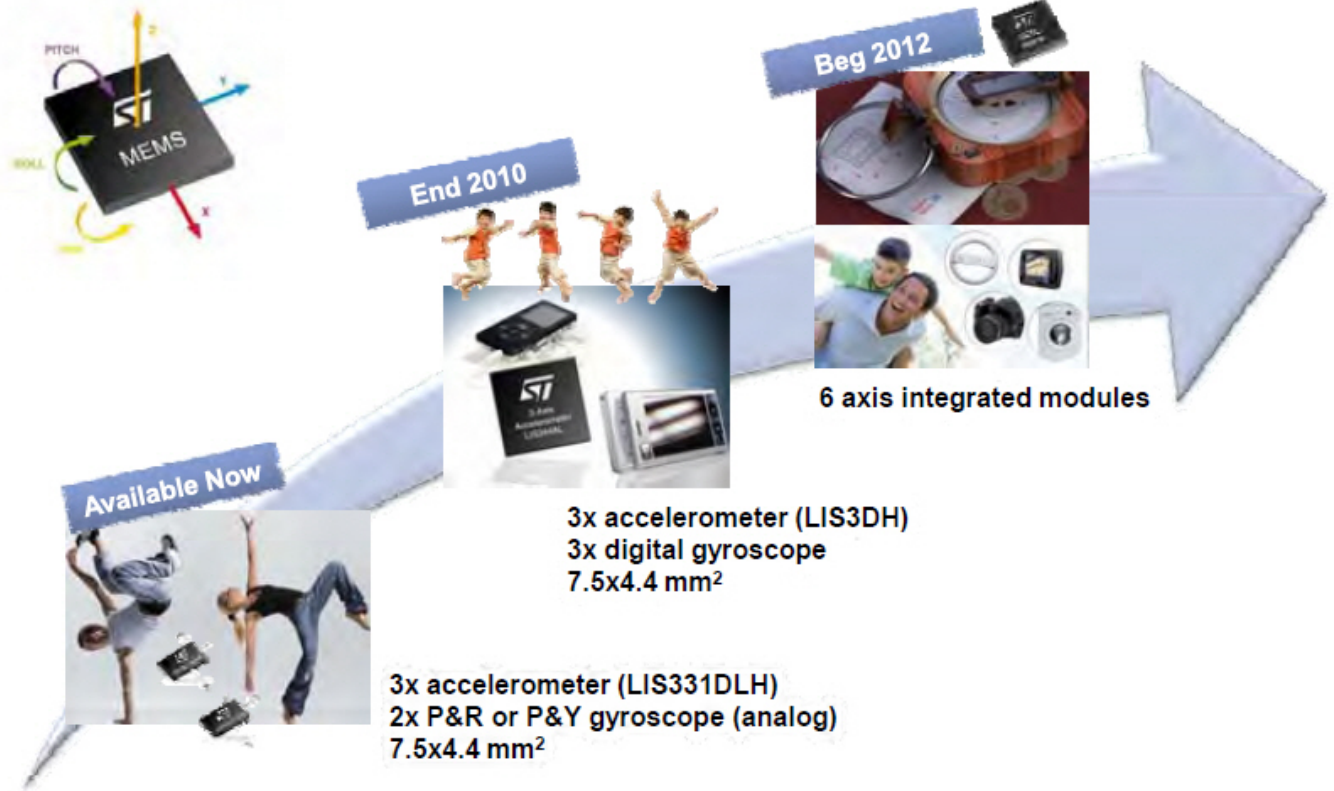
STMicroelectronics

iNEMO™ : The Smart Sensor



Smart sensor: combination of sensors, data processing and information transmission

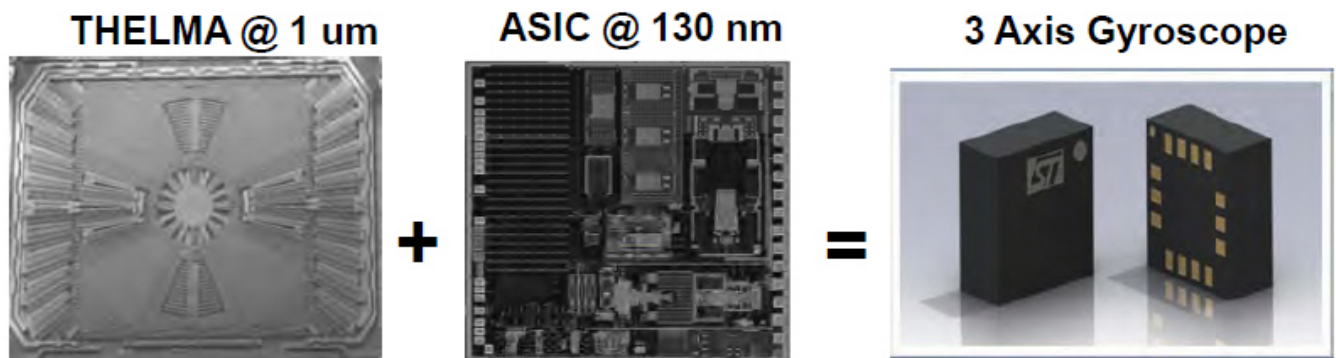
What's Next in iNEMO™ family?



MEMS are Advanced Analog Products



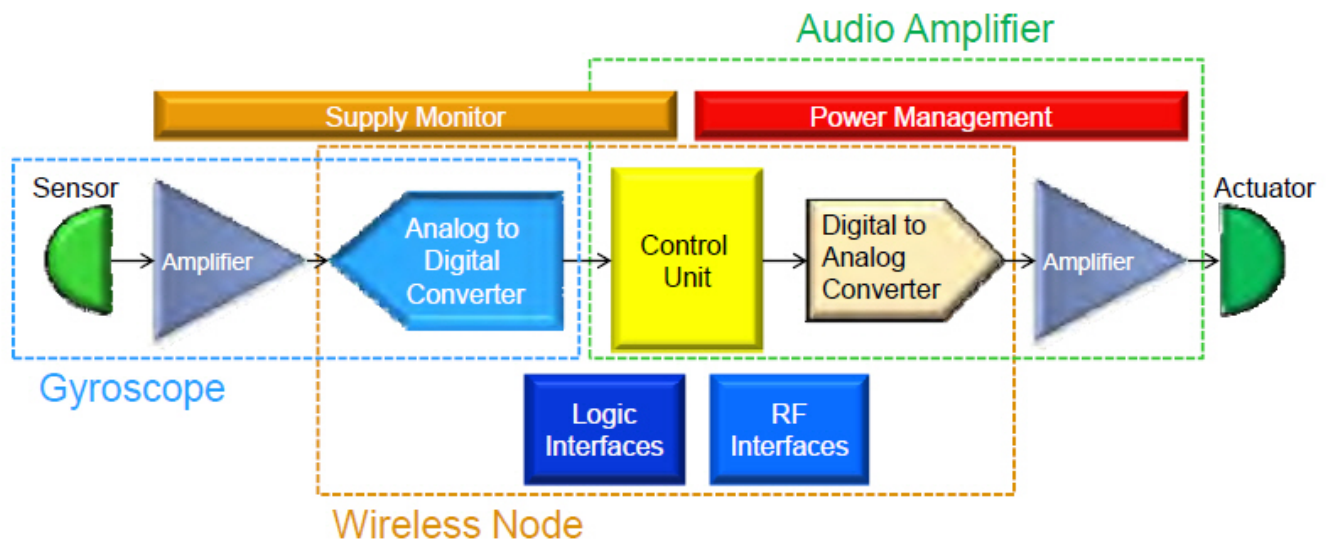
- **MEMS** means **Micro Electro Mechanical Systems** ... taking advantage of the mechanical AND electrical properties of silicon
- Three key elements:
 - **Micron-sized Transducer** realized through a specific process called Micro-Machining (THELMA)
 - An **Advanced Analog Chip** with embedded smart functionalities
 - Dedicated **package** and **calibration** features



MEMS are Advanced Analog Products



A typical Analog Signal Chain



All available in Stand Alone, ASSP and ASIC products



Analog Ranking 2009 Analog ICs* # 2

*Ranking refers to total ST Analog ICs sales

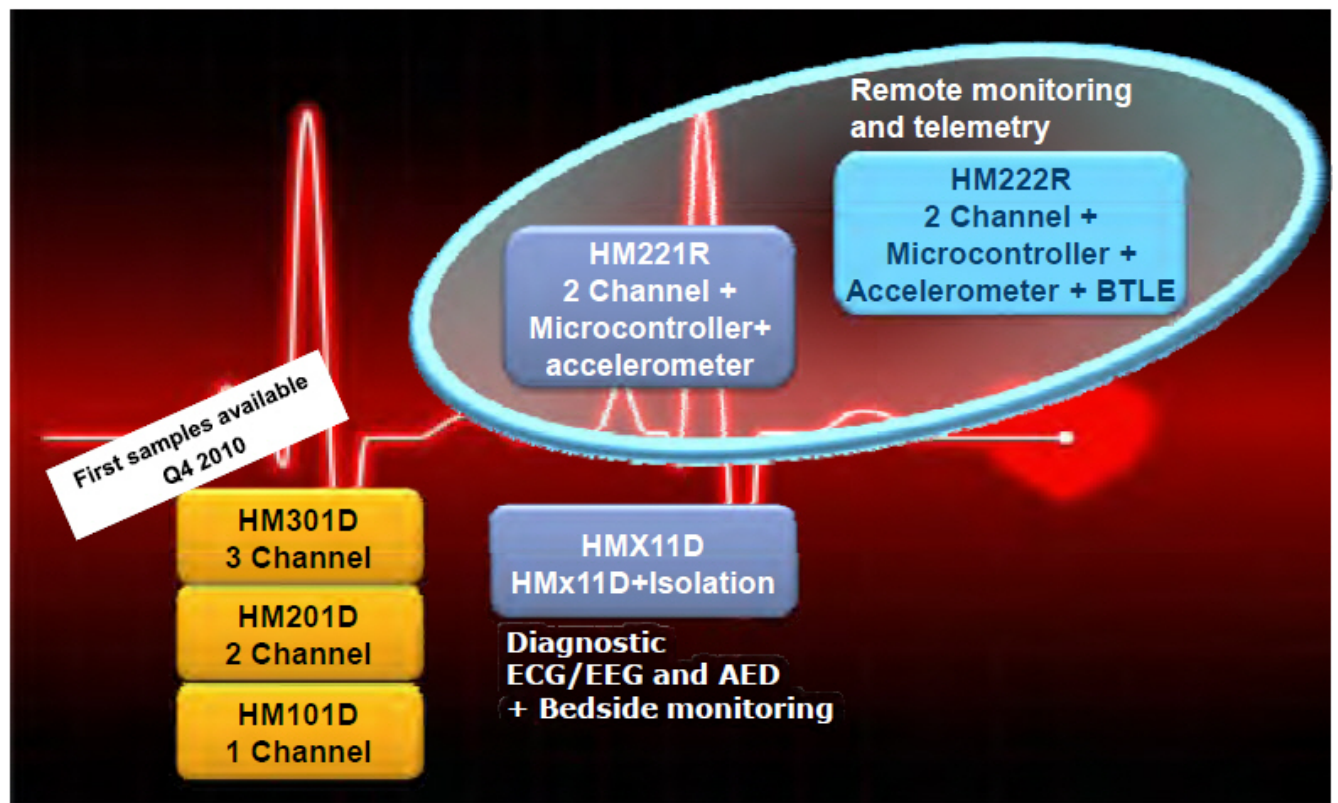
Key product family	Key Target Applications
High End Analog Front End	Healthcare, Industrial, Portable Devices
Mixed Signal ICs	Mobiles, Peripherals, Portable Medical
Low Voltage Operational Amplifiers	Mobiles, PDAs, e-Books

Competitive Advantages:

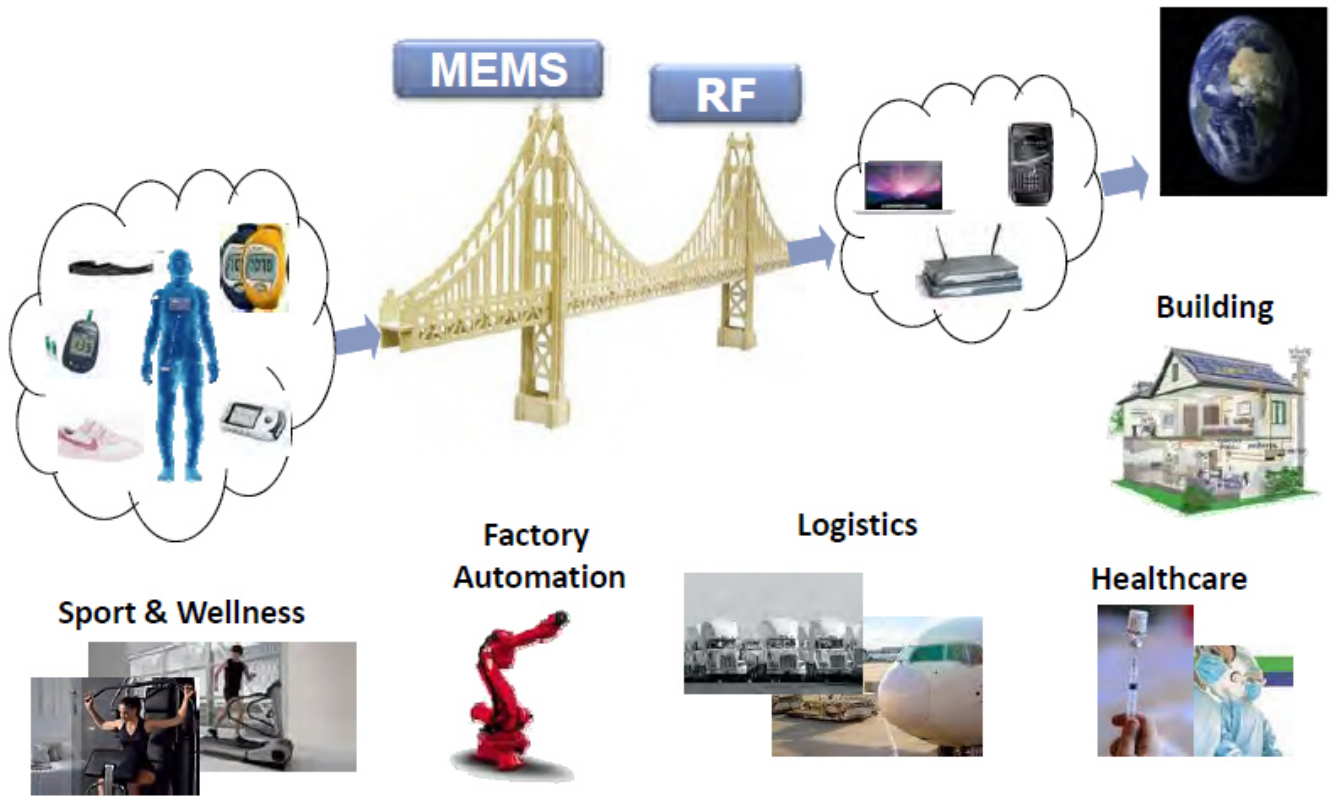
- Can integrate Analog and Power (chip or package) in Power Conversion and Power Management applications
- System know-how to design dedicated ICs for complex applications
 - Variety of reference designs for medium and small customers
- Delivery of System Solutions including Sensors, Analog ICs, Microcontrollers and Power Discrete
- The World's largest and most cost-effective 6" Front End in Singapore

Source: iSuppli, ST

Sensors Complement ElectroCardioGraph



Smart Sensors: New High-Growth Opportunities



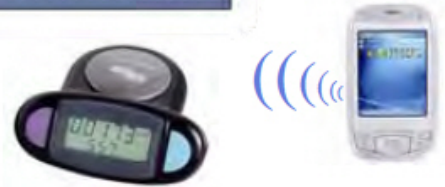
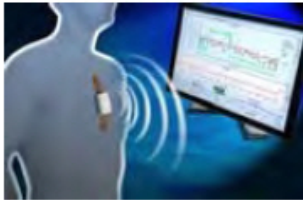
Sustaining Growth



New Sensors and Analog Products

Two main paths

Expanding MEMS Leadership in new Arenas



Takeaway Messages



- **2010 will be “Year of the Gyroscope”**
- **ST will continue to drive MEMS avalanche and extend presence in new markets**
- **ST investing heavily in MEMS and Advanced Analog products to sustain growth**
- **ST well positioned to become undisputed leader in Smart Sensors, bridging analog world to digital brain**
- **Sensors will enhance presence in the advanced analog world**



Power & Smart Power Solutions

Matteo Lo Presti

General Manager, IMS System Lab & Technical Marketing

STMicroelectronics

- Power management in IMS today
- Vision and awareness
- Innovation in technologies and products
- System innovation

Power Discrete: Strong Market Position



Power Discrete Ranking 2009

Power MOSFET (High Voltage)	# 1
Protection & IPAD	# 1
Thyristors	# 1
Rectifiers & power diodes	# 3

Key product family	Key target applications
HV Power MOSFETs	Power supply, lighting, solar
Rectifiers	Power management
ACS switches	Home appliances
Protections & IPAD	Mobiles, USB/HDMI interfaces, wired data transfer

Competitive Advantages:

- The widest range of power technologies and packages from low to very high voltage (MOSFET, IGBT, Bipolar, IPAD, Rectifiers) offering the highest efficiency in the most demanding applications
- Expertise in composite materials (SiC, GaN) for high frequency and very high temperature applications (Electric Cars, Photovoltaic Converters, Wind Generators)
- Extremely competitive manufacturing machine (Singapore, Long Gang, Shenzhen)

Source: iSuppli, ST

Power Management ICs: Pillar of IMS



Power Management*
Ranking 2009
Power Management # 2

Key product family	Key Target Applications
Off-line converter ICs	Power supply, lighting
Mixed Signal ICs	Mobiles, peripherals, portable medical
Battery Management ICs	Mobiles, PDAs, e-books
LED Driver ICs	Street lighting, building, panel arrays

Competitive Advantages:

- **Innovative System Solution combining Smart Power ICs, Power Discretes and Microcontrollers on a single board or in a single package**
- **Mixed technologies (digital, signal and power, low and high voltage) to develop advanced Smart Power ICs**
- **System know-how enabling the design of dedicated Smart Power ICs for complex applications**

(*) Power Management includes: Voltage Regulator/Reference, Industrial & Other Analog ASSP, Power RF Transistor, Bipolar PT, FET PT, IGBT, Thyristor, Rectifier & Power Diodes

Source: iSuppli, ST

Power Management Today

Key Areas of Strength



- Analog drivers
- High voltage power MOSFETs
- Rectifiers



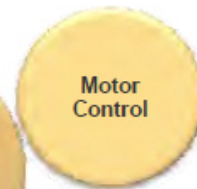
- High voltage power MOSFETs
- Ballast driver ICs
- Ultrafast diodes
- Application specific ICs



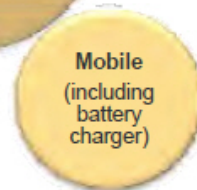
- VIPers
- Microcontrollers
- Driver ICs
- Power transistors
- ACS switches



Consolidated
IMS Key Areas



- Multi-output DC-DC converters
- Voltage regulators



- IPADs
- OLED controllers
- VIPers

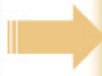
Vision and Awareness



Population and building density increase



Energy demand is increasing drastically



Post Kyoto protocols on reducing greenhouse gas emissions



A Global Commitment

Moving forward in Eco Sustainability...

- Reducing power consumption through system efficiency
- Reducing oil combustion and pollution through renewable energies and hybrid electric vehicles

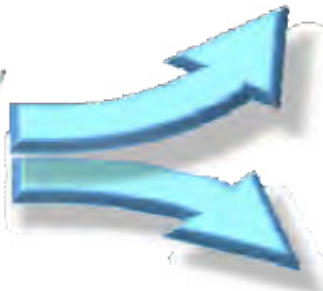


... for a better day-by-day life

- Building automation, surveillance & safety through sensor networks and remote monitoring
- Intelligent use of energy through smart systems
- Home healthcare through portable devices



Advanced Semiconductor Technologies and Innovative Products



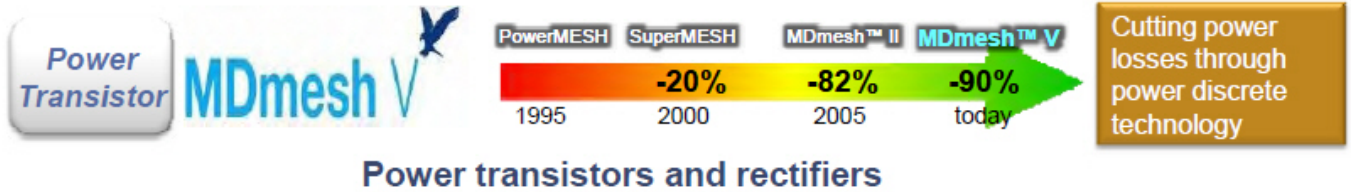
Two main paths

New Solutions and Smart Power Systems for Intelligent use of Energy, Remote Control, Healthcare and Automation

Leveraging Smart Power ICs & Power Discretes



Power management ICs, off-line converter ICs, integrated PoE ICs, mixed digital/signal/power ICs



Power transistors and rectifiers

Power Management TAM (2009) = \$22B
CAGR (2010~2013) = ~8%

Source: iSuppli



Innovation in Technologies & Products

STMicroelectronics

LOW POWER

Ultra-low power technologies



Harvesting and thin film batteries



PACKAGING

3D heterogeneous integration/ TSV



Innovative wire bonding



Advanced packaging & system-in-package



HIGH POWER

Advanced BCD, BCD-SOI



New materials:
SiC & GaN





Ultra-Thin Wafers

60um wafers for advanced IGBT devices
become flexible

90V GaN RF Power Transistors

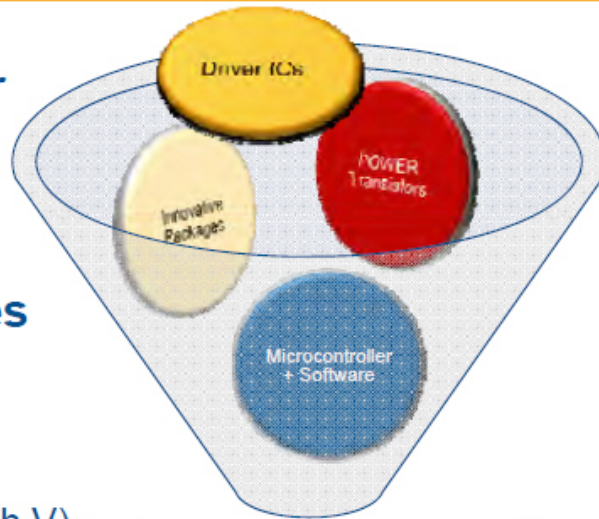
Wafers for GaN devices become
transparent



Innovation in Power Technologies



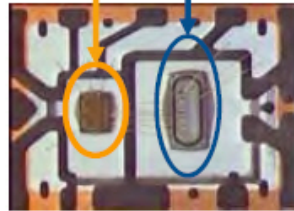
New smart power systems integrating ST current and future technologies



Power Section (MDmesh V)

Controller (BCD8)

Ultra Smart Power ICs



ASIM
Application Specific Integrated Modules

A Wave of New Products



IPAD™ (Integrated Passive & Active Devices) solution



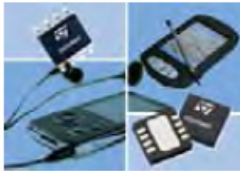
Ultra-small and energy-saving intelligent power switch



Monolithic active matrix OLED display power supply



Advanced battery chargers and gas gauge monitoring



New HV power MOSFET family featuring worldwide best R_{DSon}



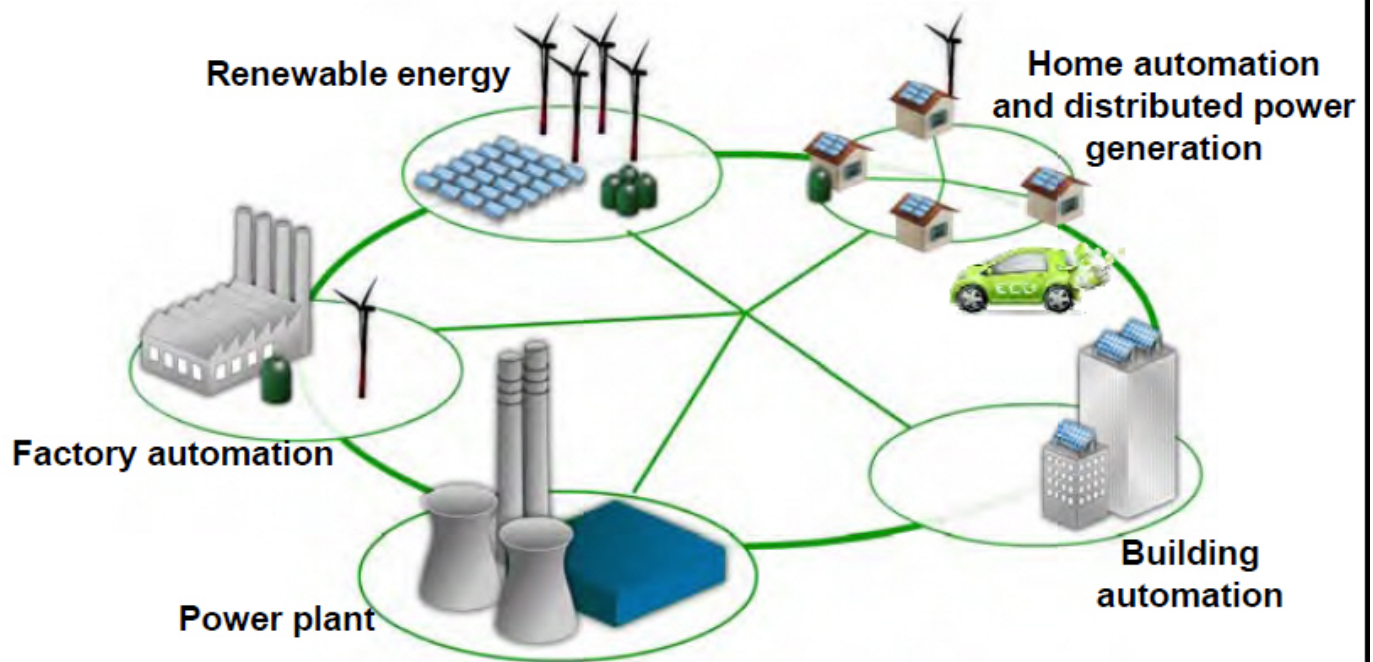


System Innovation

STMicroelectronics

SmartGrid

The Heart of Energy Management



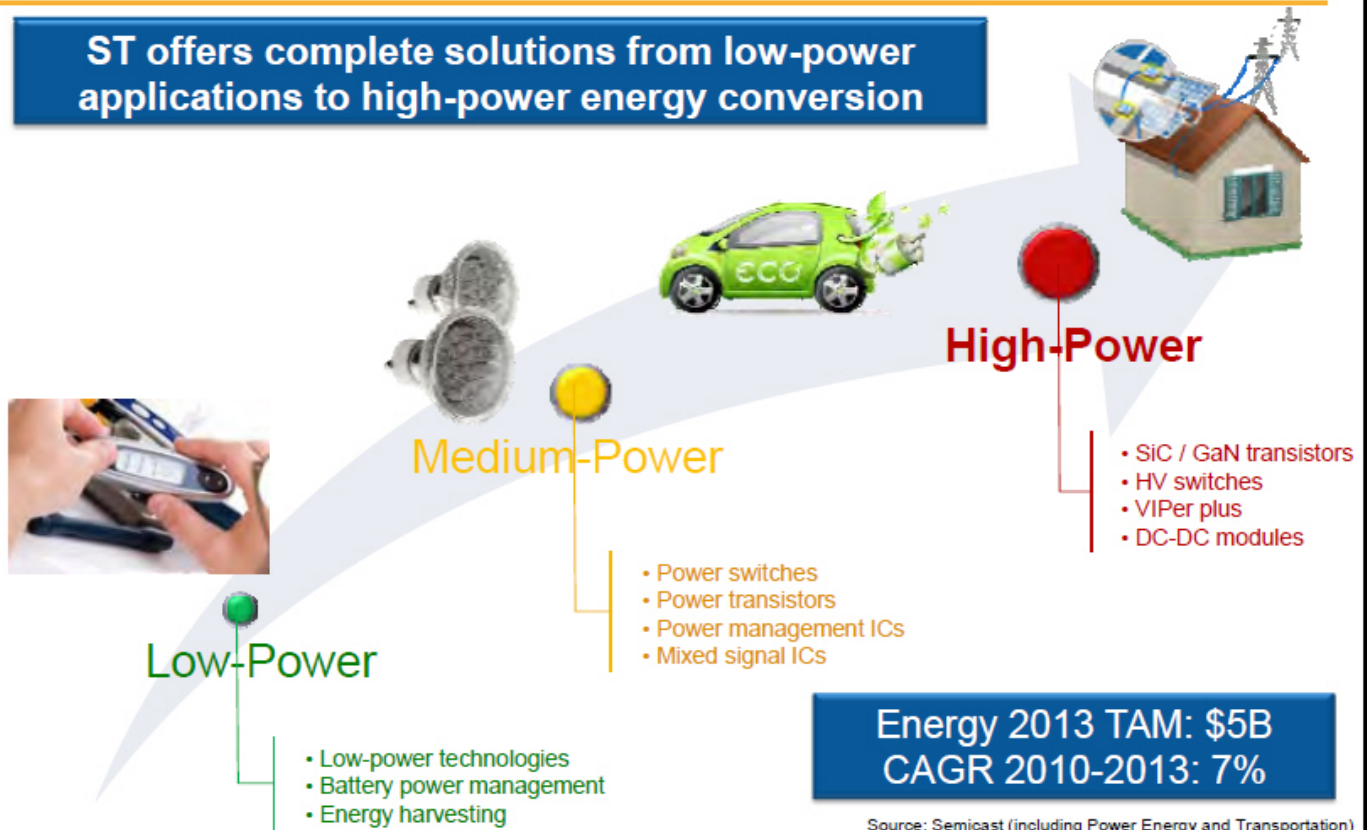
SmartGrid: Power conversion and connectivity for an intelligent use of energy

STMicroelectronics

Power Conversion in SmartGrid



ST offers complete solutions from low-power applications to high-power energy conversion



Smart Power Solutions

LED Street Lighting Control



Energy saving:

dimming based on available natural light

Comfort:

color changing (cool/warm) based on location and time of day

Architectural/fashion:

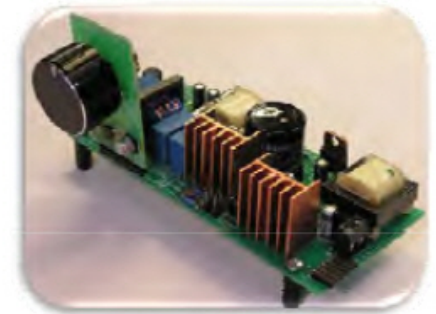
creating different *effects* using the same lights

Lighting control:

for specific applications like theater, stage lighting



ST Solution



Lighting 2010 TAM: \$1B
CAGR 2010-2015: 9%

Key Products



Driver ICs



Power transistors



Power factor ICs

Source: Semicast

STMicroelectronics

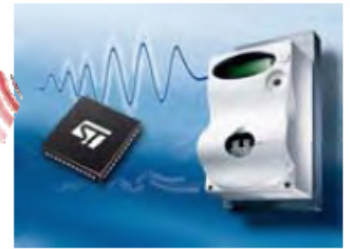
Smart Power Solutions

Smart Meters



Gas Meter
Electronic flow meter

Energy Meter



Concentrator

provides info to the consumer on energy and gas usages



ST Solution



Key Products



Motor control ICs



Power line modems



Energy meter ICs

Source: ABI Research

Smart Electricity Meters
TAM 2009: 76M units
CAGR 2010-2013: ~18%

Smart Power Solutions

Hybrid and Electric Vehicles



Plug-in battery charger for HEV

Combine an electric motor and an internal combustion engine

Reduce air pollution from greenhouse gases

Operating cost equivalence: 20¢US / liter**



ST Solution



Key Products



Power transistors



Driver ICs



32-bit microcontrollers

**More than \$600 of
semiconductors
for every HEV (*)**

Source: (*) Strategic Analytics, (**) US Dept of Energy

STMicroelectronics

Smart Power Solutions

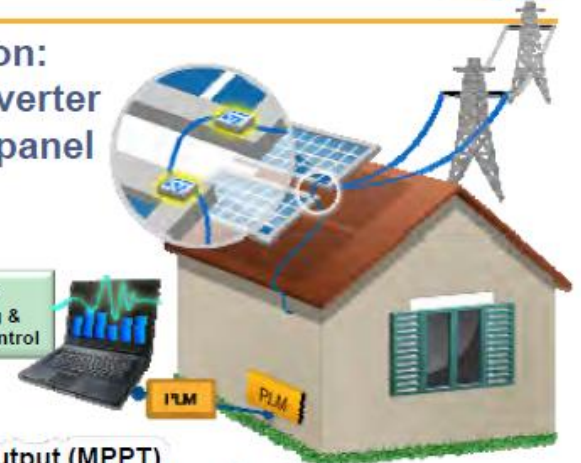
Photovoltaic



ST Solution

ST Solution:
One microinverter
module per panel

Remote
Monitoring &
PV Panel Control



Key Products



Cool bypass switch



Power transistors



MPPT
(Max Power Point Tracker)

- ❖ Maximizing energy output (MPPT)
- ❖ Energy monitoring (daily, monthly, yearly, etc.)
- ❖ Diagnostic, anti-theft and anti-tearing protection
- ❖ Reducing operation costs due to modularity

Electronics on panel value from \$1.50 to \$15
PV energy production growth

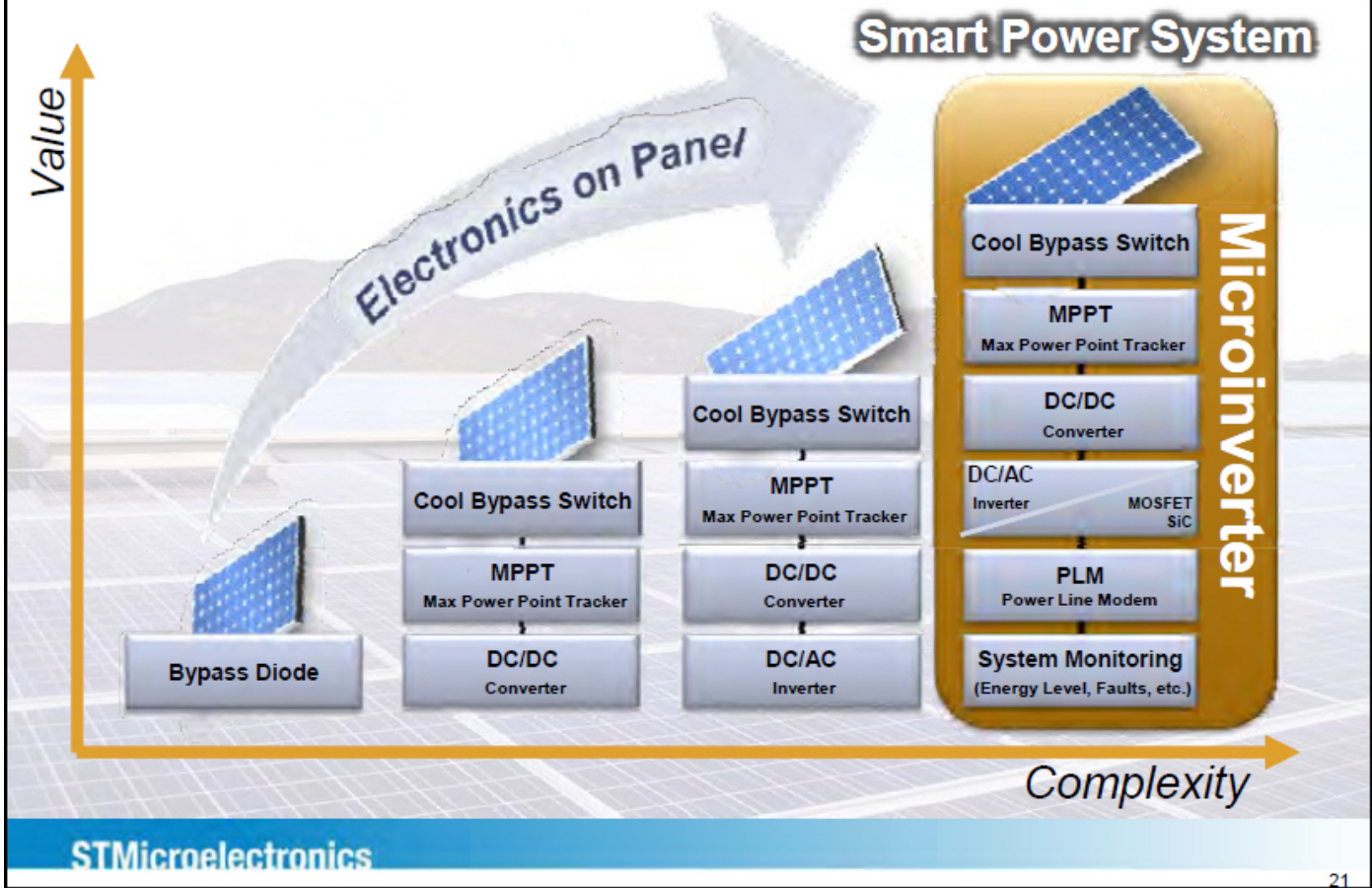
- 2010 → about 7 GW
(about 35 million single photovoltaic panels)
- 2020 → about 56 GW

Source: European Photovoltaic Industry Association, ST

STMicroelectronics

Smart Power Solutions

Photovoltaic



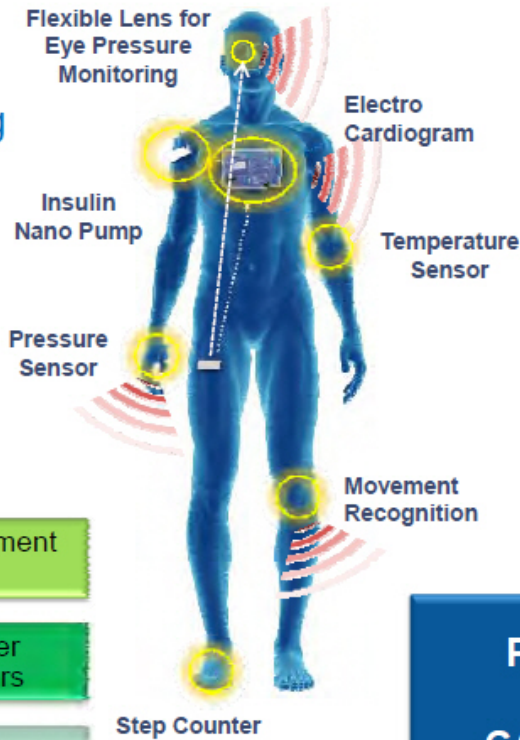
STMicroelectronics

Smart Power Solutions

Home Healthcare



Portable distributed diagnostics and remote monitoring



Key Products

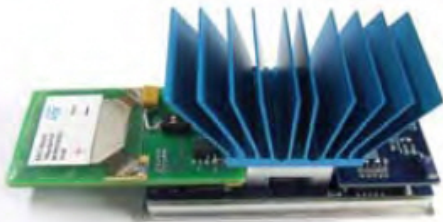
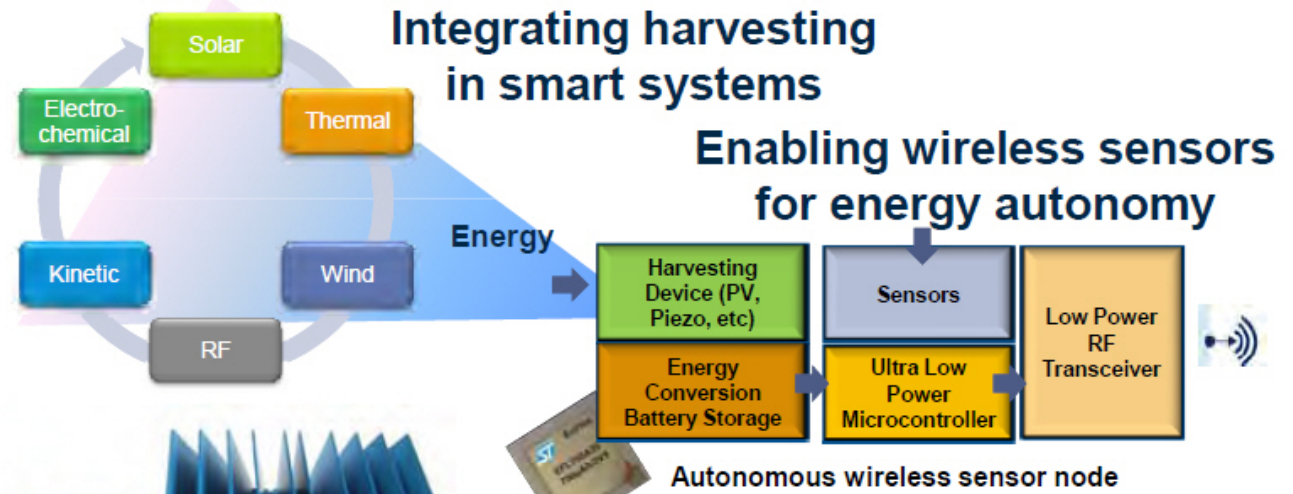
- Battery management ICs
- 8-bit low-power microcontrollers
- IPAD and protection

Source: Semicast

Portable Healthcare
2010 TAM: \$1B
CAGR 2010-2015: 11%

Smart Power Solutions

Energy Harvesting



STMicroelectronics and Micropelt demonstrate 'Perpetual Energy' thermoharvesting power supply

The Future is Here

A "Virtuous" Circle



Smart Power ICs



Develop Solutions



System Approach
Acts as a
Flywheel



Product Innovation



Customer Endorsement



TRANSFORMING THE PORTFOLIO

Pascal Langlois

Senior Vice President, Chief Sales and Marketing Officer



TRANSFORMING THE PORTFOLIO

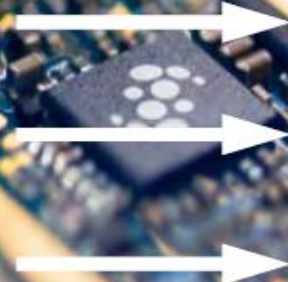
- Entry & feature phones

- Modem only

- Three big customers

- Custom solutions

- Europe and Asia



- High-value entry
- Smartphones
- Connected devices

- Application engine
- Modem
- Connectivity

- Diversified customer portfolio

- Open/complete platforms

- Global

MARKET TRANSFORMATION

In Production

Modern Platforms



DRIVING MOBILE BROADBAND EVERYWHERE

Mobile Broadband and M2M Devices



THE BEST SMARTPHONE PLATFORMS FOR ALL TIERS

High-end and mid range smart devices



ADDING VALUE TO AFFORDABLE DEVICES

High value entry devices

Connectivity and
Integration

Manufacturing

Service and
Support

Product
Lifecycle

Customer
Experience

Device
Ecosystem

Complete Platforms

TODAY

UMTS/
HSPA TD-SCDMA
2G/EDGE

In Production

Thin Modems Platforms

M340
HSDPA
5209
EDGE
M6718
TD-HSPA

HSPA
EDGE
TD

Separated Smartphone solutions (Application engine + Thin modem)

Entry & Feature Platforms

U67XX
WCDMA
U6715
HSDPA
U33x
HSPA/HSDPA
T72XX
TD-HSDPA
65XX
EDGE
E4908
EDGE

Internet and Multimedia enabled solutions

Single-chip 2G & EDGE

Connectivity and Enhancements

GNS7560
GPS
STLC2690
BT/FM
STLC4560
WLAN
STw8019
TVout
STw5200
Audio

Complete Platforms

TOMORROW

 LTE
  TD-SCDMA
 UMTS/HSPA
  2G/EDGE

	In Production	Announced	
Thin Modems Platforms	M340 HSDPA 5209 EDGE M6718 TD-HSPA	M700 LTE M570 HSPA+ M720 LTE/HSPA+	LTE / HSPA+ Mobility Best combined UL/DL performance Data in every region
Application Processor with Integrated Modem Platforms		U8500 HSPA+ TD U5500 HSPA+	High-performance Smartphone platforms
Entry Platforms	U67XX WCDMA U33x HSPA/HSDPA 65XX EDGE U6715 HSDPA T72XX TD-HSDPA E4908 EDGE	U68XX HSDPA E4910 EDGE G4850/52 GSM/GPRS T6718 TD-HSPA	Internet and Multimedia enabled solutions Single-chip 2G & EDGE
Connectivity and Enhancements	CG2900 BGF CW1200 WLAN	AV8100 HD TVout AV5230 Audio PTE	Complete Platforms

A COMPLETE SINGLE CHIP 2G PORTFOLIO

Single Chip
ULC+ GSM/GPRS
MPEG4, MP3, FM record
Dual SIM / Dual Standby



G4852

Single-Chip EDGE
WQVGA display, touchscreen
3MP camera
MPEG4, H.263, MP3, AAC+



E4910

Single Chip
ULC GSM/SMS
MP3 ringtones
Dual SIM / Dual Standby



G4850

Single-Chip EDGE-Rx
QVGA display, 2MPix camera
MPEG4, H.263, MP3, AAC+
USB FS



E4908

Bringing high value features to the entry segment

CONNECTIVITY AND ENHANCEMENTS

-  **GPS**
Leading footprint and power
-  **Bluetooth**
Fully-integrated single-chip Bluetooth
-  **FM Radio**
Over 1 Billion FM radio shipped
-  **WLAN**
Outperforms in Bluetooth co-existence
-  **Video**
Full HD TV out
-  **Audio**
Extend playtime without reducing quality
-  **Power**
Smart power distribution 

CG2900
BT/FM/GPS
First 45nm Combo
Leading footprint size

CW1200
802.11a/b/g/n
< 50mm2 BOM
Integrated FEM, SMPS

AV8100
HDMI/CVBS combo
Full HD 1080p
7.1 audio surround

AV5230
102 dB SNR
Integrated headset AMP
Playback Time Extender

Integrated into complete platform solutions

U6715 SMARTPHONE FOR ALL



HSDPA supporting multiple OS

Touch screen

5 Mpixel camera

QVGA or WQVGA Video

3G talk time up to 7 hours
standby up to 25 days

Android ready



U6715

Great user experience at an affordable price

INNOVATION FOR SMARTPHONES

Dual core architecture with > 1Ghz
Over 5000 DMIPs power

Full HD Camcorder 1080p
20 megapixel cameras
High-end 3D graphics subsystem

Integrated connectivity
HSPA+ modem

Supporting multiple OS

U8500



Dual core architecture

HD video 720p
12 megapixel cameras
3D graphics subsystem

Integrated connectivity
HSPA+ modem

U5500



- TD variants for the Chinese market
- Compatibility and scalability for our customers
- Reference hardware for ARM Mali ecosystem
- Driving evolution of SMP for Android

Technology leadership brought to mainstream

ADVANCED TD-SCDMA SOLUTIONS

Feature rich TD-HSPA/EDGE platform

Enabling affordable high-speed internet phones

5 megapixel camera
WQVGA display

T6718

Thin modem platform with
TD-HSPA for higher uplink data rates

65nm process

Improved overall integration

M6718



Leader in TD-SCDMA in China – 12 Million chipset shipped

MOBILE BROADBAND WITH HSPA+ AND LTE

Commercially available chipsets

Low power consumption and best-in-class thermal performance

Full data speed downlink of 21Mbps and uplink of 5.7Mbps simultaneously

Modem optimized for easy integration into a variety of devices



M570

Successfully combining LTE with HSPA+ technology

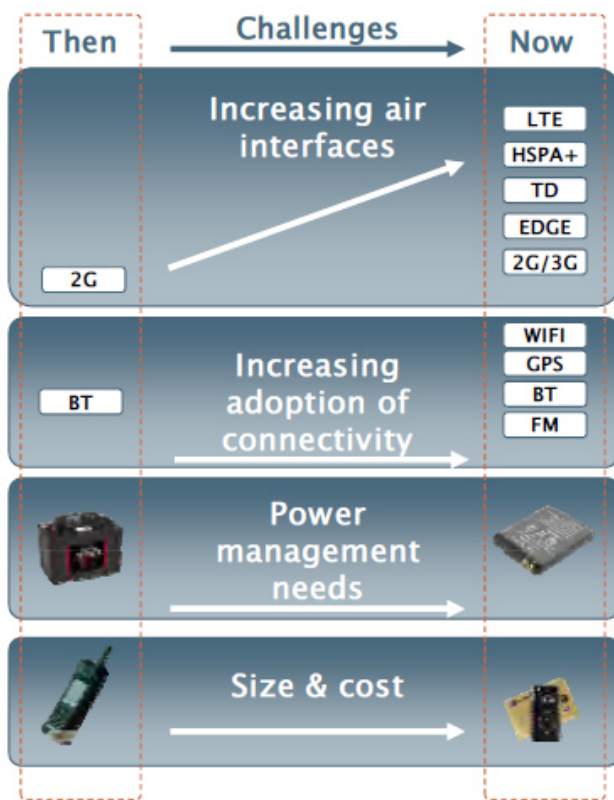
Optimized modem solution suitable for USB data devices



M720

First to successfully show interoperability between HSPA and LTE

ADDRESSING MODEM EVOLUTION



New ST-Ericsson multi-mode modem architecture

- Software-defined radio access
- LTE 100Mbps, HSPA+ 42Mbps
- Target >2X power improvement
- Scalable for cost
- Building on existing LTE solution
- Single SW and HW platform
- Drastic reduction of testing

SUMMARY

Transforming the portfolio to address key market

Complete portfolio with highly competitive products

Good feedback from customers on the new portfolio

DEMOS

Thin
Modems
Platforms

M570

Application
Processor with
Integrated
Modem Platforms

U8500 + Connectivity
(CG2900 & CW1200)

Entry
Platforms

U6715

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, STMicroelectronics N.V. has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Date: June 4, 2010

STMicroelectronics N.V.

By: /s/ CARLO FERRO

Name: **Carlo Ferro**
Title: **Executive Vice President and
Chief Financial Officer**
